

# Agenda 1

Time	Presentation	Speakers
9:00 a.m.	<b>Introduction</b>	<b>Tait Sorensen</b> , Group Vice President, Investor Relations
	<b>Welcome</b>	<b>Carlo Bozotti</b> , President and Chief Executive Officer
	<b>Business and Financial Roadmap</b>	<b>Carlo Ferro</b> , Chief Financial Officer
	<b>Technology and Manufacturing</b>	<b>Jean-Marc Chery</b> , Chief Operating Officer
	<b>Application Strategic Focus</b>	<b>Georges Penalver</b> , Chief Strategy Officer
10:30 a.m.	<b>Break – Demos</b>	
10:50 a.m.	<b>Internet of Things: A key driver of growth</b>	<b>Claude Dardanne</b> , EVP, General Manager, MDG <b>Benedetto Vigna</b> , EVP, General Manager, AMG <b>Bob Krysiak</b> , EVP, Region Americas, Global Mass Market & OLM Programs
	<b>Smart Driving: ST leading the transformation</b>	<b>Marco Monti</b> , EVP, General Manager, ADG <b>Marco Cassis</b> , EVP, President, Region Asia Pacific <b>Paul Cihak</b> , EVP, General Manager, Sales and Marketing, EMEA
	<b>Closing Remarks</b>	<b>Carlo Bozotti</b> , President and Chief Executive Officer
12:10 p.m.	<b>Q&amp;A Panel</b>	<b>C.Bozotti, C.Ferro, G.Penalver, J.M.Chery</b>
1:00 p.m.	<b>Lunch – Demos</b>	

# Agenda – Breakout Sessions

2

	<b>Room 1</b> (Library)  <b>ADG</b> Automotive and Discrete Group	<b>Room 2</b> (Louis XVI B)  <b>MDG</b> Microcontroller and Digital ICs Group	<b>Room 3</b> (Louis XVI A)  <b>AMG</b> Analog and MEMS Group
<b>2:00 p.m.</b>	<b>Marco Monti</b> <b>Bob Krysiak</b>	<b>Claude Dardanne</b> <b>Marco Cassis</b>	<b>Benedetto Vigna</b> <b>Paul Cihak</b>
<b>2:30 p.m.</b>	<b>Marco Monti</b> <b>Paul Cihak</b>	<b>Claude Dardanne</b> <b>Bob Krysiak</b>	<b>Benedetto Vigna</b> <b>Marco Cassis</b>
<b>3:00 p.m.</b>	<b>Marco Monti</b> <b>Marco Cassis</b>	<b>Claude Dardanne</b> <b>Paul Cihak</b>	<b>Benedetto Vigna</b> <b>Bob Krysiak</b>
<b>3:30 p.m.</b>	Reception		

# Forward Looking Statements

*Some of the statements contained in this release that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance, or events to differ materially from those anticipated by such statements, due to, among other factors:*

- Uncertain macro-economic and industry trends;*
- Customer demand and acceptance for the products which we design, manufacture and sell;*
- Unanticipated events or circumstances, which may either impact our ability to execute the planned reductions in our net operating expenses and / or meet the objectives of our R&D Programs, which benefit from public funding;*
- Financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;*
- The loading, product mix, and manufacturing performance of our production facilities;*
- The functionalities and performance of our IT systems, which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers or suppliers;*
- Variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;*
- The impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;*
- The ability to successfully restructure underperforming business lines and associated restructuring charges and cost savings that differ in amount or timing from our estimates;*
- Changes in our overall tax position as a result of changes in tax laws, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;*
- The outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;*
- Product liability or warranty claims or recalls by our customers for products containing our parts;*
- Natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, health risks and epidemics in locations where we, our customers or our suppliers operate;*
- Changes in economic, social, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macro-economic or regional events, military conflict, social unrest, labor actions, or terrorist activities;*
- Availability and costs of raw materials, utilities, third-party manufacturing services, or other supplies required by our operations.*

*Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.*

*Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2015, as filed with the SEC on March 16, 2016. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed, or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.*

# Business & Financial Roadmap

**Carlo Ferro**

Chief Financial Officer

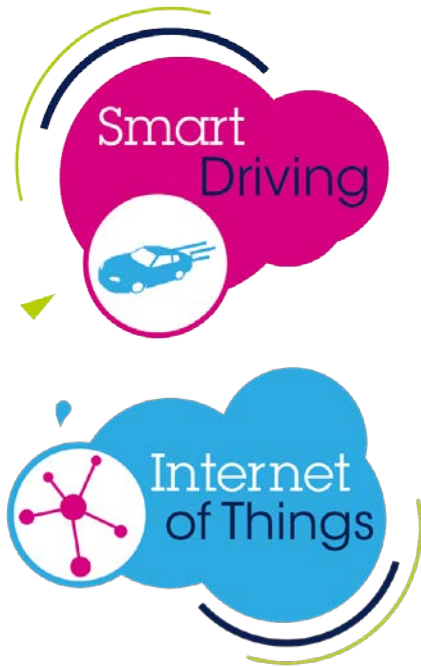




life.augmented

## ST stands for life.augmented

Everywhere microelectronics make a positive contribution to people's lives, ST is there

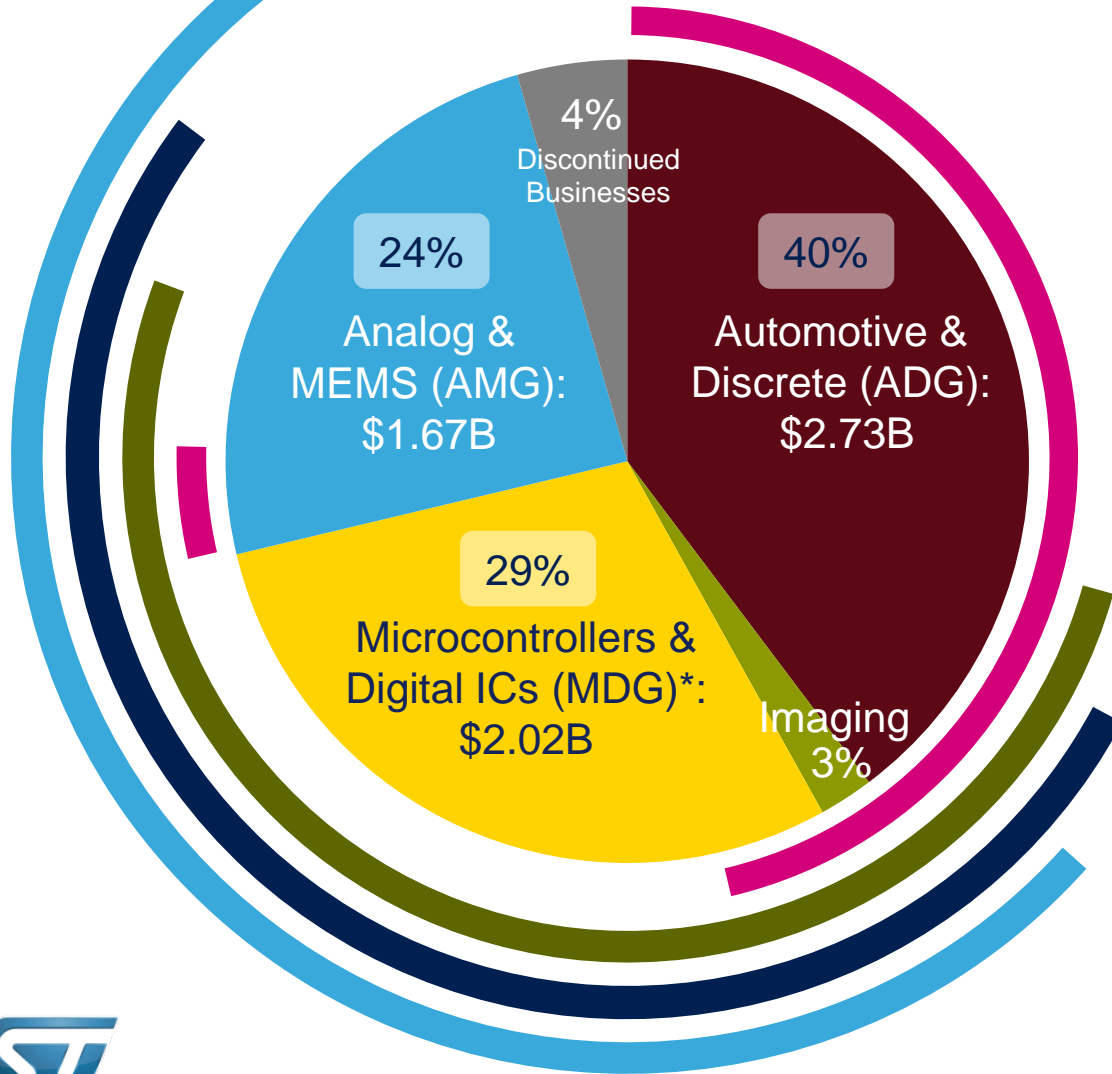


- A global semiconductor leader with an application strategic focus
- 2015 revenues of **\$6.90B**
- Listed: NYSE, Euronext Paris and Borsa Italiana, Milan
- Approximately **43,200** employees worldwide
- Approximately **8,300** people working in R&D
- Portfolio of over **9,400** patent families
- **11** manufacturing (front and back-end) sites
- Over **75** sales & marketing offices

# New Organization...

Aligned to Strategic Focus

2015 Revenues  
(\$6.90B)



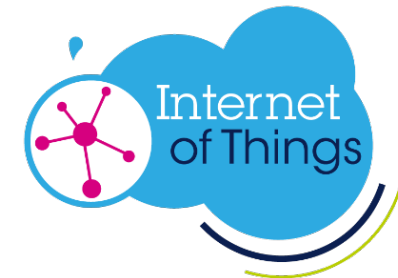
Smart Driving



Smart Industry

Smart Home & City

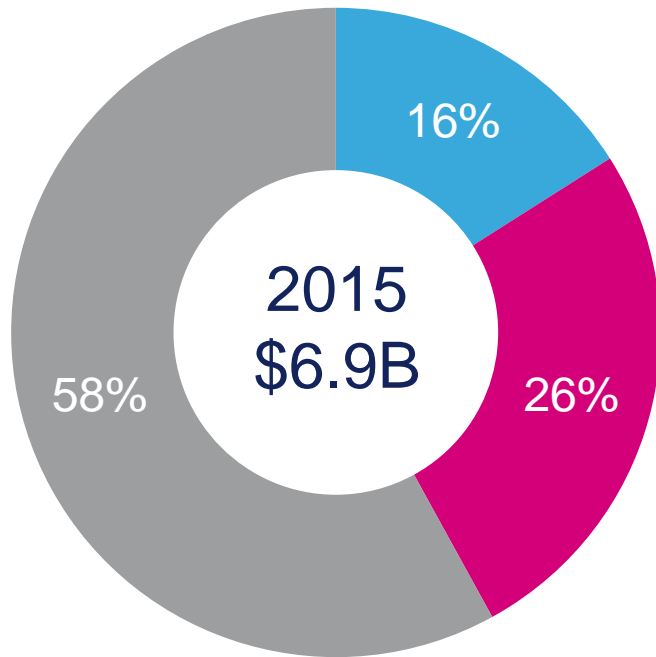
Smart Things



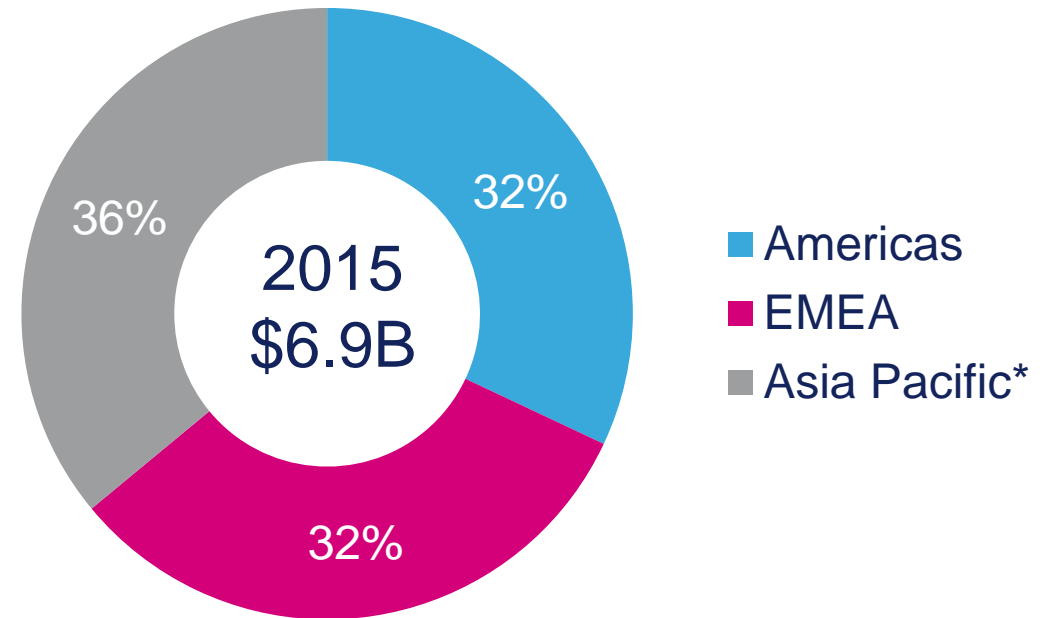
\* For illustrative purposes. Discontinued businesses include set-top box, camera modules and the former ST-Ericsson products.

# A Global Business

revenues by location of shipment (%)

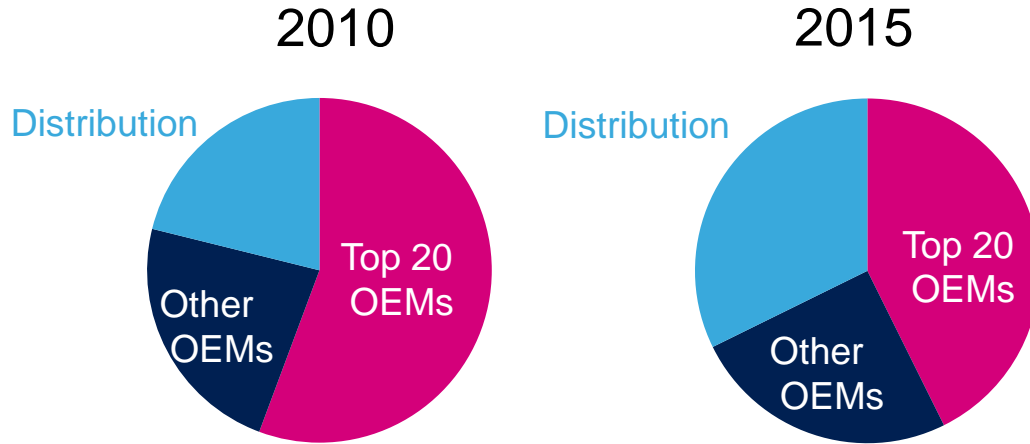


revenues by region of origin (%)



\* Combination of former Japan & Korea and Greater China & South Asia regions

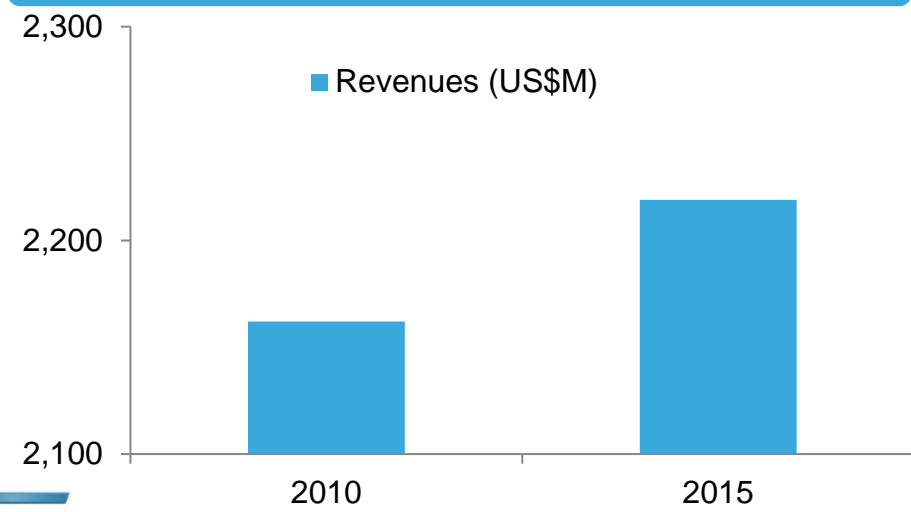
# Transforming our Customer Base



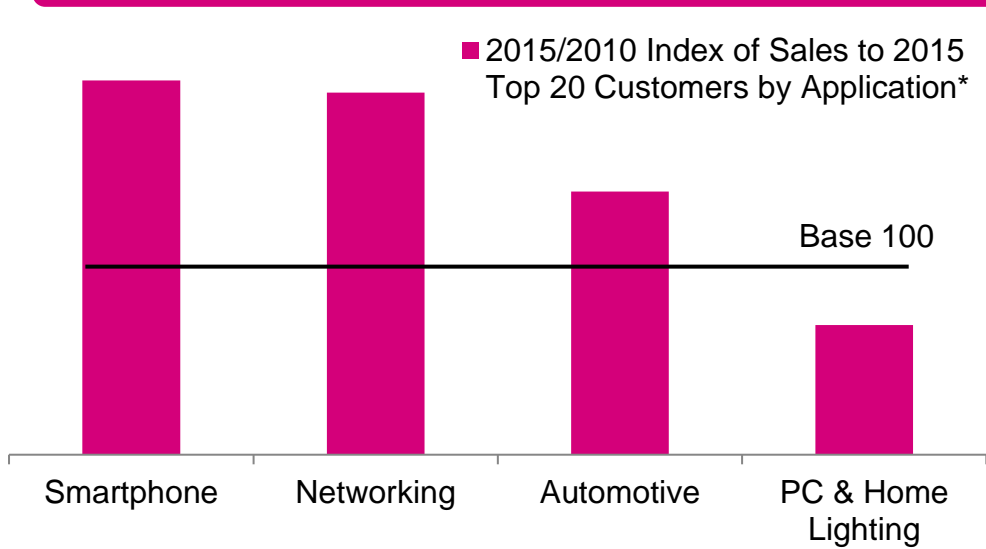
- React to Nokia Business
- Customer Diversification
- Better Balance by Application
- Preparing to Restart Growth

- 2015 Top 20 OEMs:**  
(alphabetically)
- Apple
  - Bosch
  - Ciena
  - Cisco
  - Conti
  - Delta
  - Denso
  - Finisar
  - HP
  - Huawei
  - Marelli
  - Mobileye
  - Philips
  - Samsung
  - Seagate
  - Sirius
  - Technicolor
  - Valeo
  - Western Digital
  - ZF-TRW

**Growing in Distribution**



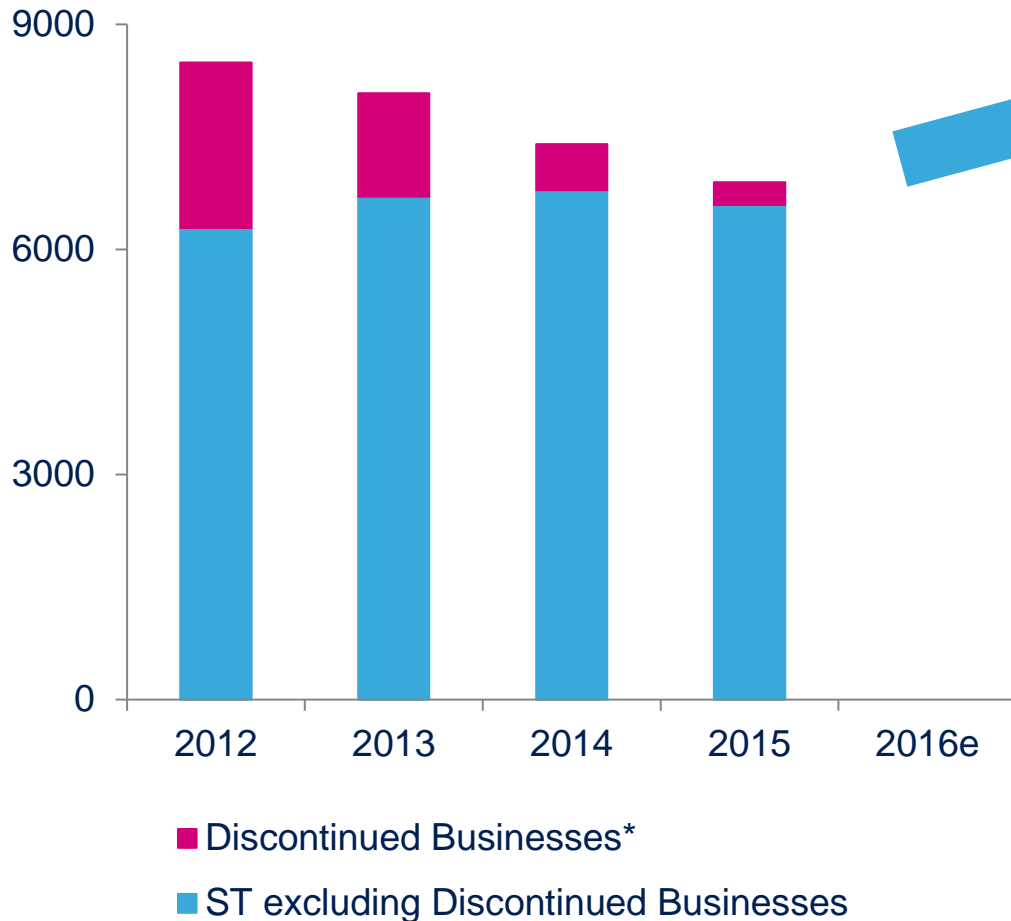
**Growing with most of the Top 20 Customers\***



\*Excluding discontinued businesses



# Returning to Revenue Growth



## Focus on growth...

**Microcontrollers and automotive already growing Y-o-Y**

**Power discrete, AMG and Imaging targeting sequential growth from current quarter and Y-o-Y growth 2H16/2H15**

### Gain market share

- Focus on key customers
- Continue expansion of customer base, particularly in mass market
- Sustain momentum in microcontrollers and automotive
- Stabilize position in analog and power discrete
- Recover in MEMS

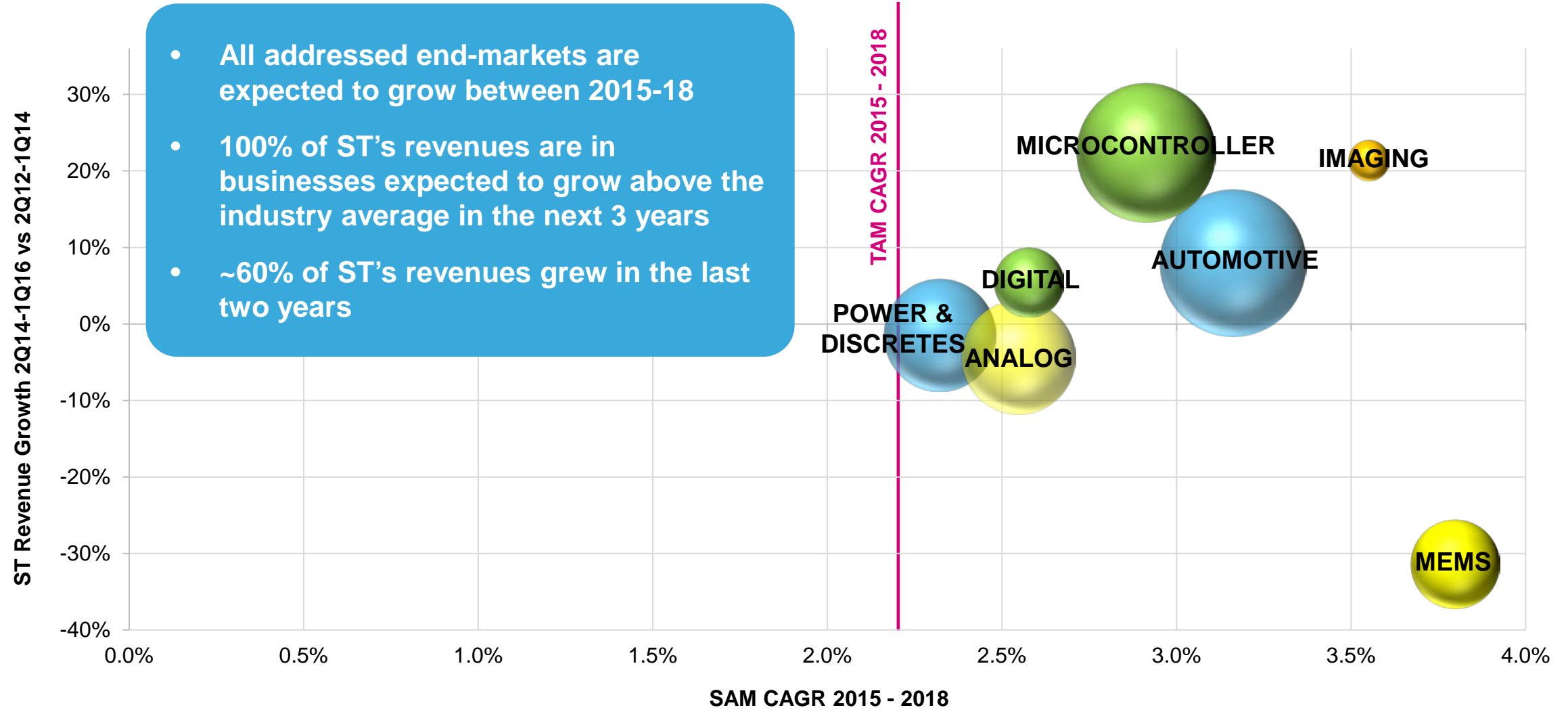
### Boost sales & marketing support and product development

- Increase sales & marketing efforts across all regions
- Redeploy ~600 people to support and accelerate growth of microcontrollers, digital automotive and ASICs

\*Discontinued businesses include set-top box, camera modules and the former ST-Ericsson products

# Focusing on Businesses with above Market Growth

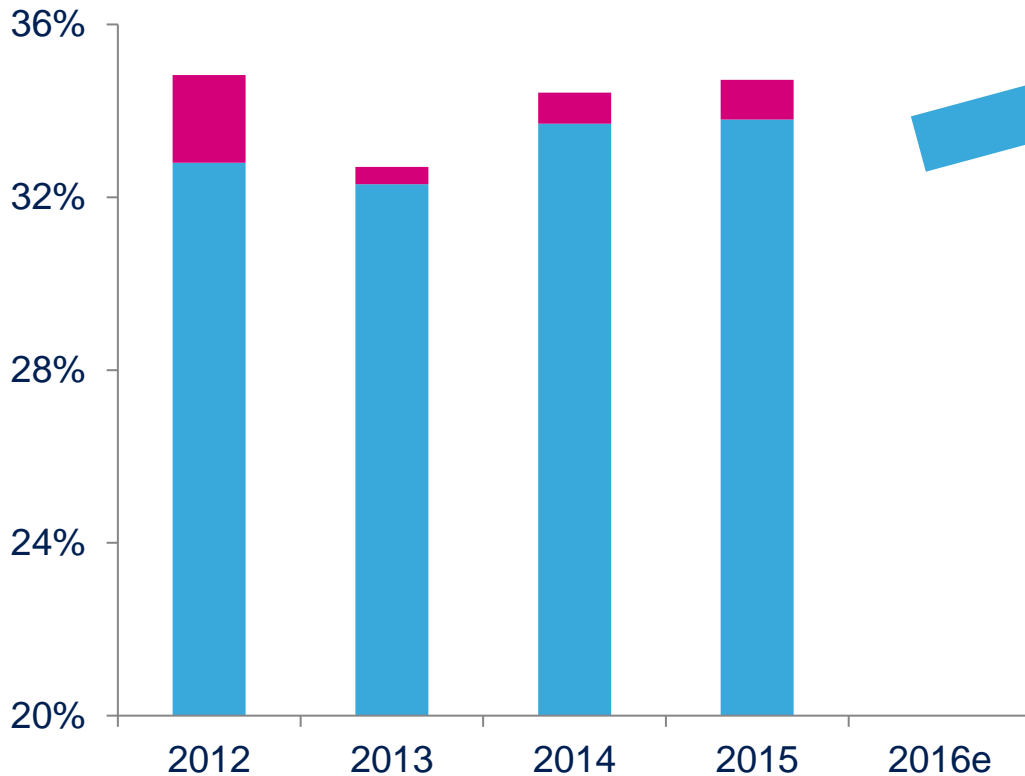
- All addressed end-markets are expected to grow between 2015-18
- 100% of ST's revenues are in businesses expected to grow above the industry average in the next 3 years
- ~60% of ST's revenues grew in the last two years



Note: Size of bubble is proportional to ST's revenue.

Source: Company data, WSTS

# Gross Margin Initiatives



■ Gross Margin - Reported ■ Unused Charges (%)

## ...with margin expansion\* ...

### Improve product mix

- Increase revenues from value-add and differentiated new products / innovation / new technologies
- Decrease revenues from low margin discontinued products while executing on the Set-Top Box restructuring plan

### Manufacturing excellence

- Improve fab loading, particularly in 12" with expanded technology mix
- Volume to reduce wafer cost in almost all fabs
- Continue capacity conversion from 6" to 8"
- Technology evolution, improved loading and performance of Front and Back-end plants
- Assembly cost and yields

### Favorable Currency Effects, net of hedging

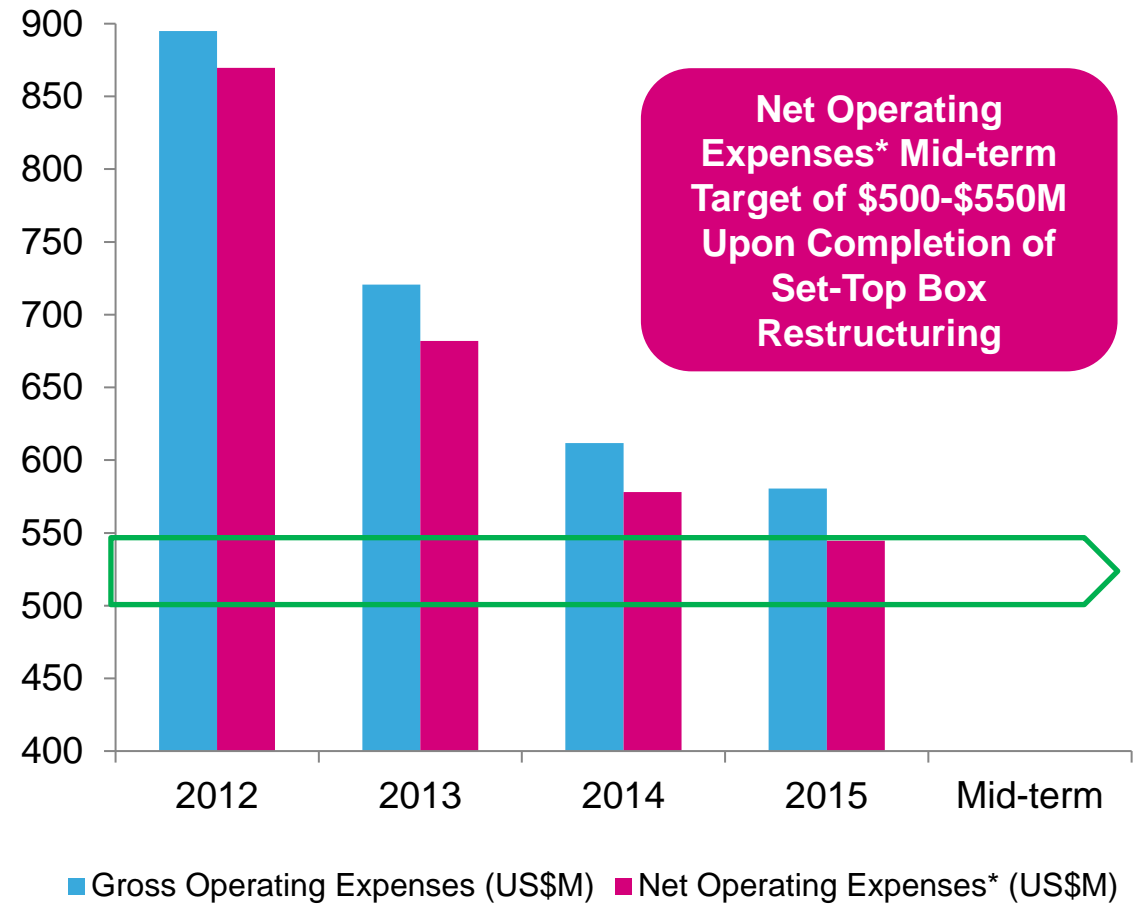
# Operating Expense Discipline

## ...and expenses control...

Ongoing execution of the Set-Top Box restructuring plan

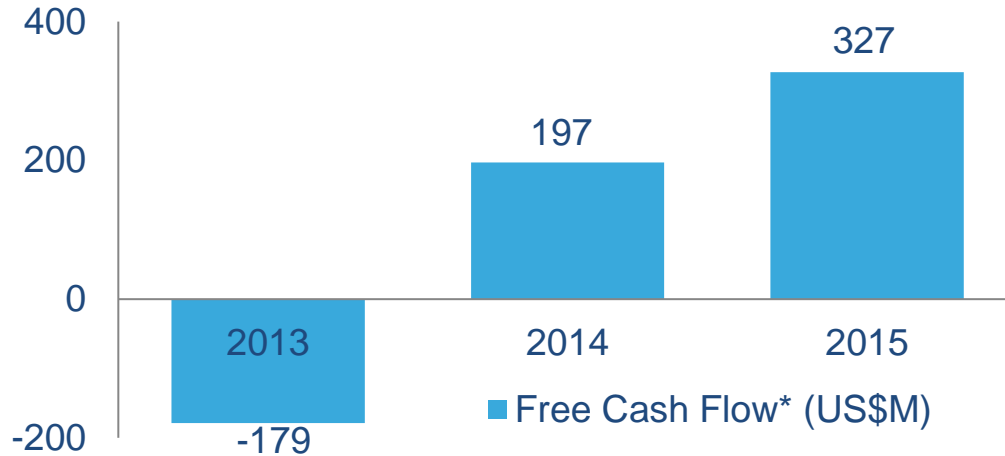
- Annualized savings at completion of plan estimated at \$170M per year
- Restructure ~1,400 headcount
- Redeploy ~600 people to accelerate product development principally in digital automotive and microcontrollers

Favorable Currency Effects, net of hedging\*\*



# A Solid Capital Structure

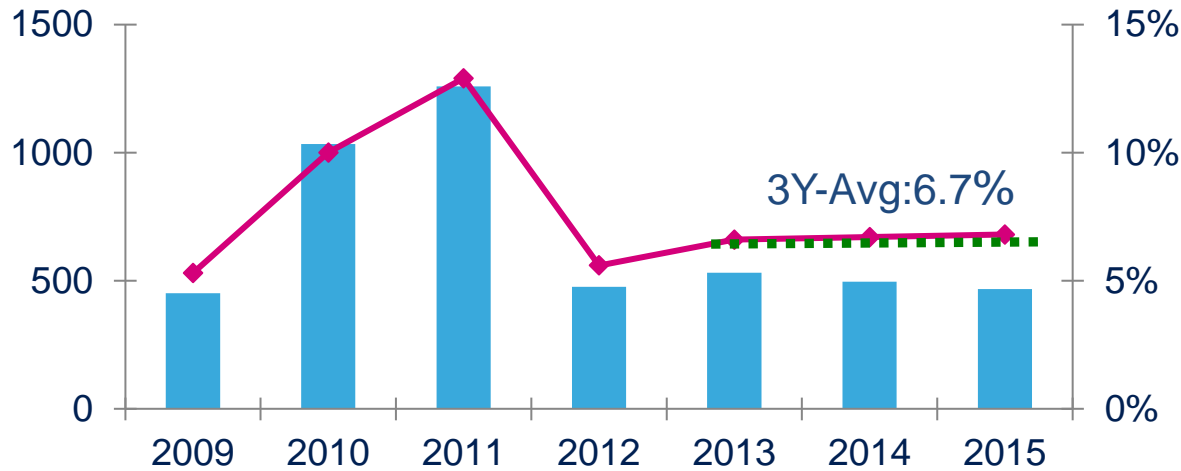
## Free Cash Flow\* generation



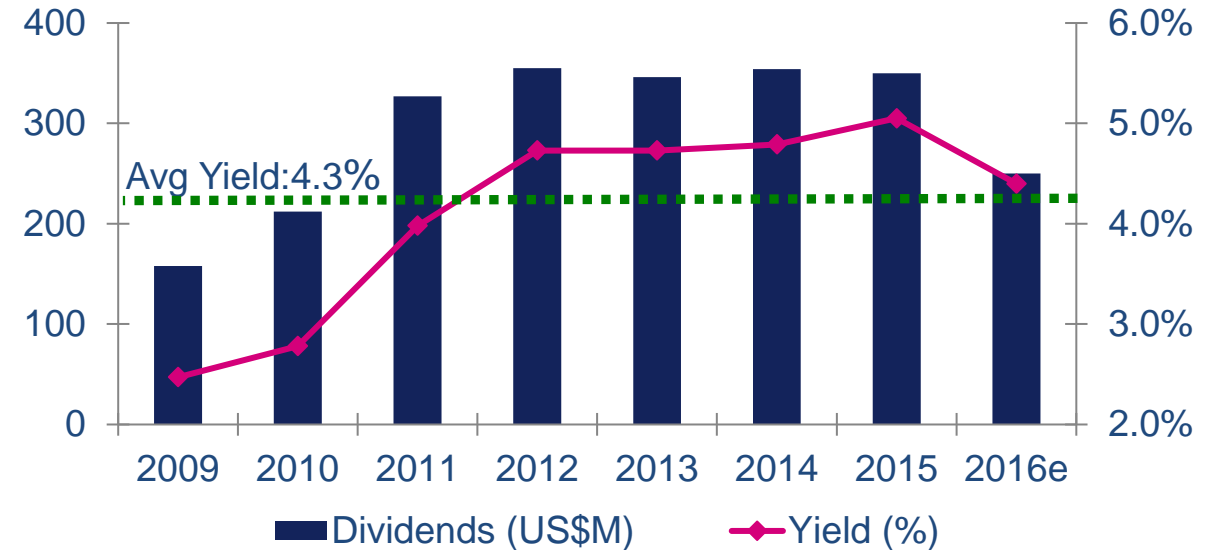
## Net Cash Balance

End of period (US\$M)	Dec 31 2014	Dec 31 2015	Apr 2 2016
Total Liquidity	2,351	2,106	2,040
Total Financial Debt	(1,801)	(1,612)	(1,601)
<b>Net Financial Position*</b>	<b>550</b>	<b>494</b>	<b>439</b>

## Capital Expenditures



## Dividends distribution

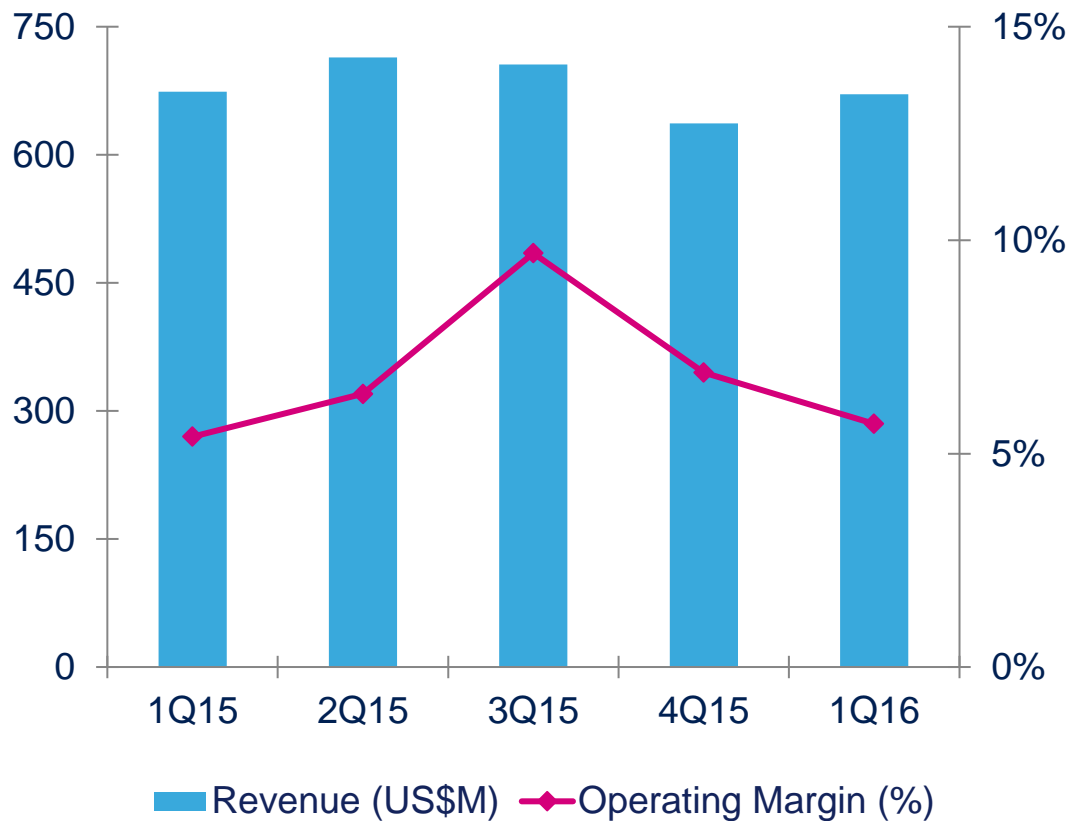


■ Capex, net of proceeds from sales (US\$M)  
◆ Capex / Sales (%)

\*Non-GAAP measures – see Appendix

# Automotive and Discrete (ADG)

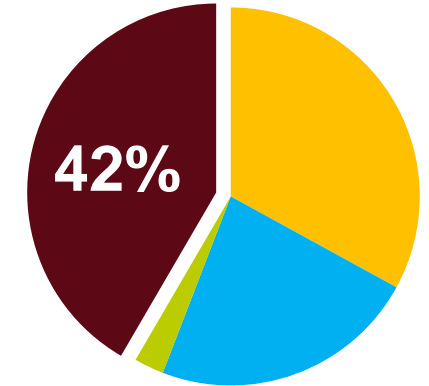
## Financial Performance



## ADG at a glance and contribution to ST 1Q16 sales

### Dedicated Automotive ICs:

- ADAS
- Chassis
- Powertrain
- Body Electronics
- Infotainment
- Automotive-grade 32-bit microcontrollers



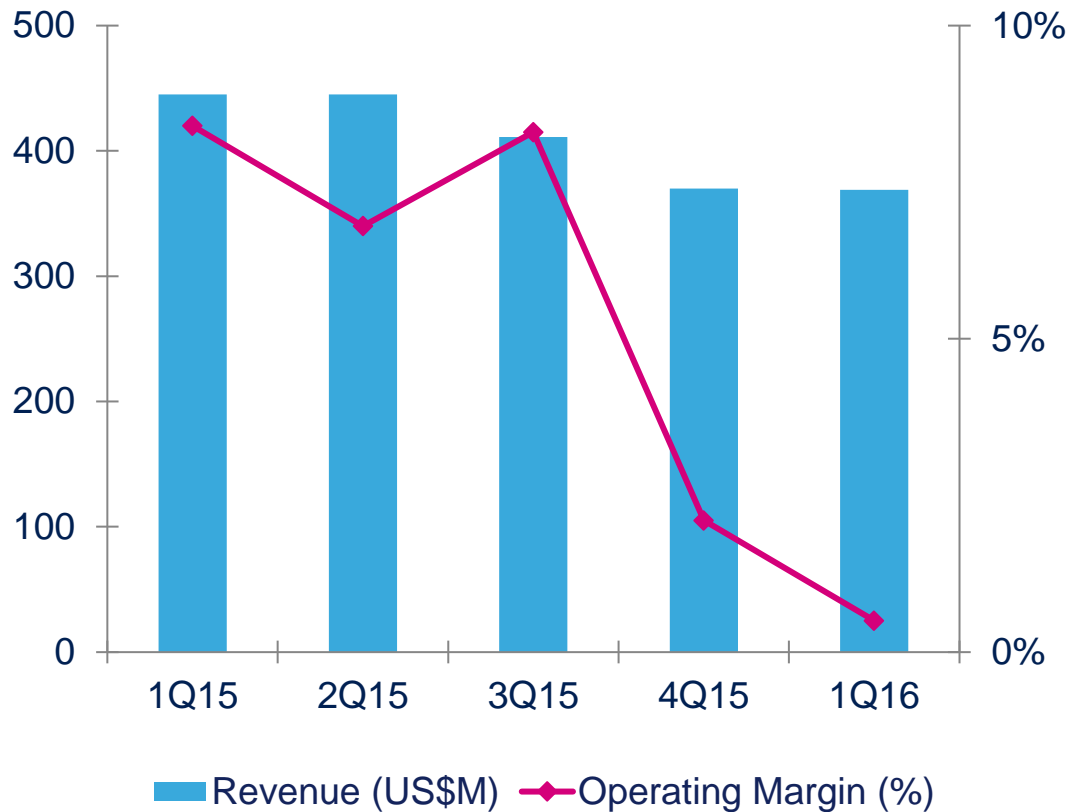
### Power Discrete:

- MOSFET, including Silicon Carbide
- IGBT and Power Bipolar Transistors
- Power rectifiers, TRIACs and protections
- Passive integration products



# Analog and MEMS (AMG)

## Financial Performance



## AMG at a glance and contribution to ST 1Q16 sales

### MEMS Sensors

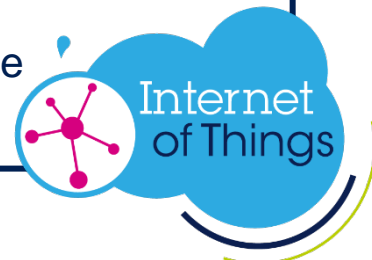
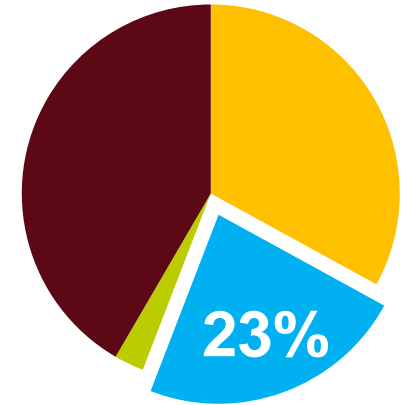
- Motion
- Acoustic
- Environmental

### MEMS Micro-actuators

- Mirrors
- Thermal / piezoelectric

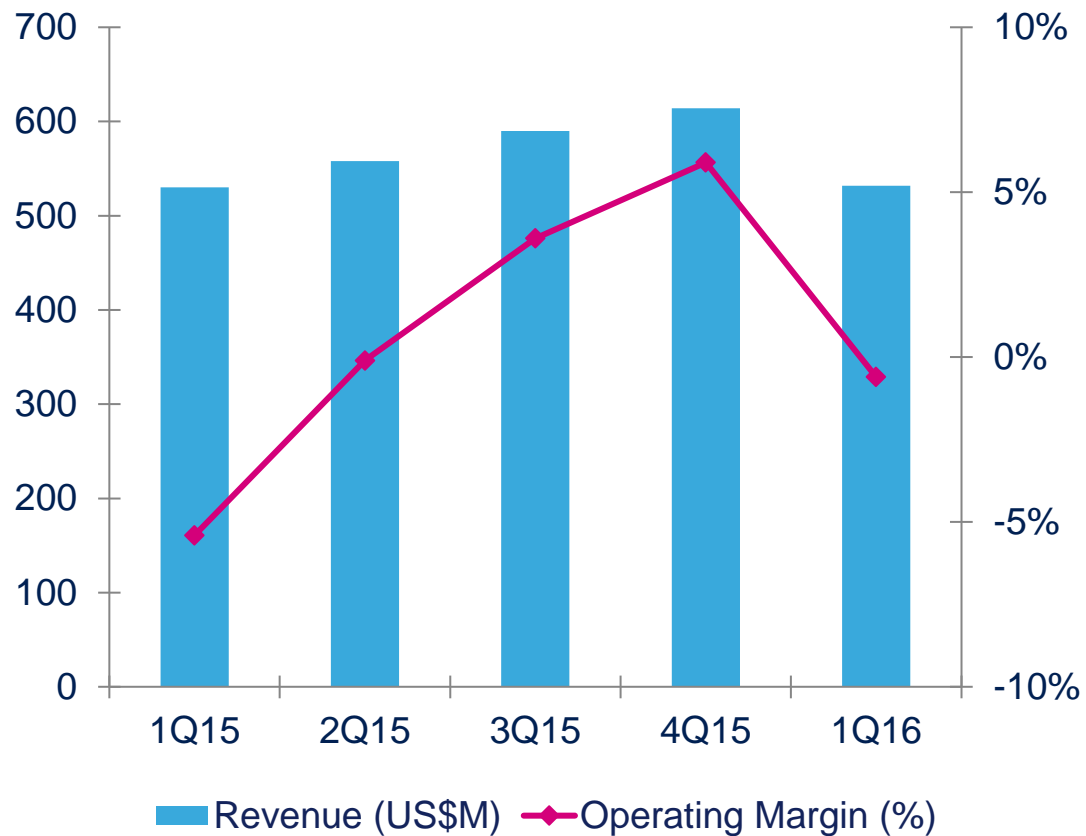
### Smart Power and Analog

- Industrial and power conversion
- General purpose analog
- Wired and wireless connectivity
- Power Management IC for mobile and portable
- Touchscreen controller



# Microcontrollers and Digital ICs (MDG)

## Financial Performance



## MDG at a glance and contribution to ST 1Q16 sales

### Microcontrollers:

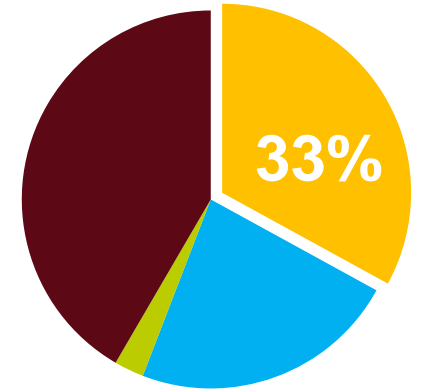
- General Purpose
- Secure

### Memories:

- EEPROM

### ASICs:

- Digital including FD-SOI
- Mixed-process Technologies including Silicon Photonics

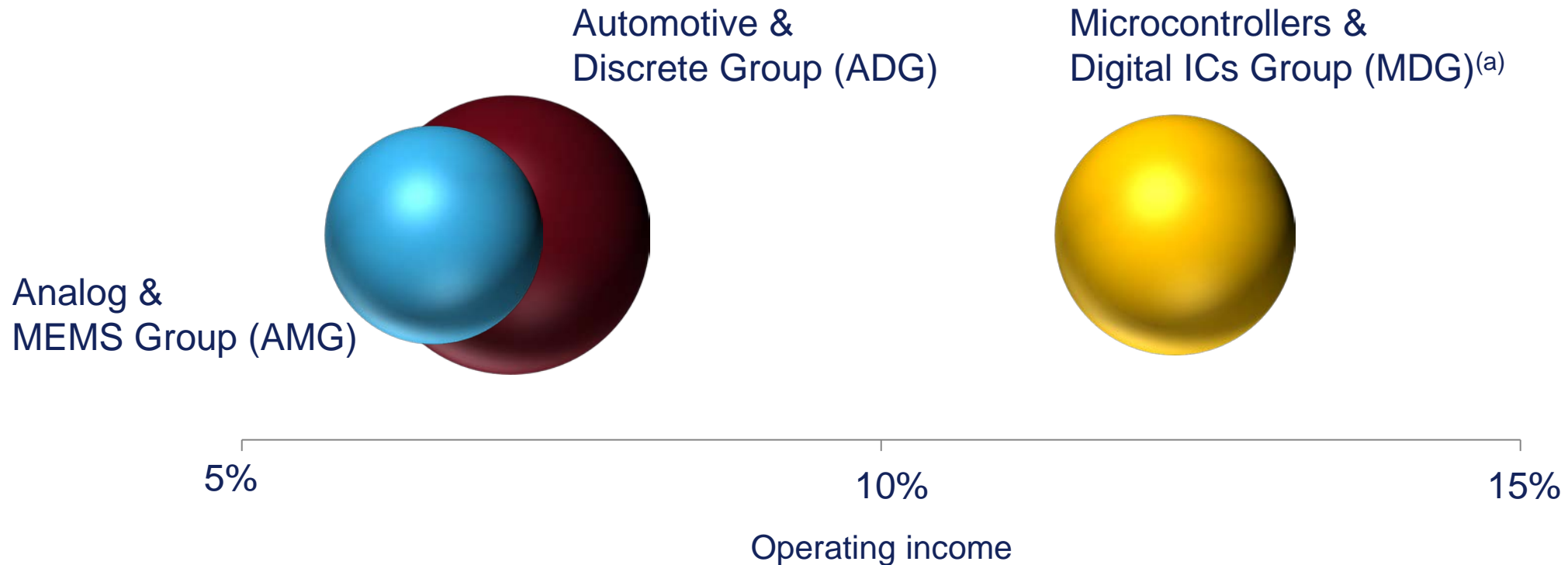


*Also includes discontinued business of Set-Top Box and former ST-Ericsson products*



# New Groups Profitability in 2015

A starting point for improvement

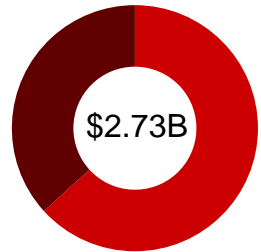


(a) MDG excludes Set-Top Box business and former ST-Ericsson products

Note: Size of bubble is proportional to revenue. Operating income before impairment and restructuring as a percentage of sales, excluding allocation of unused capacity charges.

# Revenue Drivers & Opportunities

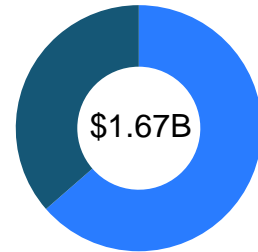
**ADG**  
2015 Revenues



■ Automotive ■ Power Discrete

- Leverage on technology leadership in Smart Power, eNVM, RF, FD-SOI and SiC
- Automotive-grade 32-bit MCU
- ADAS (Vision & Radar)
- Infotainment (Multimedia and Telematics, Navigation, Connectivity)
- ASIC and ASSP for Automotive
- ICs and discrete for car lighting
- Silicon Carbide products, MOSFET and IGBT for car electrification

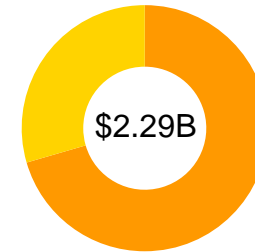
**AMG**  
2015 Revenues



■ Analog ■ MEMS

- Leverage on technology leadership in Analog and Smart Power and MEMS
- Wired and Wireless connectivity for IoT
- General purpose analog
- Power management in servers, smartphones and industrial
- Analog ASICs for industrial
- Automotive MEMS
- Micro-actuators
- Consumer MEMS recovery

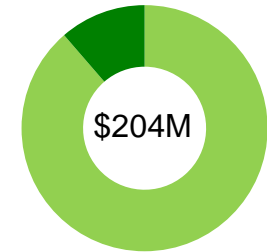
**MDG**  
2015 Revenues



■ MCU ■ Digital

- Leverage on technology leadership in eNVM, FD-SOI and RF
- General Purpose STM32 MCU
- Advanced Secure Element
- Secure contactless: banking / ID
- RF EEPROM
- Digital ASICs on FD-SOI
- Optical module ICs leveraging Silicon Photonics and BiCMOS

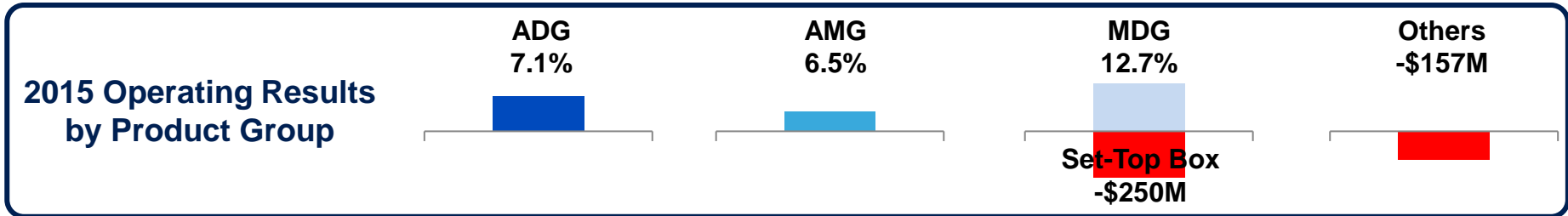
**Others**  
2015 Revenues



■ Imaging ■ Others

- Leverage on technology in CMOS sensors and pioneering "Time of Flight" Technology
- Specialized imaging sensors

# Profitability Drivers & Opportunities

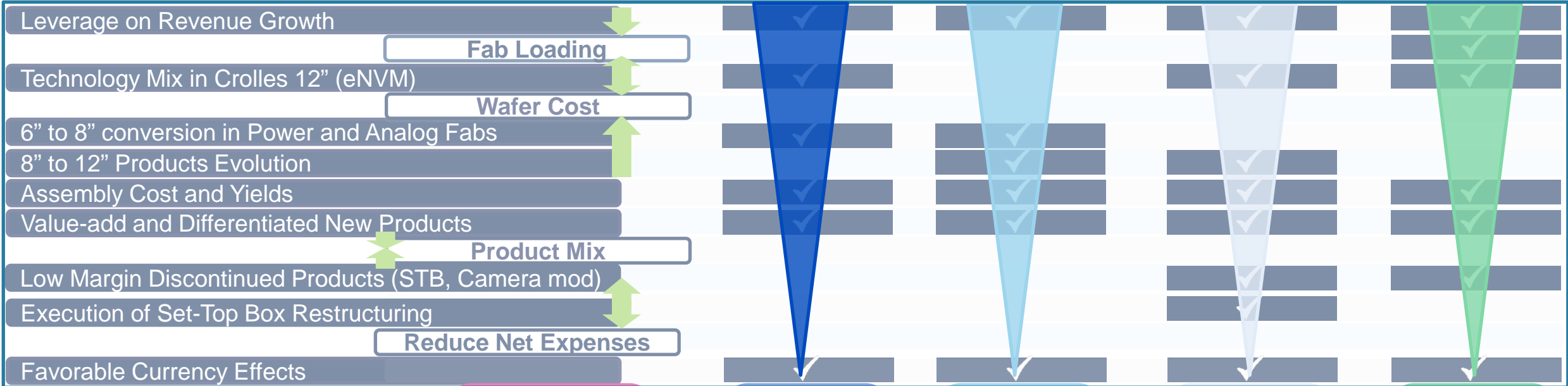
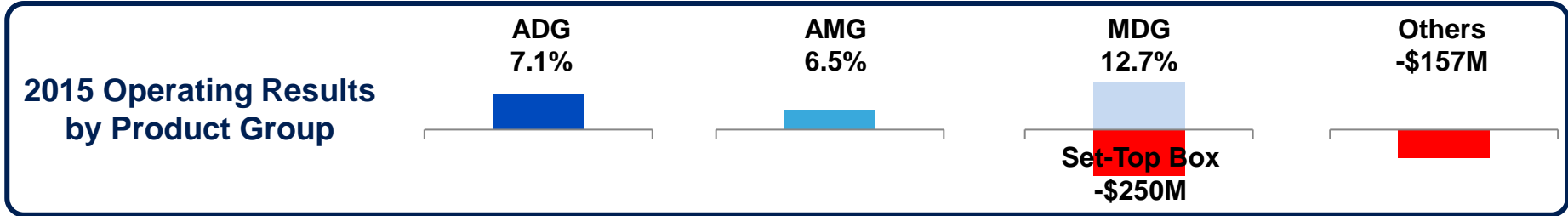


Driver/Opportunity	ADG	AMG	MDG	Others
Leverage on Revenue Growth	✓	✓	✓	✓
<b>Fab Loading</b>				✓
Technology Mix in Crolles 12" (eNVM)	✓		✓	✓
<b>Wafer Cost</b>				
6" to 8" conversion in Power and Analog Fabs	✓	✓		
8" to 12" Products Evolution		✓	✓	
Assembly Cost and Yields	✓	✓	✓	✓
Value-add and Differentiated New Products	✓	✓	✓	✓
<b>Product Mix</b>				
Low Margin Discontinued Products (STB, Camera mod)			✓	✓
Execution of Set-Top Box Restructuring			✓	
<b>Reduce Net Expenses</b>				
Favorable Currency Effects	✓	✓	✓	✓



Note: Base FY2015

# Profitability Drivers & Opportunities



**Mid-term Target**

**>10%**

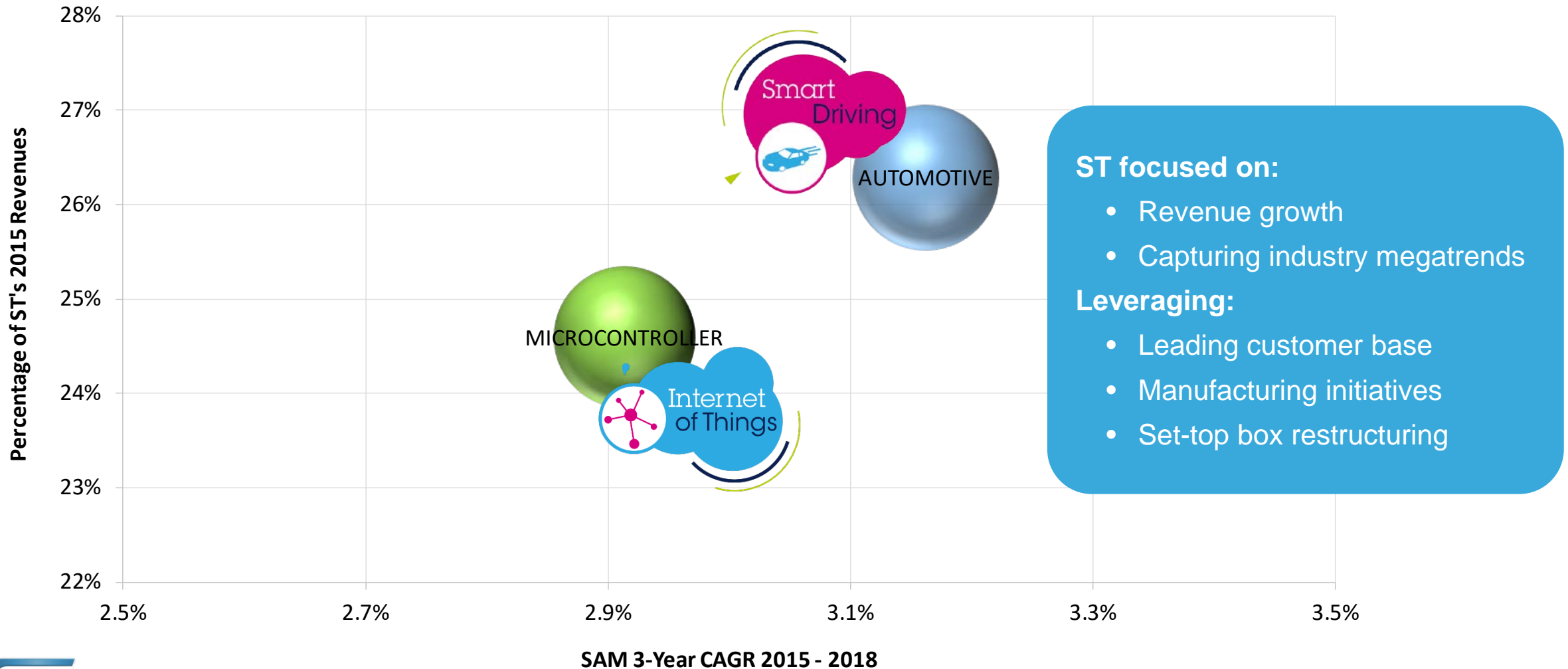
**Mid-high single digit %**

**>10%**

**Profit**

# ST Revenue Focus:

Addresses high-growth areas to boost profitability



**ST focused on:**

- Revenue growth
- Capturing industry megatrends

**Leveraging:**

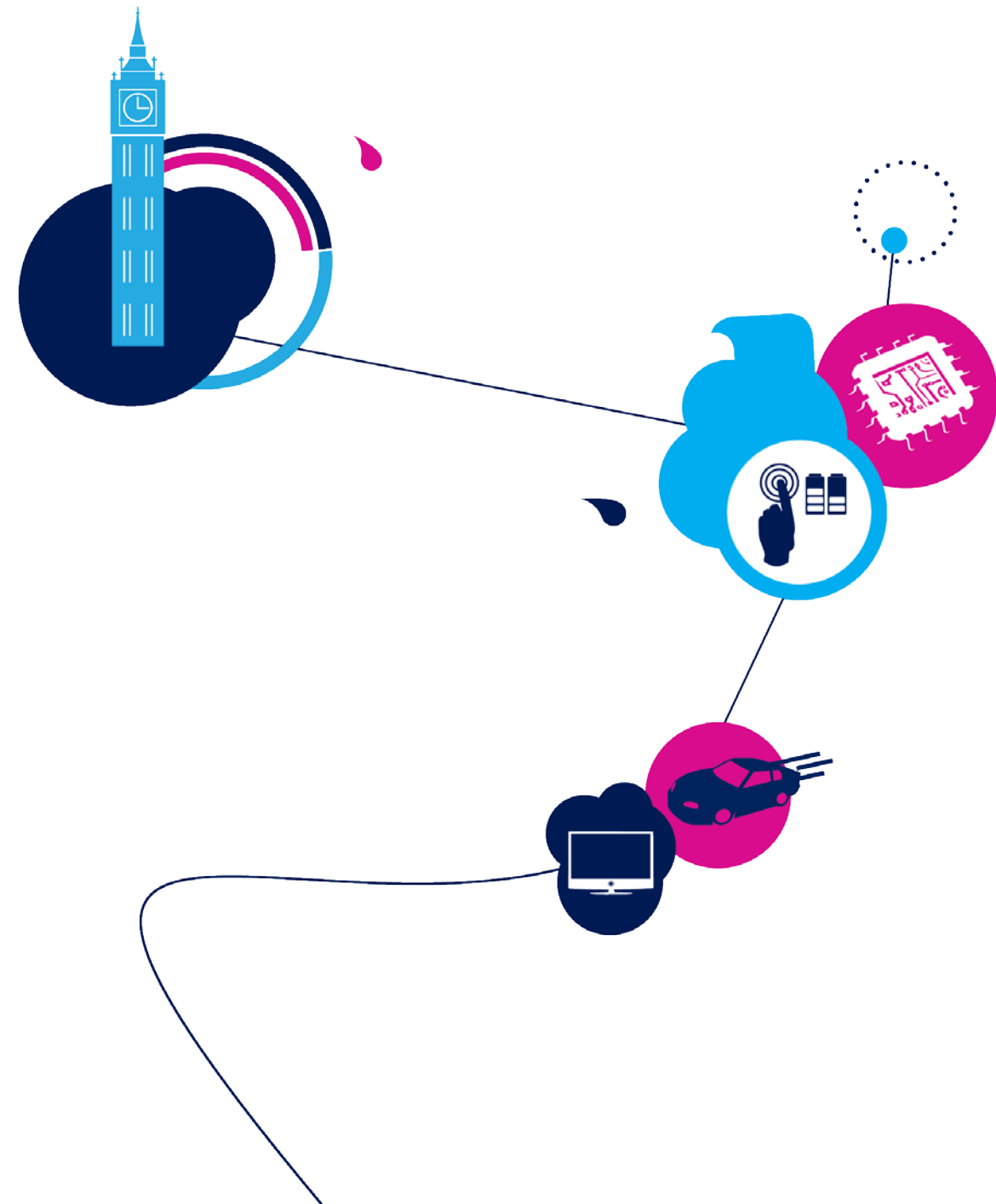
- Leading customer base
- Manufacturing initiatives
- Set-top box restructuring



Note: Size of bubble is proportional to ST's revenue.

Source: Company data, WSTS

# Appendix



# Product Group Data

In 1Q16, ST realigned its product families into three product groups: Automotive and Discrete Group (ADG); Analog and MEMS Group (AMG) and Microcontrollers and Digital ICs Group (MDG). MDG includes ST's set-top-box business which is currently undergoing a restructuring targeting annualized savings of \$170 million upon completion. All prior-period amounts have been retrospectively aligned to the 2016 reporting segments.

<i>Million US\$</i>	1Q15	2Q15	3Q15	4Q15	FY15	1Q16
<b>Automotive and Discrete Group (ADG)</b>						
- Net Revenues	674	714	706	637	2,731	<b>671</b>
- Operating Income (Loss)	36	46	68	44	194	<b>39</b>
<b>Analog and MEMS Group (AMG)</b>						
- Net Revenues	445	445	411	370	1,671	<b>369</b>
- Operating Income (Loss)	37	30	34	8	109	<b>2</b>
<b>Microcontrollers and Digital ICs Group (MDG)</b>						
- Net Revenues	530	558	590	614	2,292	<b>532</b>
- Operating Income (Loss)	(28)	(1)	22	36	29	<b>(3)</b>
<b>Others *</b>						
- Net Revenues	56	43	57	47	203	<b>41</b>
- Operating Income (Loss)	(64)	(63)	(33)	(63)	(223)	<b>(71)</b>
<b>Total</b>						
- Net Revenues	<b>1,705</b>	<b>1,760</b>	<b>1,764</b>	<b>1,668</b>	<b>6,897</b>	<b>1,613</b>
- Operating Income (Loss)	<b>(19)</b>	<b>12</b>	<b>91</b>	<b>25</b>	<b>109</b>	<b>(33)</b>

# Financial Performance

<i>In US\$M, except EPS</i>	1Q15	2Q15	3Q15	4Q15	FY14*	FY15	1Q16
<b>Net Revenues</b>	1,705	1,760	1,764	1,668	7,404	6,897	1,613
<b>Gross Margin</b>	33.2%	33.8%	34.8%	33.5%	33.7%*	33.8%	33.4%
<b>Operating Income (Loss) before impairment, restructuring**</b> Operating Margin before impairment, restructuring**	10 0.6%	33 1.9%	102 5.8%	29 1.7%	258* 3.5%	174 2.5%	(5) (0.3%)
<b>Net Income – Reported</b>	(22)	35	90	2	128*	104	(41)
<b>EPS Diluted</b>	(0.03)	0.04	0.10	0.00	0.14	0.12	(0.05)
<b>Adjusted EPS Diluted**</b>	0.01	0.06	0.12	0.00	0.29	0.19	(0.02)
<b>Free Cash Flow**</b>	41	53	85	148	197	327	31
<b>Net Financial Position</b>	512	459	459	494	550	494	439
<b>Effective Exchange Rate €/\$</b>	1.23	1.17	1.16	1.11	1.34	1.17	1.10

\* Includes Nano2017 catch-up: the European Union approved the funding for the Nano2017 R&D program for the period 2013 to 2017 in June 2014; as a consequence, FY14 include a pre-tax profit of \$97 million for grants related to FY13 (including 18 bps impact in gross margin)

\*\*See appendix



# Pre-Tax Items to Adjusted Earnings\*

OPERATING RESULT	<i>In US\$M</i>	1Q15	2Q15	3Q15	4Q15	1Q16
	<b>NET EARNINGS</b>					
	<b>U.S. GAAP Net Earnings</b>	(22)	35	90	2	(41)
	Impairment & Restructuring	29	21	11	4	28
	Estimated Income Tax Effect	(1)	(1)	-	(4)	(3)
	<b>Adjusted Net Earnings*</b>	6	55	101	2	(16)

- **Free cash flow** is defined as net cash from operating activities minus net cash from (used in) investing activities, excluding payment for purchases (proceeds from the sale of) marketable securities and net cash variation for joint venture deconsolidation. We believe free cash flow provides useful information for investors and management because it measures our capacity to generate cash from our operating and investing activities to sustain our operating activities. Free cash flow is not a U.S. GAAP measure and does not represent total cash flow since it does not include the cash flows generated by or used in financing activities. In addition, our definition of free cash flow may differ from definitions used by other companies.
- **Net financial position** resources (debt) represents the balance between our total financial resources and our total financial debt. Our total financial resources include cash and cash equivalents, marketable securities, short-term deposits and restricted cash, and our total financial debt includes short term borrowings, current portion of long-term debt and long-term debt, all as reported in our consolidated balance sheet. We believe our net financial position provides useful information for investors because it gives evidence of our global position either in terms of net indebtedness or net cash position by measuring our capital resources based on cash, cash equivalents and marketable securities and the total level of our financial indebtedness. Net financial position is not a U.S. GAAP measure.
- **Operating income before impairment and restructuring charges** excludes impairment, restructuring charges and other related closure costs. It is used by management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items.
- **Adjusted net earnings and earnings per share (EPS)** are used by our management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items like impairment, restructuring charges and other related closure costs, net of the relevant tax impact.
- **Net revenues of “Others”** includes revenues from sales of Imaging Product Division, Subsystems, assembly services, and other revenue. **Operating income (loss) of “Others”** includes items such as unused capacity charges, impairment, restructuring charges and other related closure costs, phase out and start-up costs, and other unallocated expenses such as: strategic or special research and development programs, certain corporate-level operating expenses, patent claims and litigations, and other costs that are not allocated to product groups, as well as operating earnings of the Imaging Product Division, Subsystems and other products. “Others” includes \$10 million, \$30 million, and \$19 million of unused capacity charges in the first quarter of 2016 and fourth and first quarters of 2015, respectively; and \$28 million, \$4 million, and \$29 million of impairment, restructuring charges, and other related closure costs in the first quarter of 2016 and fourth and first quarters of 2015, respectively.



# Technology & Manufacturing

**Jean-Marc Chery**

Chief Operating Officer



# Front-End Manufacturing

## Unique capability

Technology portfolio aligned with application focus areas

Flexible IDM model with foundry partners

- Internal / external technology complementarity
- Manufacturing capacity flexibility at foundry

Clustering approach



### 6 Front-End sites, including 3 R&D centers

Digital		Analog and Power	
<b>Crolles</b> <small>R&amp;D</small>	FD-SOI Logic BiCMOS & RF Image Sensors Embedded-NVM	<b>Tours</b>	Power Discrete Passive integration
<b>Rousset</b>	Embedded-NVM	<b>Agrate</b> <small>R&amp;D</small>	Advanced BCD MEMS
		<b>Catania</b> <small>R&amp;D</small>	Advanced BCD MOSFET and Silicon Carbide
		<b>Singapore</b>	Power Discrete BCD

Foundry partners

# Back-End Manufacturing

## Unique capability

Packaging portfolio aligned with application focus areas

Internal and external complementarity

Combining specialized packages and mass production capability



### Back-End: 5 manufacturing sites + R&D centers offering over 400 packages

<b>Bouskoura</b>	SOIC Power SO Power TO	<b>Calamba</b>	QFN BGA LGA (MEMS)	<b>Shenzhen</b>	SOIC Power SO / Power TO WLCSP Optical sensor package
<b>Kirkop</b>	LGA (MEMS) Sensor package BGA QFP	<b>Muar</b>	QFP SOIC Power SO BGA	<b>Grenoble Agrate Singapore Kirkop</b>	Package R&D & Central Engineering

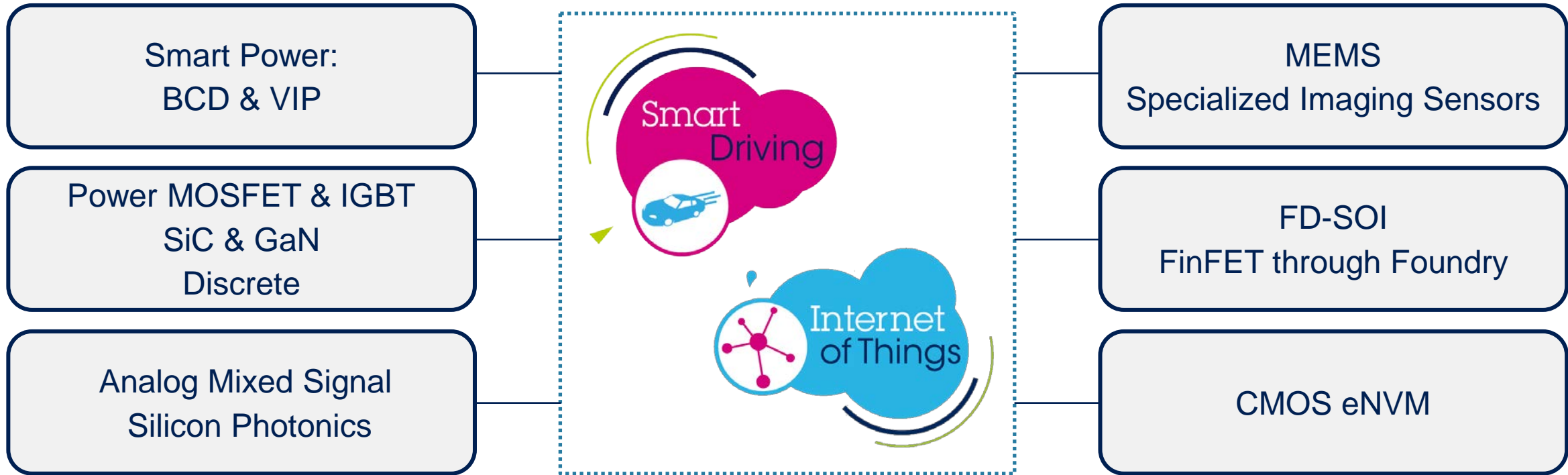
OSAT partners



# Technology Portfolio

aligned with strategic focus areas

The leading provider of technologies enabling solutions for Smart Driving and the Internet of Things



Package technologies	Leadframe	Sensors
	Laminate	Wafer level

# Advanced CMOS Roadmap

- Mass Production
- Development
- Development at foundry
- Research

FD-SOI

> 40% speed  
- 50% power

FD-SOI next

FinFET

Derivatives

FD-SOI 28nm



Body Bias, cost, simplicity, reliability

RF, Mixed Signal

Ultra Low Power

Embedded Non Volatile



Differentiated options for the long-lasting 28nm process node

# FD-SoC Fast Growing Ecosystem





40nm eFLASH technology for advanced MCUs  
addressing a wide range of applications



## Consumer

- High performance logic for 32-bit MCUs
- State of the art Flash technology
- Competitive solution

## Secure

- High performance page Flash erasable
- High robustness
- Competitive solution




## Automotive & Industrial

- High performance logic for 32-bit MCUs
- State of the art Flash technology
- High reliability with extended temperature



### Smart Things

Camera assist, ranging, gesture



### Smart Home & City


Robot cleaners, light control, toys



**True distance measurement**  
*Independent of target size, color & reflectance*

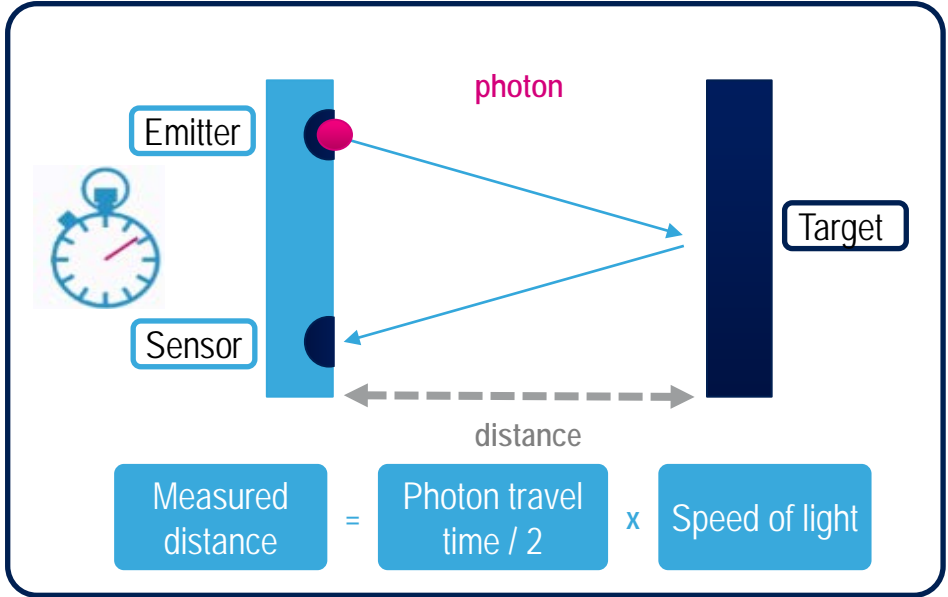
### Smart Driving

Infotainment system control



### Smart Industry

Detection, door control, robotics



## BiCMOS55

Continuous evolution of **Silicon Germanium** & CMOS solutions improving performance vs. complexity trade-off

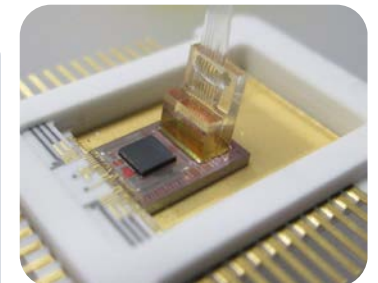
$f_T > 300$  GHz  
 $f_{MAX} > 400$  GHz

## High Bandwidth – Power efficiency

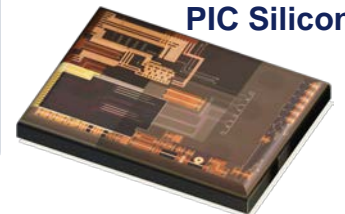
## Silicon Photonics

Enabling **high-speed optical** interconnection with **optimal space usage**, ranging from short to long-reach communication

- WAN: Transport, subway, access
- Enterprise  
Rack to rack, board to board  
LAN, data centers, routers, switches, HPC



PIC Silicon



# BCD Technology Segmentation

**High Voltage BCD**  
700V – 6KV

BCD6s Offline (0.32µm)  
BCD6s HV Transformer (0.32µm)

**SOI BCD**  
190V – 300V

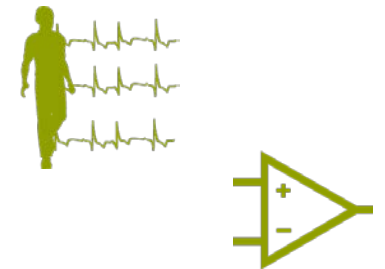
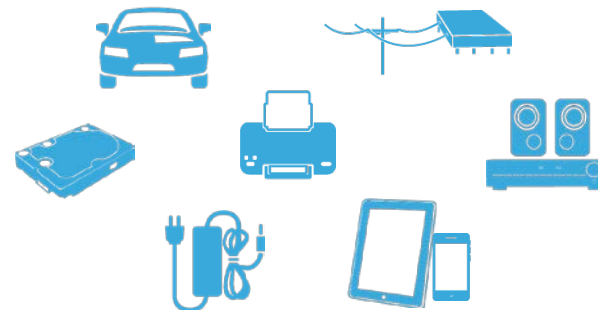
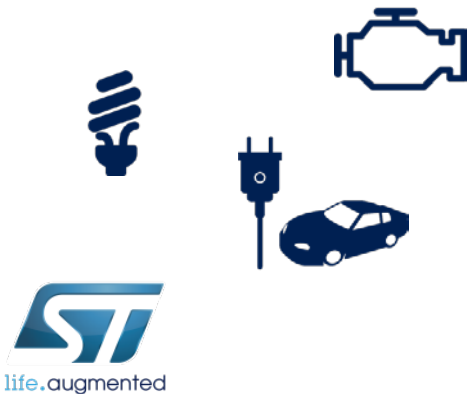
SOI-BCD6s (0.32µm)  
SOI-BCD8s (0.16µm)  
SOI-BCD9s (0.11µm)

**Advanced BCD**  
7V – 100V

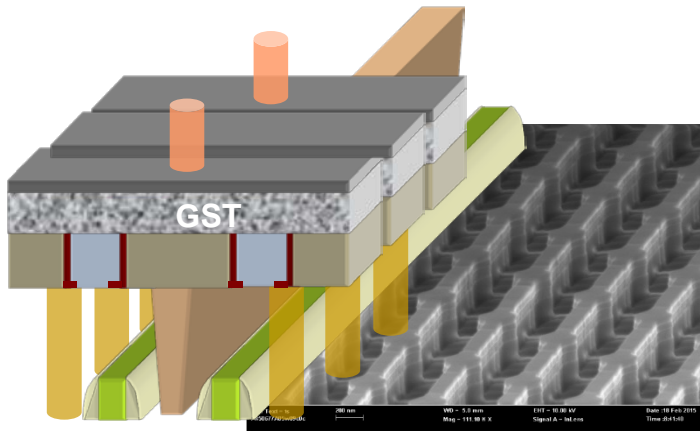
BCD8As – BCD8sP (0.16µm)  
BCD8sAUTO (0.16µm)  
BCD9s – BCD9sL (0.11µm)  
BCD10 (90nm)  
BCD11 (65nm)

**High Voltage CMOS**  
16V – 40V

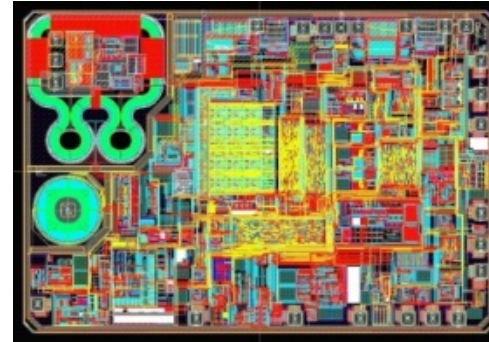
HVCMOS8 (0.18µm)  
HVG8A (0.18µm)  
HVCMOS9 (0.11µm)



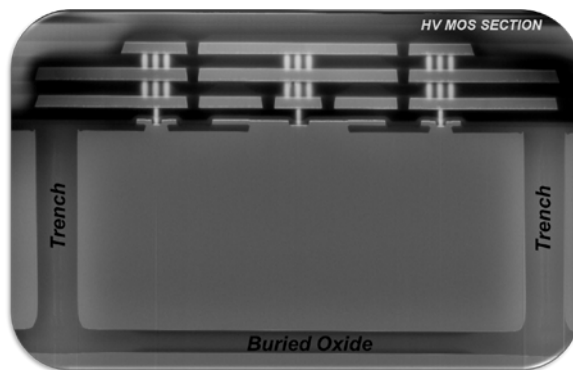
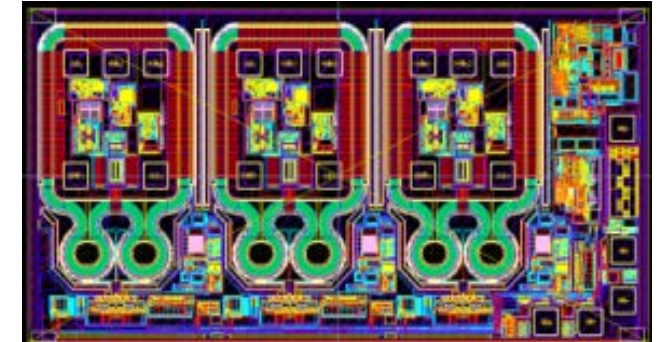
# Differentiation in BCD Technology



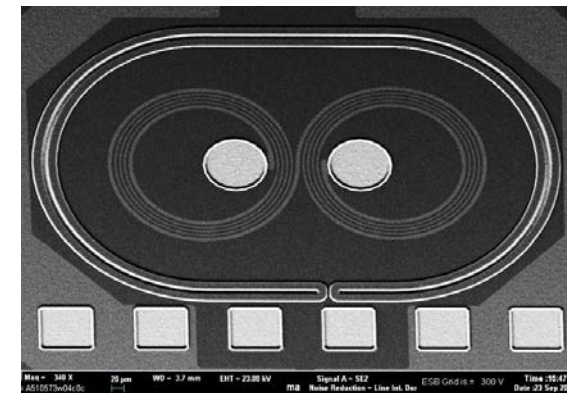
ePCM (Phase Change Memory)  
in 110nm/90nm BCD Platforms for SOC



HV (600V to 1200V) Gate Drivers  
on 0.32um BCD Platforms



HV on SOI (200V to 300V)  
on 0.16um BCD Platforms



Galvanic Isolation (4KV to 6KV)  
on 0.32um – 0.16um BCD Platforms

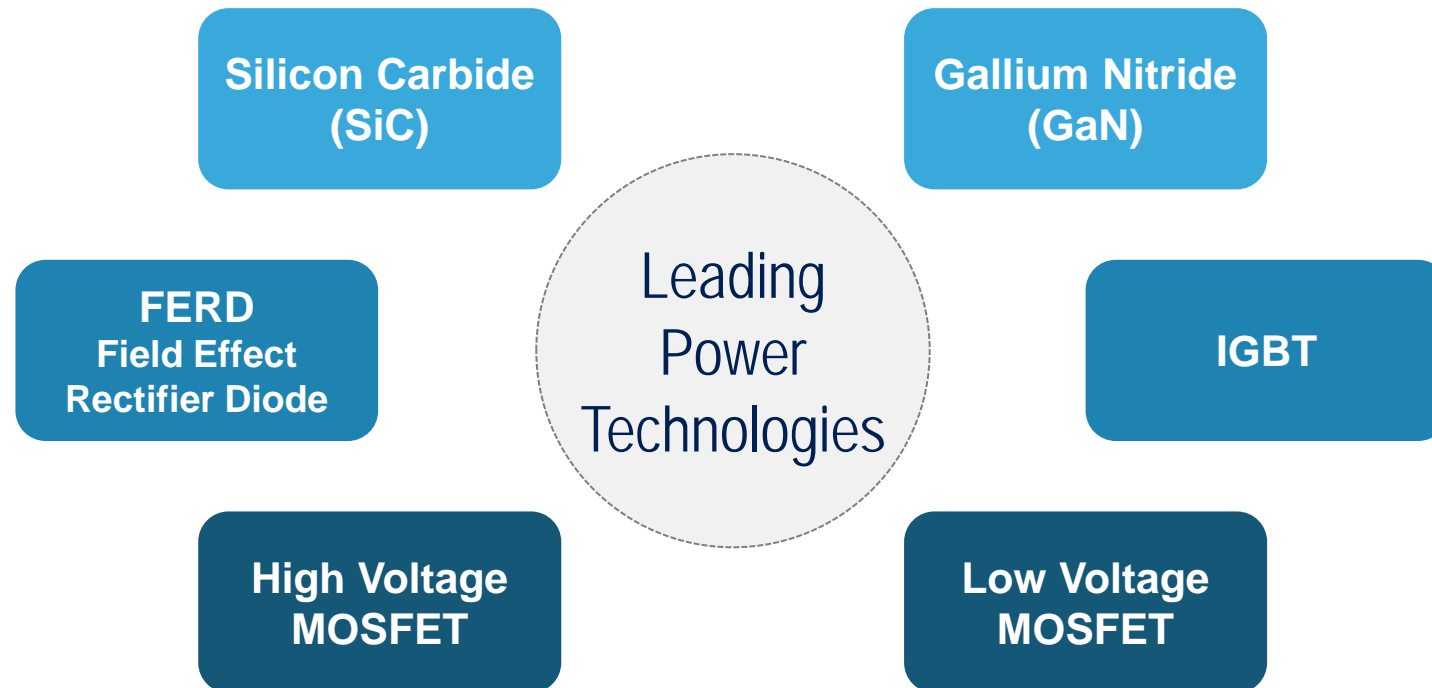
# Power Discrete Technologies

Broad spectrum of technologies specifically tuned to the needs of final applications

Established **leadership** in **high-voltage** and **very-high voltage** MOSFETs

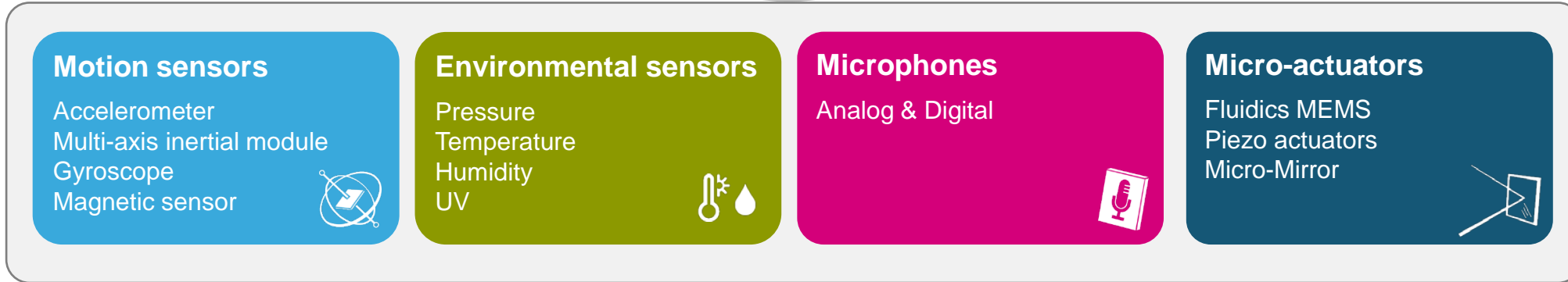
ST is **the only supplier now** qualifying **SiC MOSFETs** at **200°C** for 650, 1200 & 1700V

Introducing **new highly competitive IGBTs** and **Low Voltage MOSFETs**



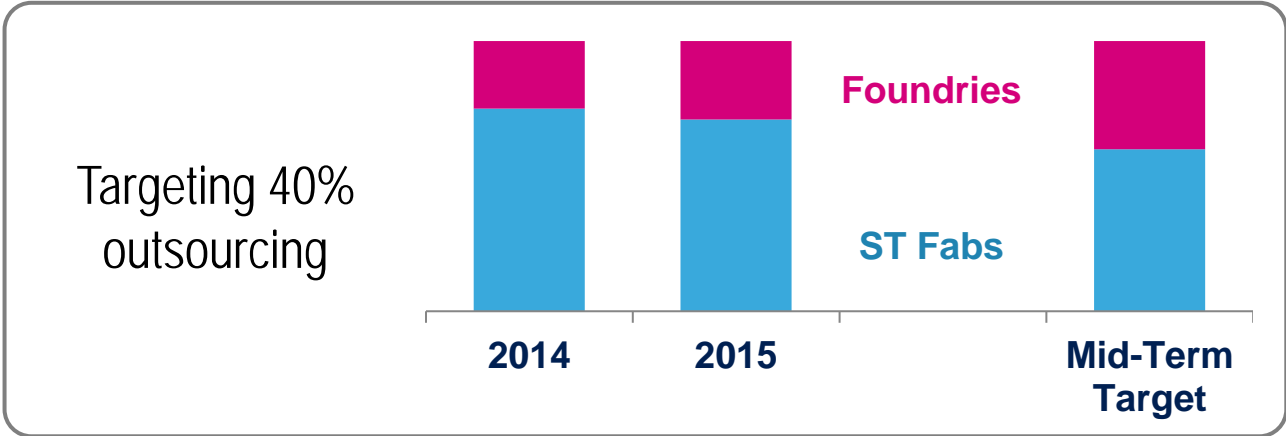
# Unique Blend of Technologies

## for sensors and micro-actuators



# Digital Manufacturing Strategy

- Multiple sourcing through technology & manufacturing partnerships
- Rousset / Crolles clustering
- Crolles 300mm increase of scale on differentiated technologies according to demand



Technology		Driver/First	Second
CMOS Bulk	≥40nm	Crolles 300	Foundry
	<40nm	Foundry	Crolles 300
CMOS FD-SOI		Crolles 300	Foundry
FinFET		Foundry	
Specialized Imaging		Crolles 300	
BiCMOS	≥90nm	Crolles 200	
	<90nm	Crolles 300	
Silicon Photonics		Crolles 300	
HCMOS9A		Crolles 200	Crolles 300
CMOS eNVM	≥90nm	Rousset 200	Foundry
	<90nm	Crolles 300	Foundry



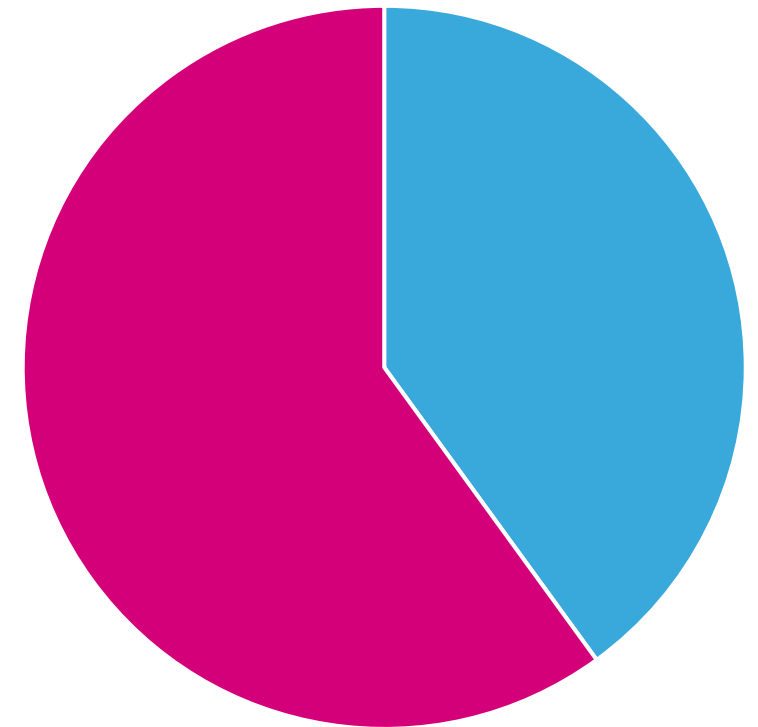
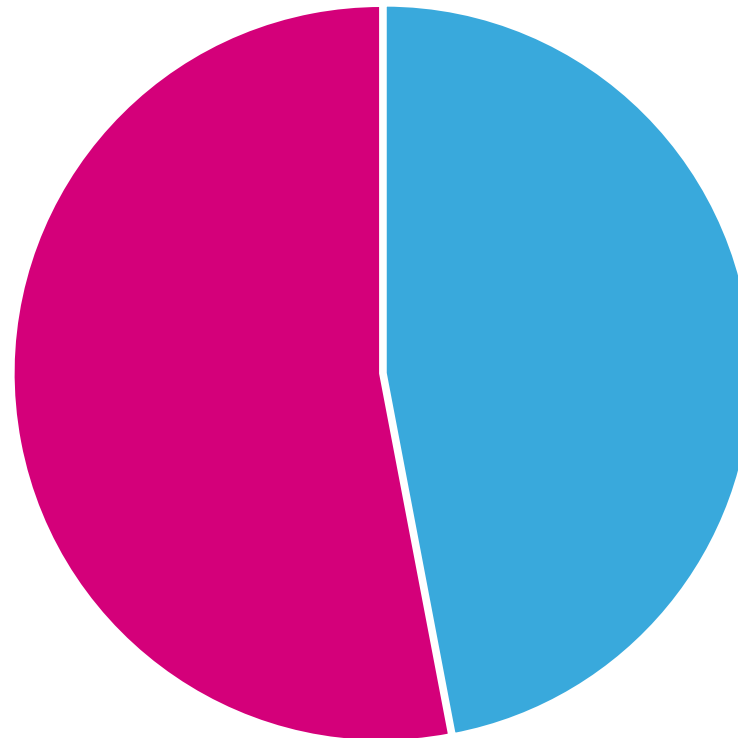
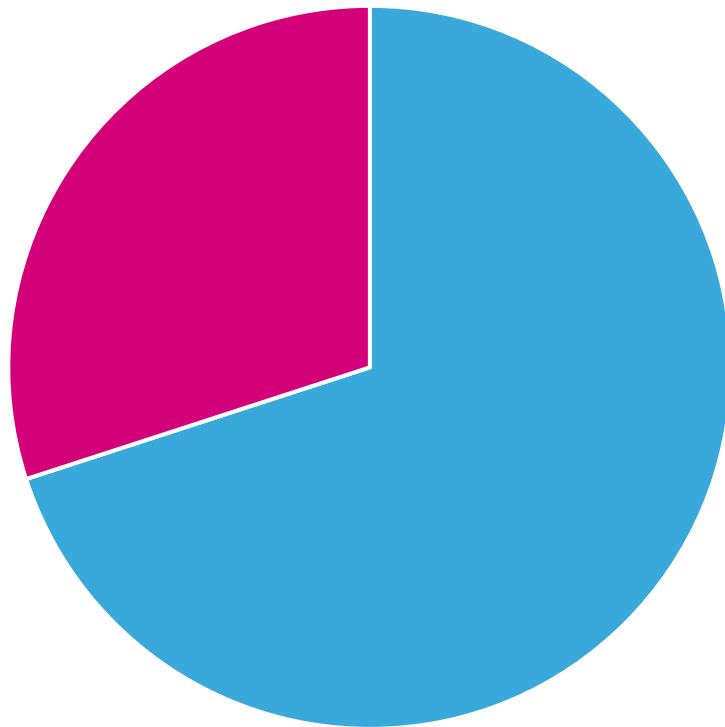
# Crolles 300mm


## Mix evolution with volume growth

4Q14

4Q15

4Q17e



-  Embedded Flash
-  Advanced Logic and Specialized Imaging

## Leading Technologies

- Smart Power BCD9s automotive grade
- MEMS: motion, microphone, actuators, PZT
- Trench Power MOSFET
- SiC Power MOSFET automotive grade in 6"
- New Integrated Passive Devices in 8"

## Cost efficiency

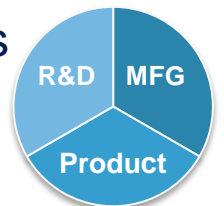
- Singapore - 8" expansion in Power discrete & BCD
- Catania - 8" expansion and 6" phase-out
- Flexibility at Foundries

## 4 Front-End sites

<b>Tours</b>	Power Discrete Passive integration	<b>Catania</b>	Advanced BCD MOSFET and Silicon Carbide
<b>Agrate</b>	Advanced BCD MEMS	<b>Singapore</b>	Power Discrete BCD

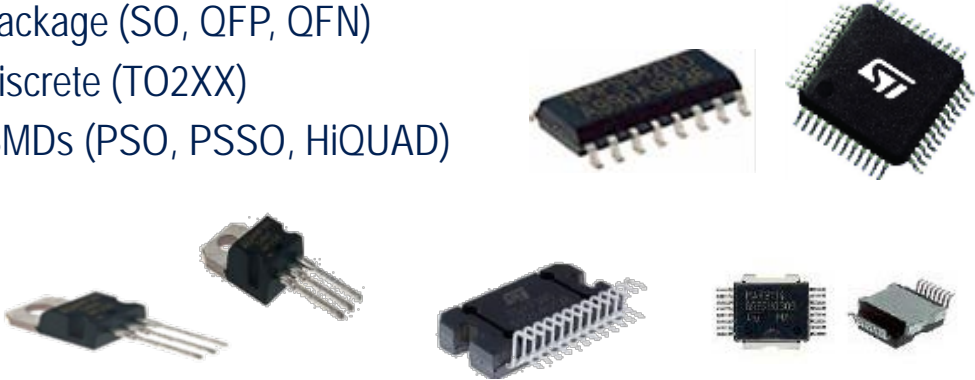
## Integrated Manufacturing & R&D

Agrate & Catania excellence centers  
Time to market – time to volume  
Clusters of leadership



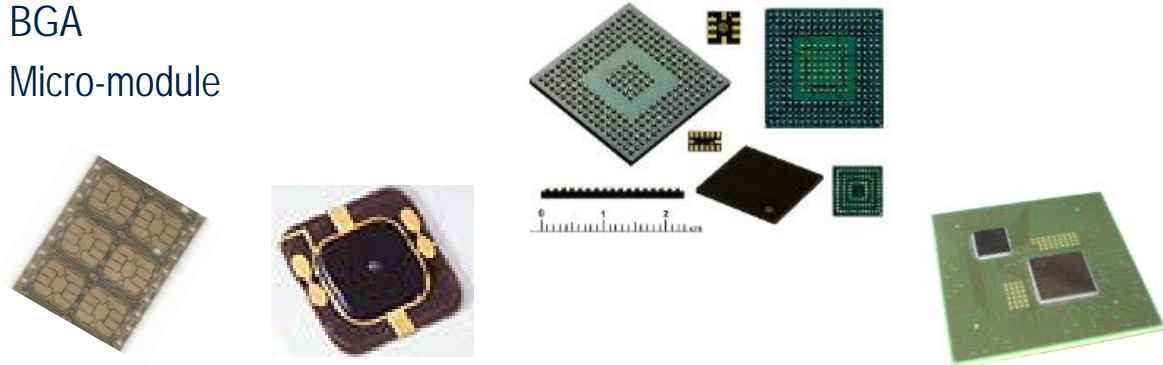
## Lead frame package

Signal package (SO, QFP, QFN)  
Power discrete (TO2XX)  
Power SMDs (PSO, PSSO, HiQUAD)



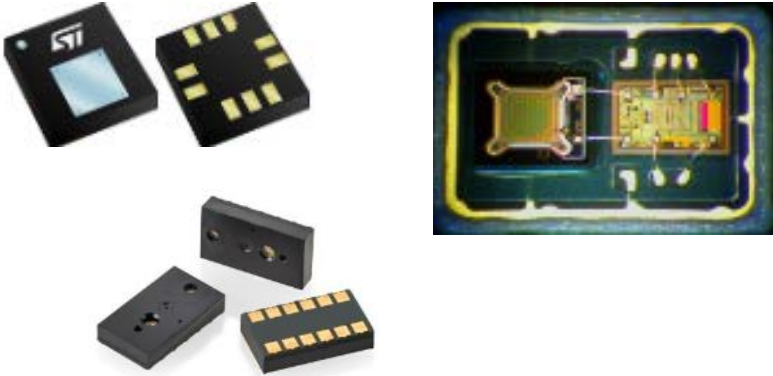
## Laminate package

BGA  
Micro-module

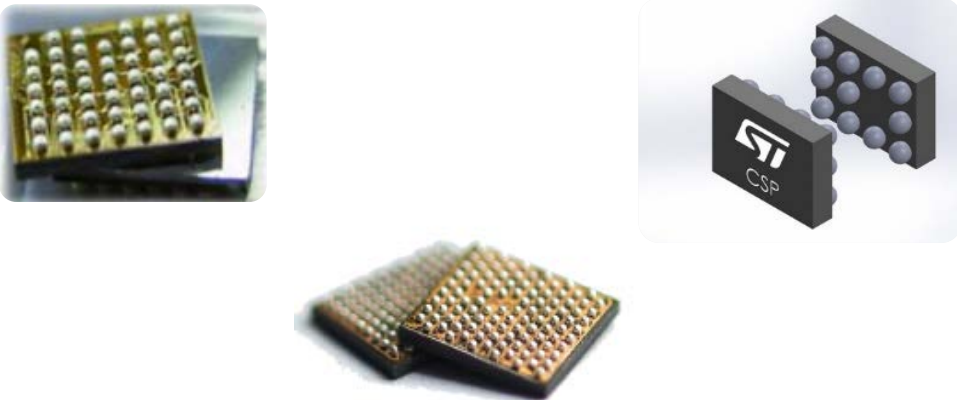


## Sensor package

MEMS  
Time-of-Flight sensor



## Wafer-level package



## Leading Technologies

- System in Package (SiP), Motion MEMS, microphone, PZT
- Ultra thin wafers (< 50 micron)
- Very-low laminate substrates (<0.13mm)
- WLCSP
- 3D integration, flip chip interconnect
- Stacked die and Silver wires (0.8-2.0 mils) on lead frame package
- Super High Density lead frames (110mm width)

## Cost efficiency

- Big Data analytics (predictive maintenance, time to yield, die pairing )
- Factory automation
- Material supply chain
- Flexibility at foundries

## Integrated Manufacturing & R&D

Kirkop excellence center

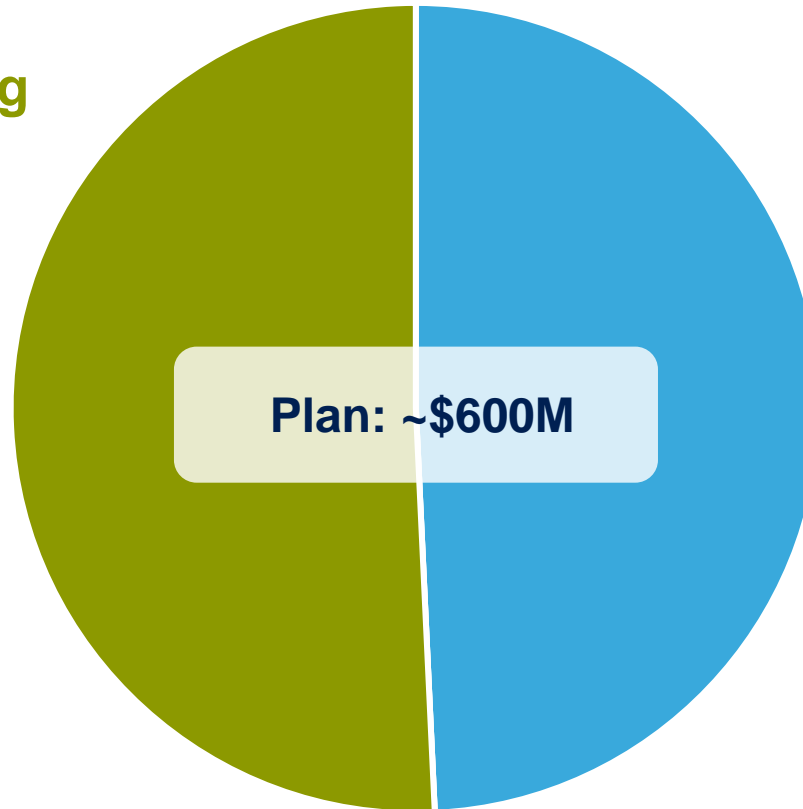
Time to market – time to volume

Design in quality

# 2016 Capital Spending

## Probing, Assembly & Testing

- New packaging development
- Capacity growth in certain packages and testers
- Specific investment in factory automation and productivity improvement



## Front-End Manufacturing/R&D

- New technologies in Crolles 300mm
- Mix evolution to advanced BCD and new MEMS actuators in Agrate
- Expanding 200mm advanced BCD, SiC in Catania
- Ramp-up 200mm in Singapore for Power Discrete & BCD
- Investment in capacity for new passive integration devices in Tours

**Investments focused on:**  
Strategic business growth and key product ramps  
Proprietary technology and manufacturing

# Technology & Manufacturing Takeaways

46

- Manufacturing and technology R&D fully aligned with application focus areas
- Combination of specialized and mass production offering with optimized internal and external allocation

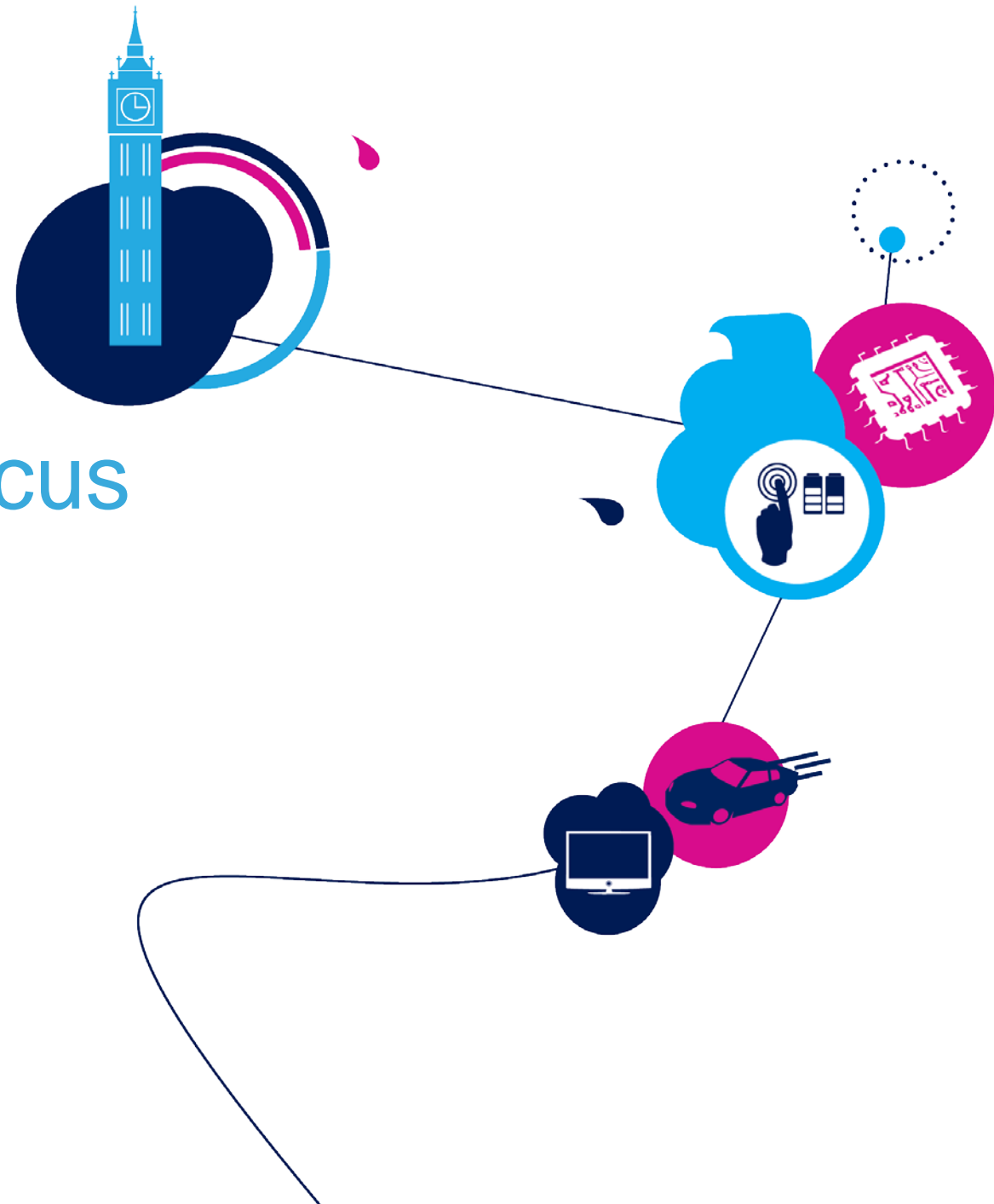
## Key programs

- Strengthening FD-SOI and FinFET through foundry
- Proliferating eNVM
- BCD mix evolution and roadmap
- Differentiated technologies for Power Discrete, BiCMOS, MEMS and specialized imaging sensors
- Wafer Level Chip Scale Package through OSAT
- System in Package

# Application Strategic Focus

**Georges Penalver**

Chief Strategy Officer

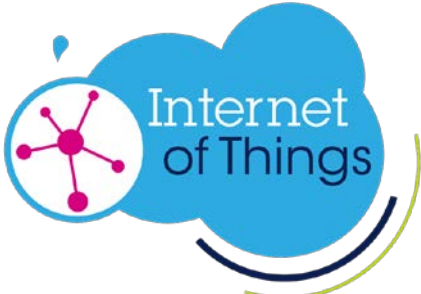


# Application Strategic Focus

The leading provider of products and solutions for Smart Driving and the Internet of Things



Safer		More connected
	Greener	



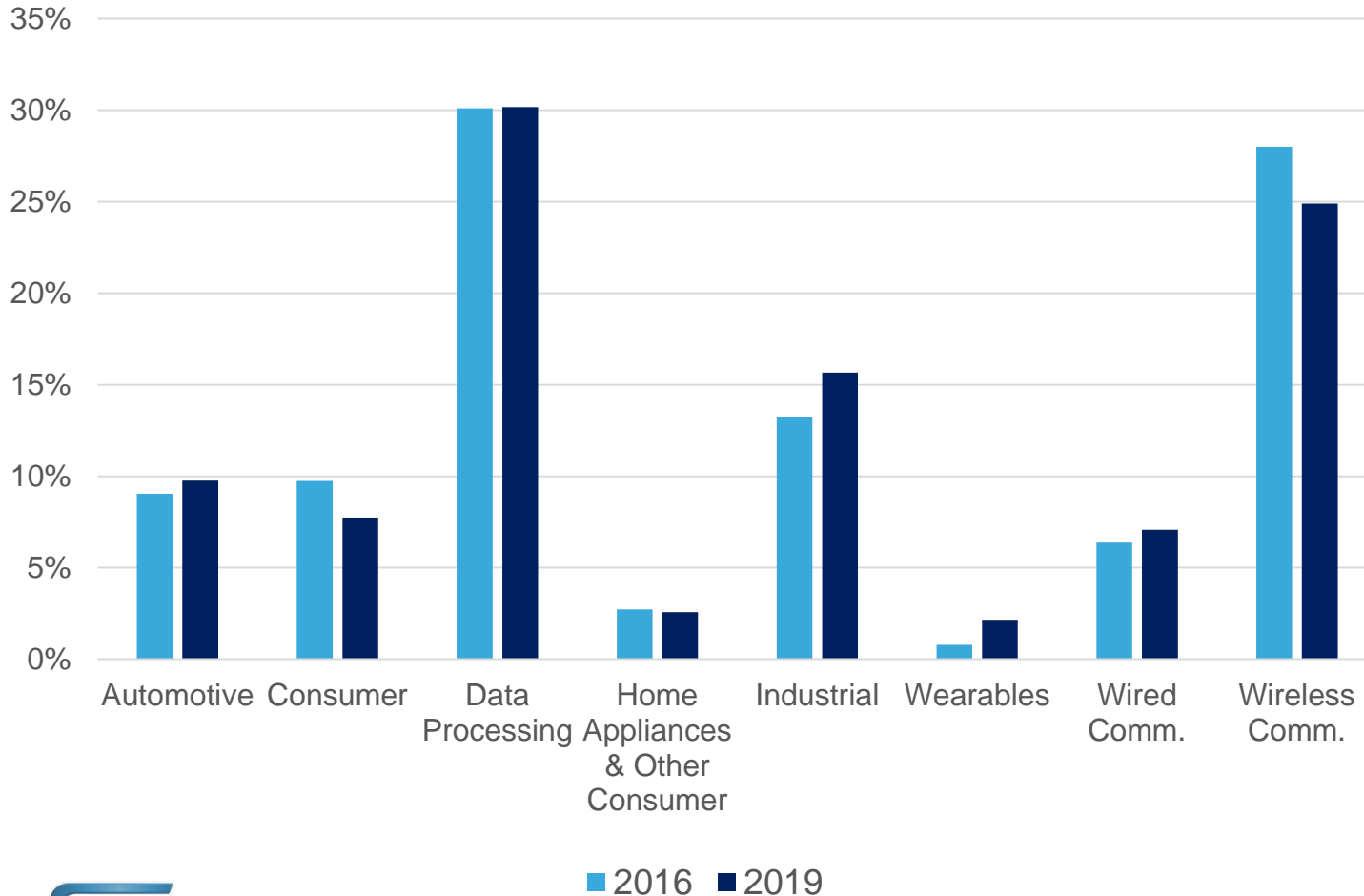
Smart Industry		Smart Home	
	Smart City		Smart Things

Addressing a Serviceable Available Market (SAM) of around \$150B

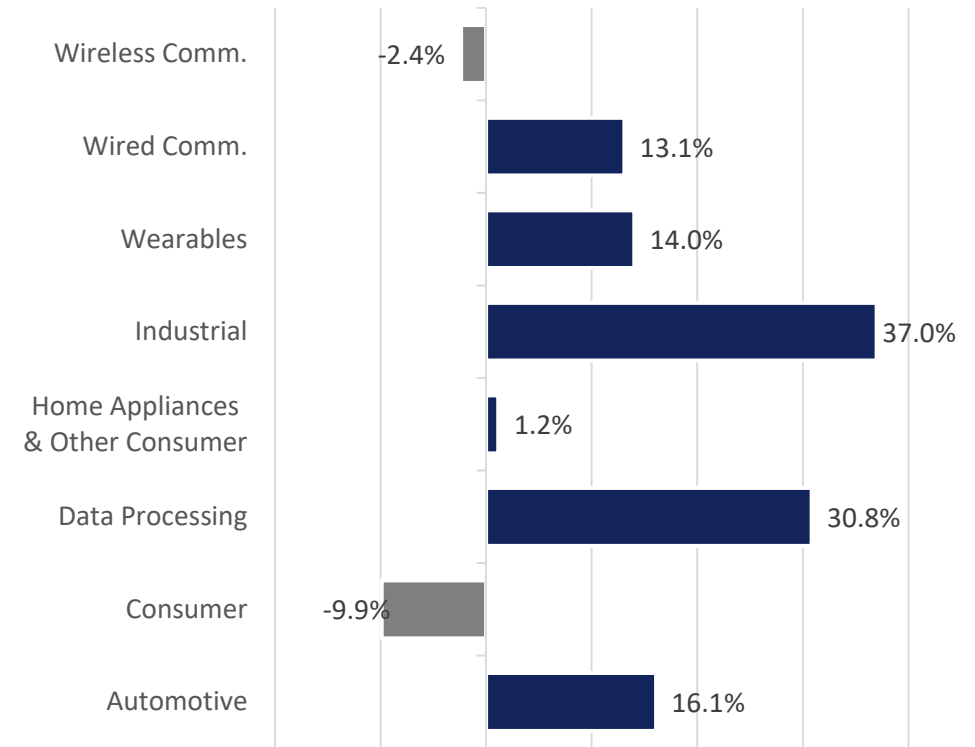


# TAM Evolution by Application

% of TAM

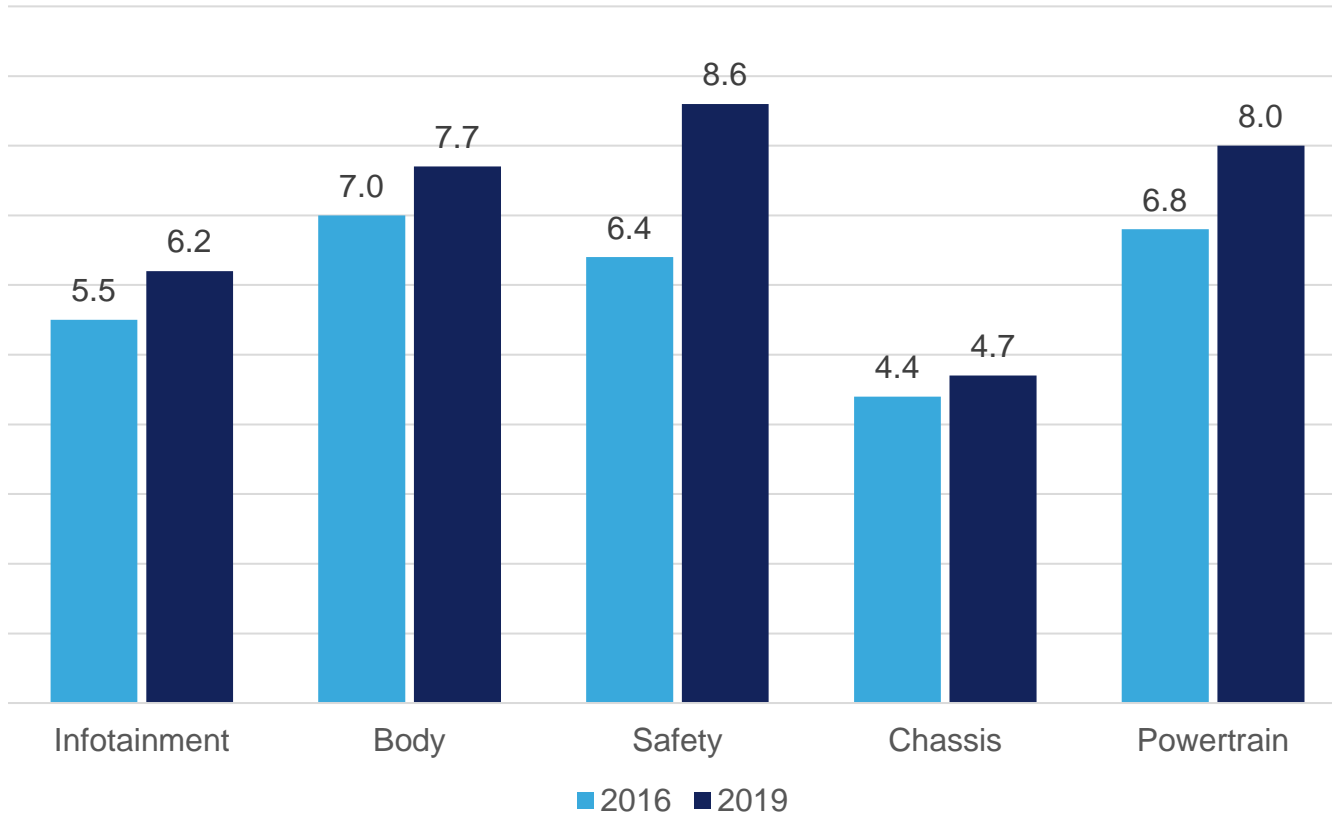


Contribution to TAM Growth (2016-2019)





ST SAM \$B

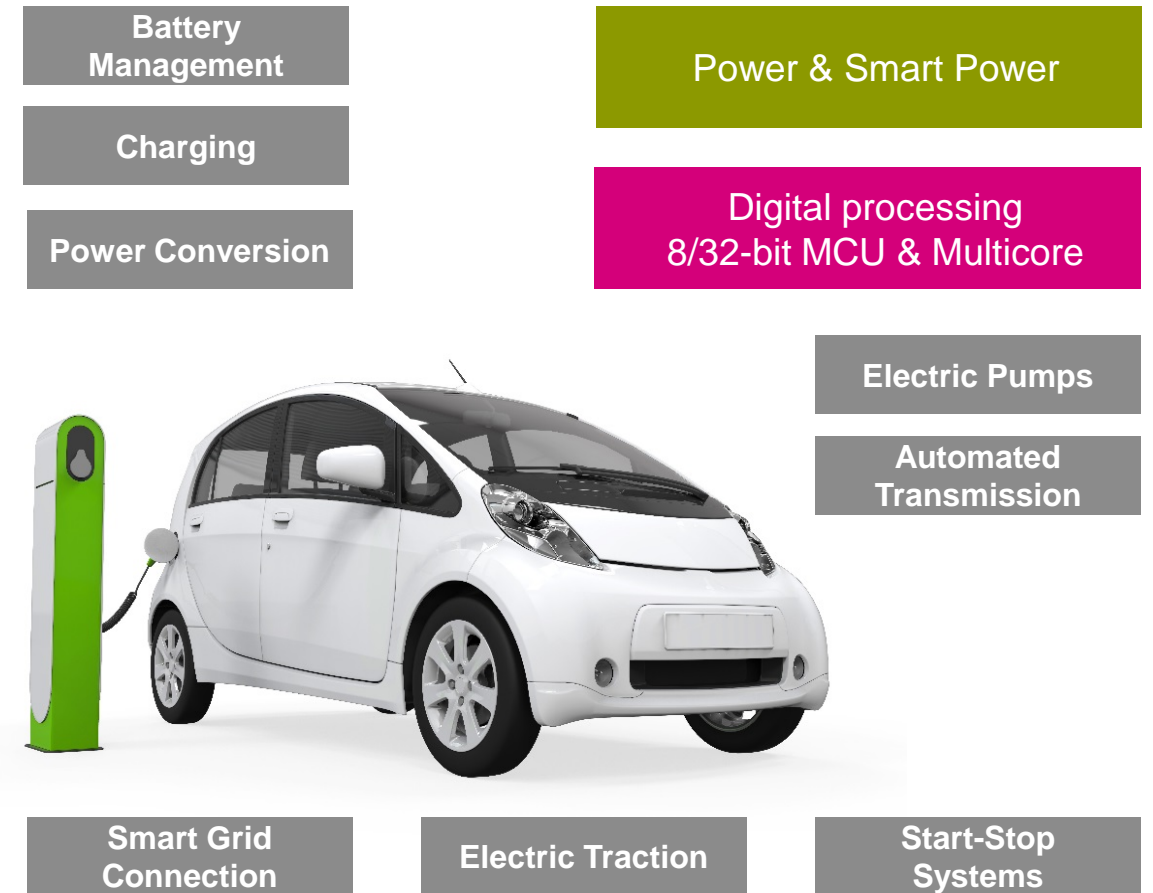
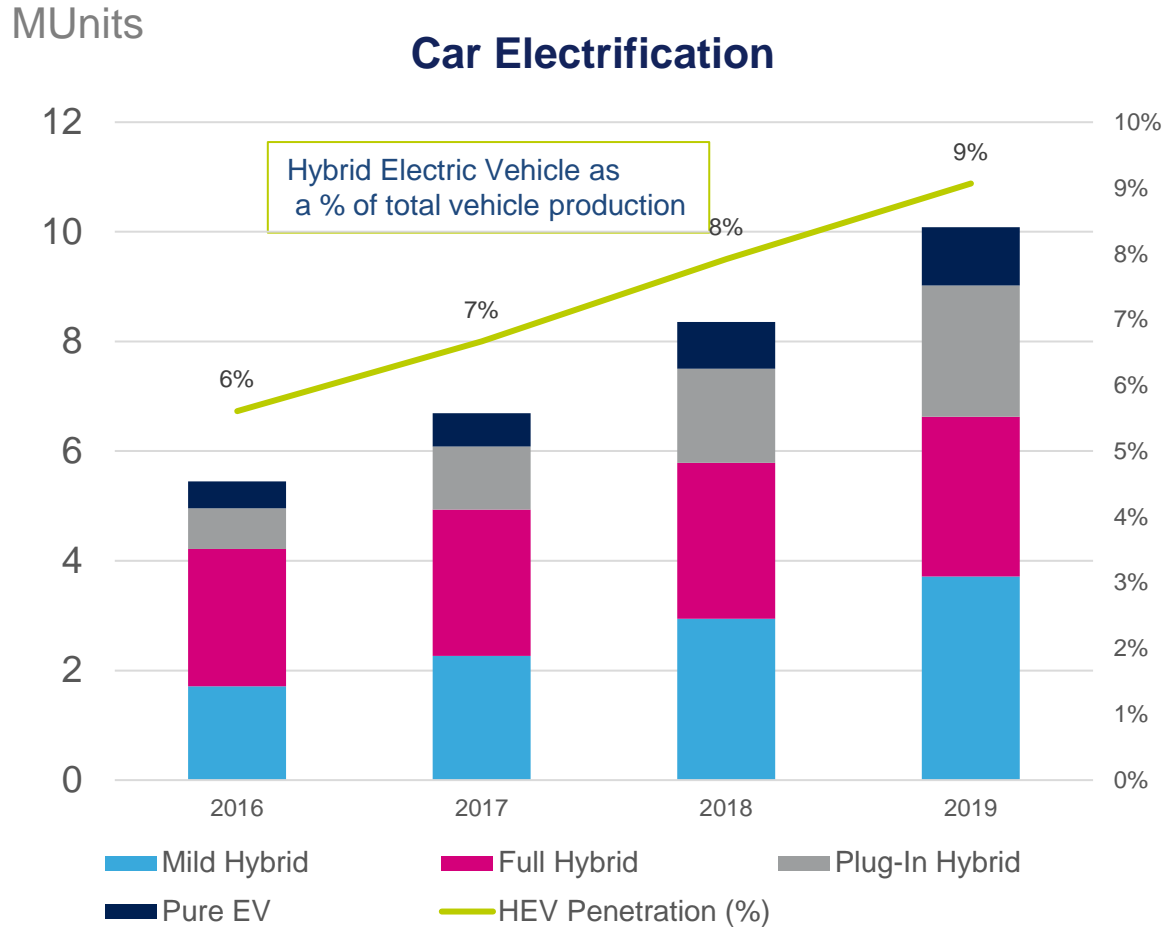


## Key Applications

- Active Safety
- Passive Safety
- Electric & Hybrid vehicle Electrification
- Infotainment
- Telematics
- Powertrain
- Direct Injection Engine
- Automatic Gearbox
- Braking
- Steering

# Smart Driving Application Focus

## Electric & Hybrid vehicle Electrification

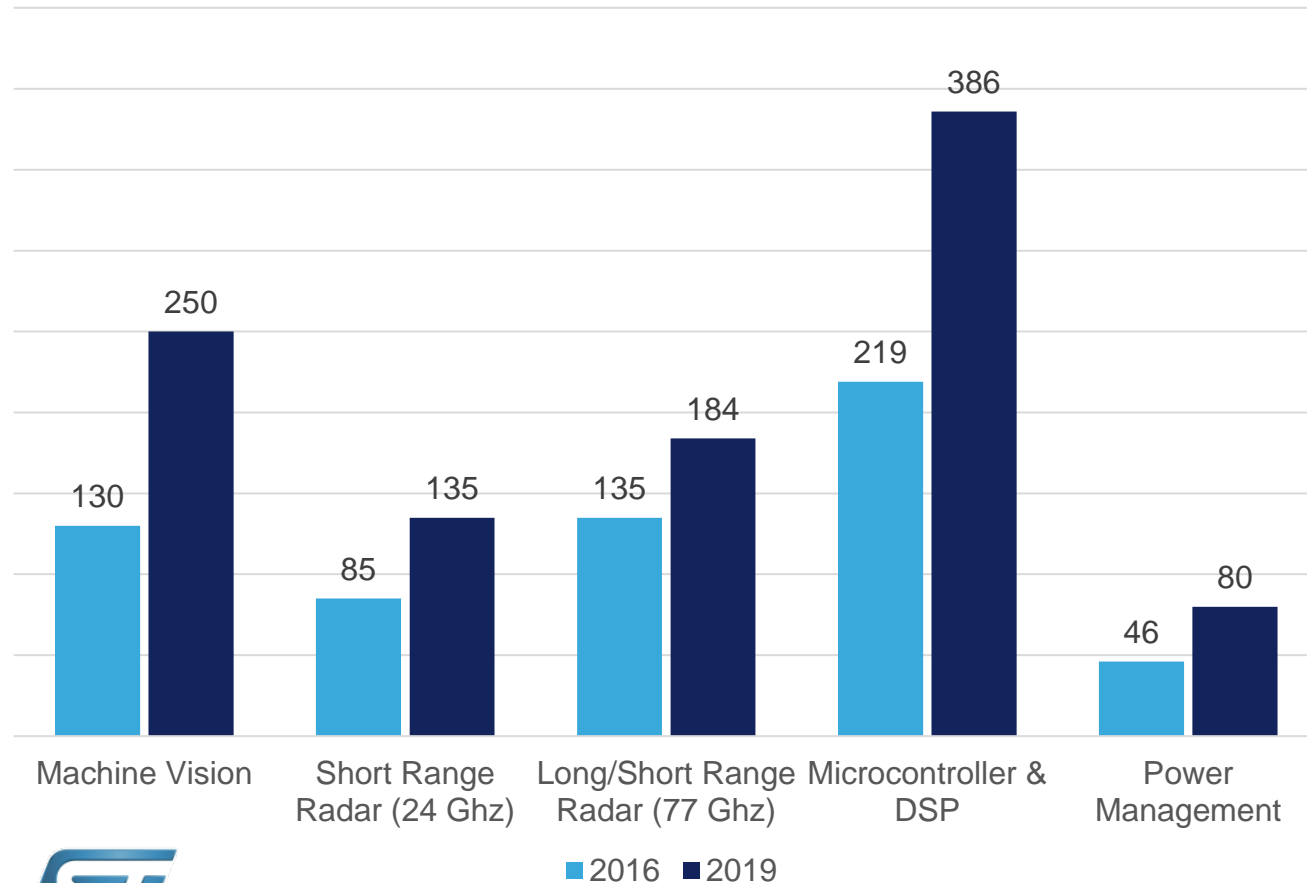




# Smart Driving Application Focus

## ADAS

ST SAM \$M



Applications: Forward collision warning, lane departure warning, pedestrian detection, adaptive cruise control, blind-spot detection

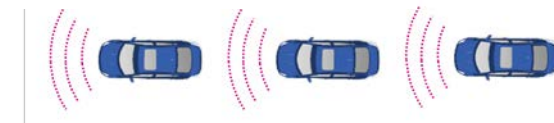
Sensors,  
Motion MEMS, Cameras

Power & Smart Power

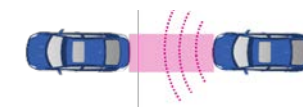
Machine Vision,  
ASSP/Radar

Digital processing  
8/32-bit MCU & Multicore

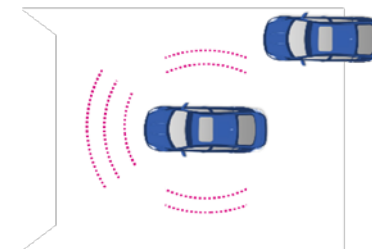
Adaptive Cruise Control



Collision Warning

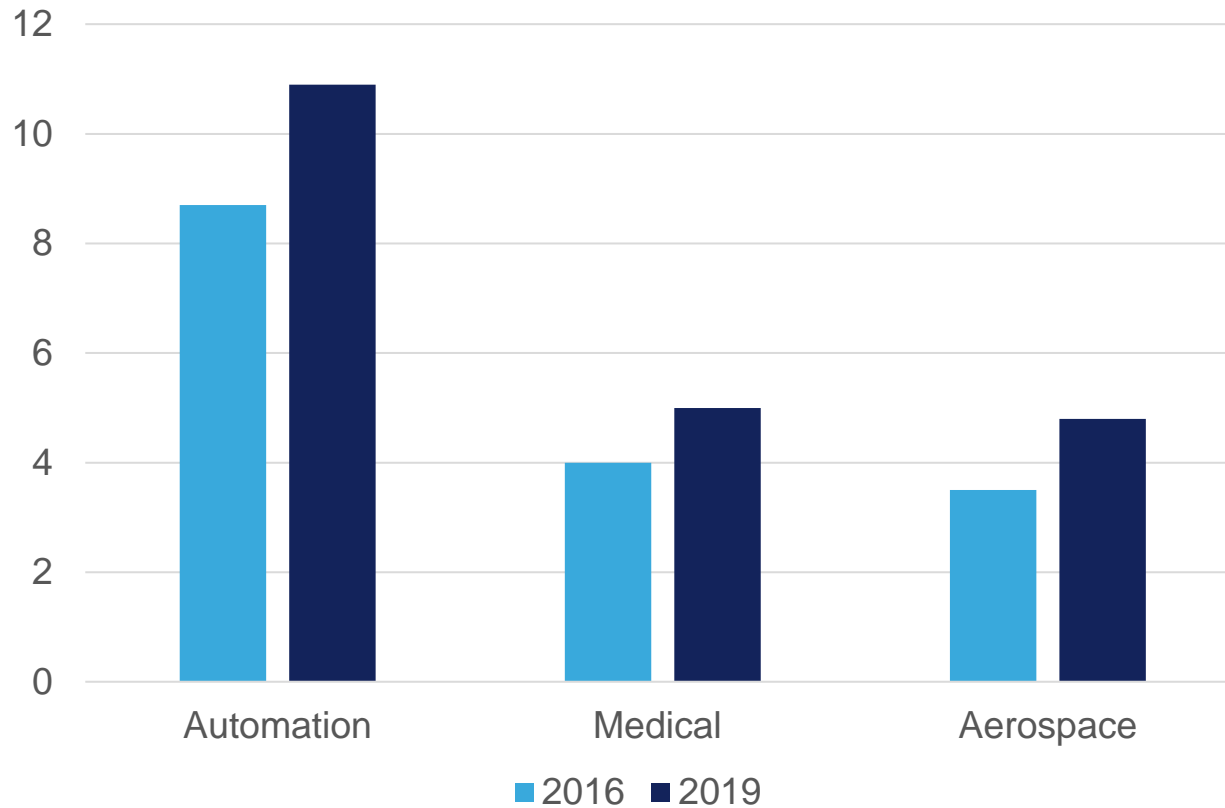


Blind Spot Detection



Source: Strategy Analytics, ST

ST SAM \$B



Source: IHS

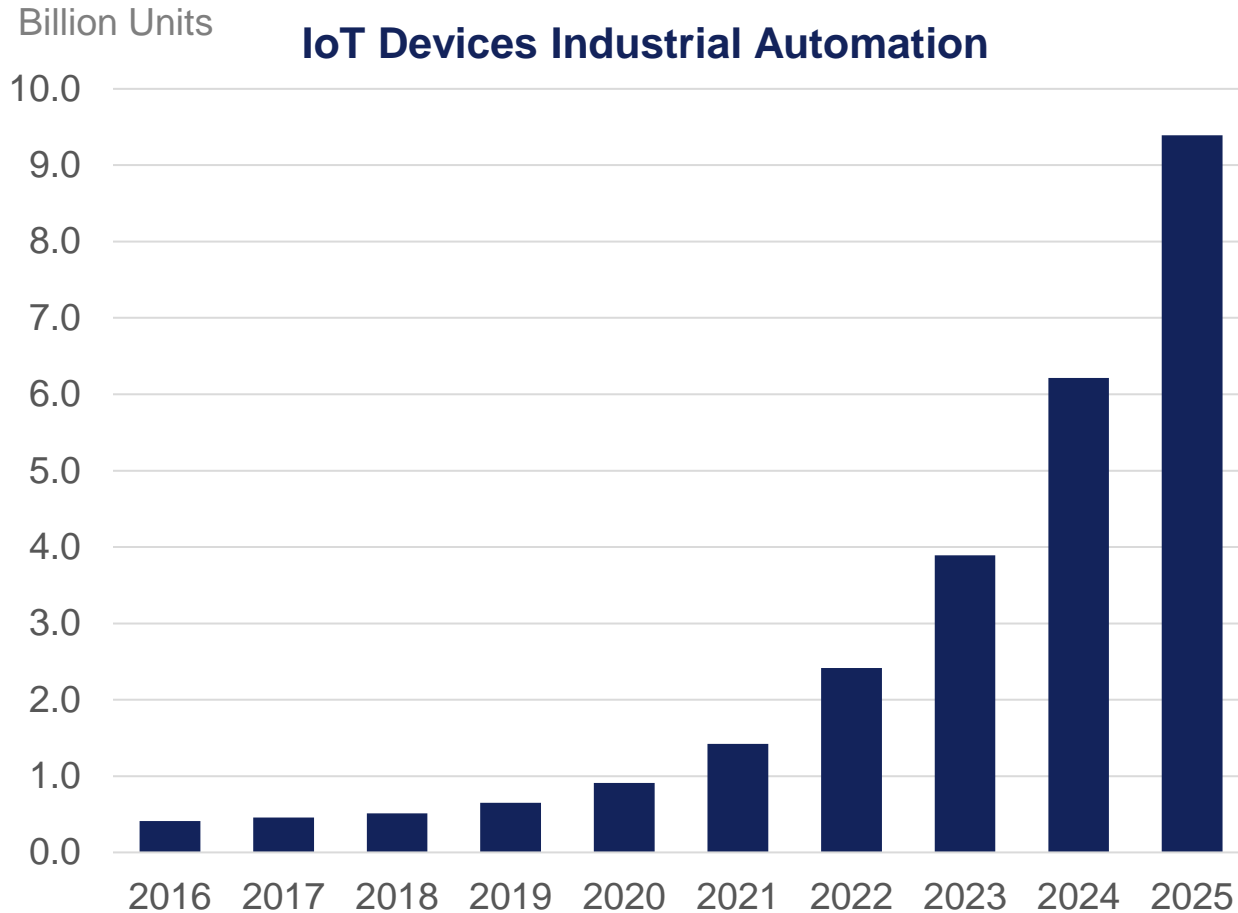


## Key Applications

- Smart Manufacturing
- Factory Automation
- Smart Motion Control
- Industrial Robots
- Industrial Lighting
- Sensors for Industrial, Medical, Aerospace & Defense

# Smart Industry Application Focus

## Factory Automation



### Smart Sensing

- Environmental sensors
- Motion sensors
- Acoustic MEMS
- Ranging sensors

### Processing

- STM32 32-Bit MCU
- Secure MCU

### Actuation & motor control

- Motor drivers
- Gate drivers
- Power switches

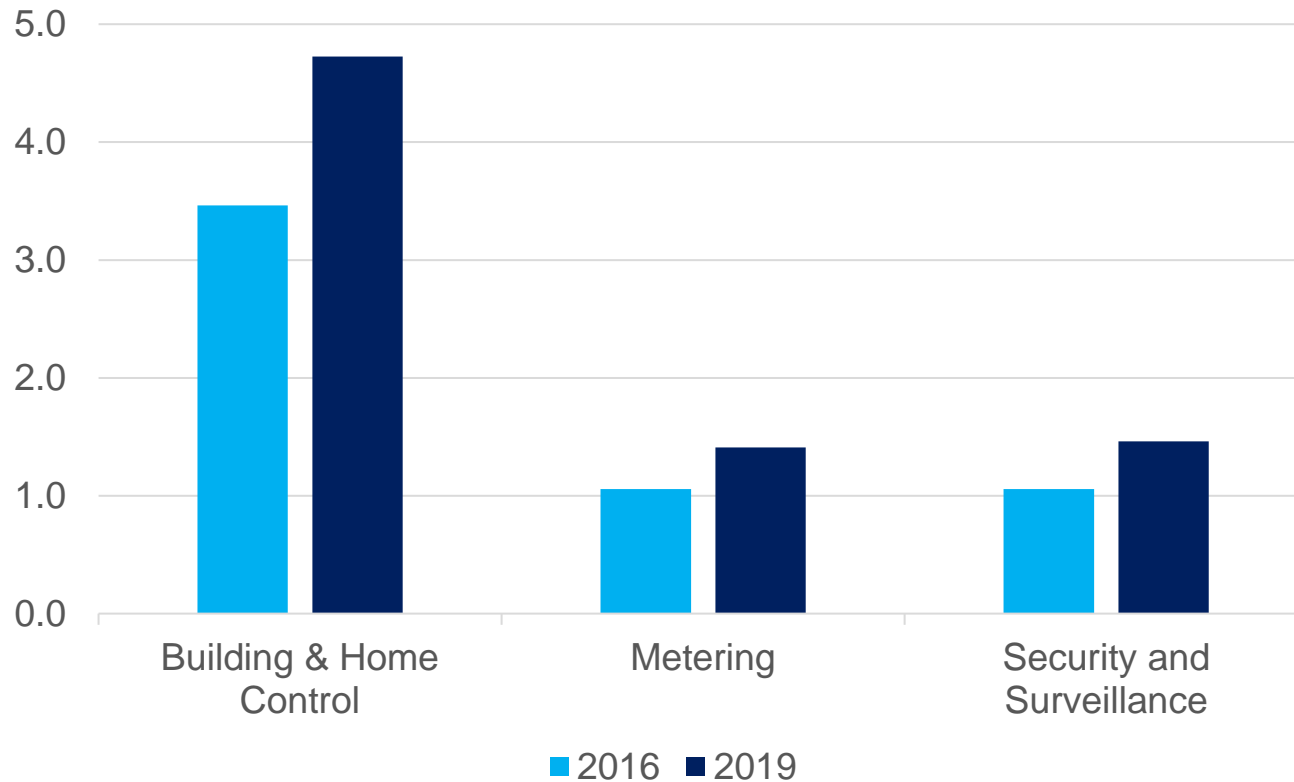
### Connectivity

- Power line modem
- Bluetooth modules
- Wi-Fi modules
- SubGHz connectivity (LPWA)
- I/O link
- NFC

### Power management

- AD/DC converters
- DC/DC regulators
- Analog & digital I/Os
- Protections

ST SAM \$B



## Key Applications

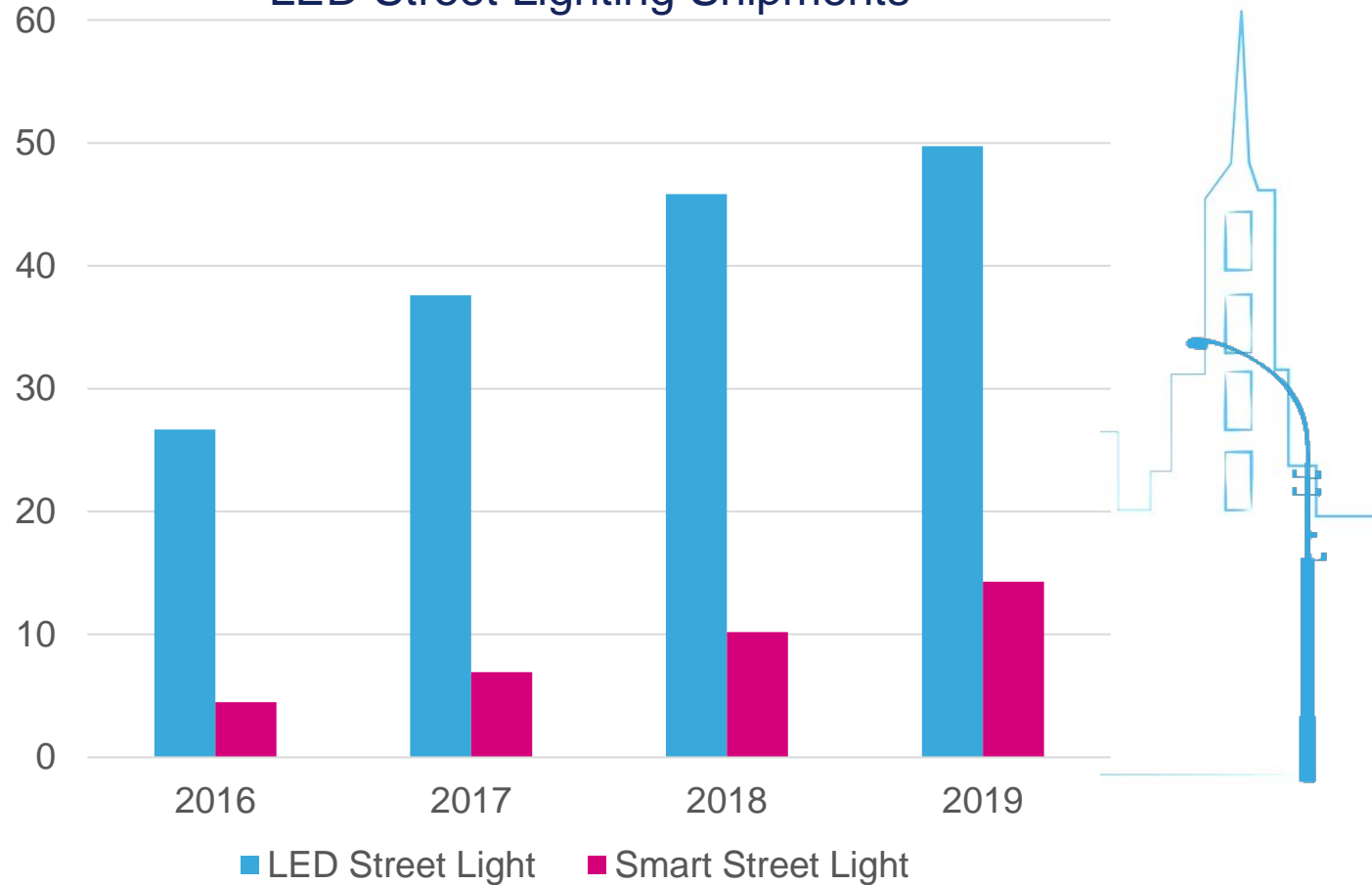
- Smart Transportation
- Home & Building automation
- Smart Metering
- Security & Surveillance
- Smart LED Lighting
- Heating & Energy Control

# Smart Home & City Application Focus

## Smart Street Lighting

MUnits

### LED Street Lighting Shipments



### Smart Sensing

- Environmental sensors
- Acoustic MEMS
- Ranging sensors

### Processing

- STM32 32-Bit MCU
- Secure MCU

### Connectivity

- Power line modem
- Wi-Fi modules
- SubGHz connectivity (LPWA)

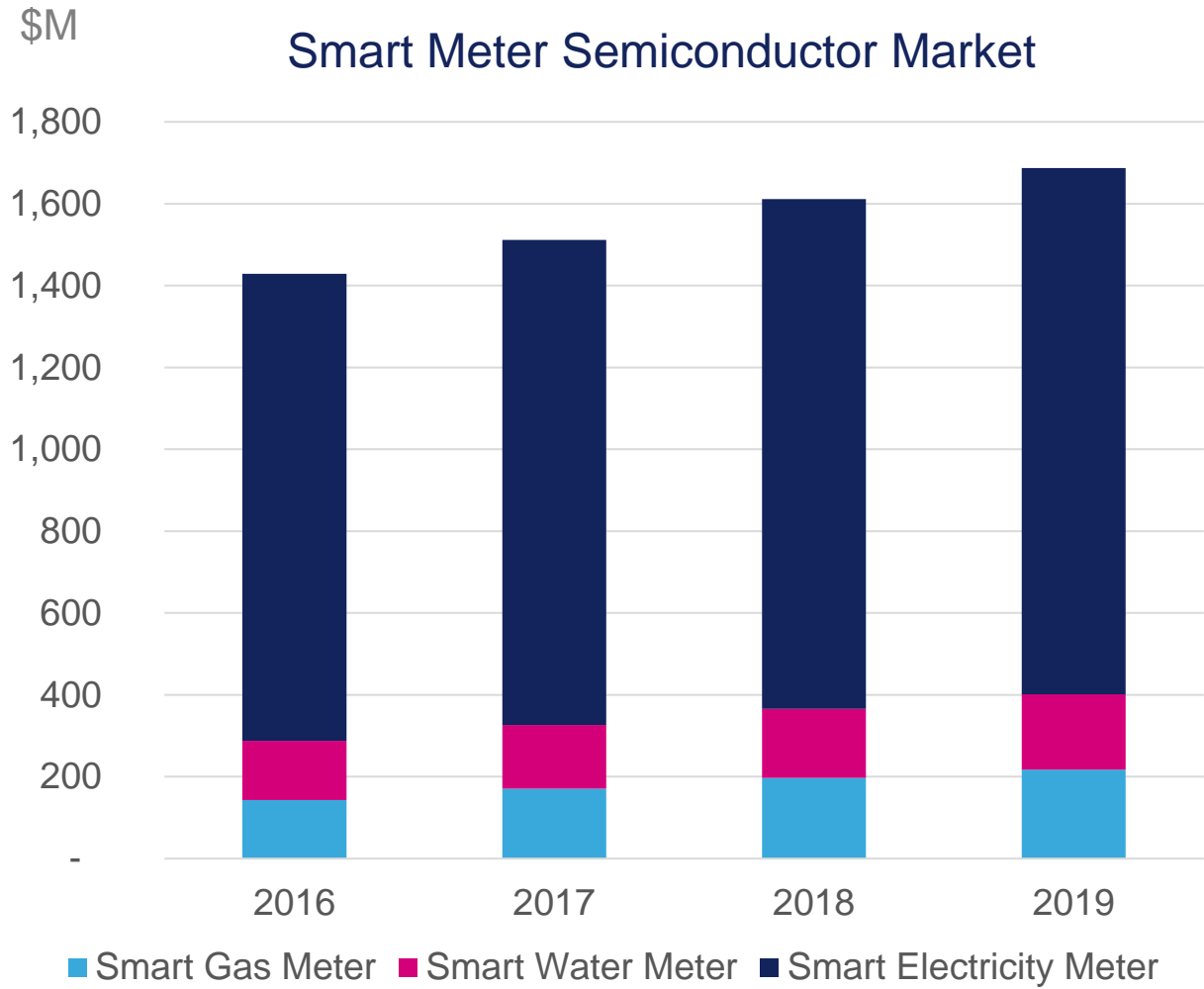
### Power management

- Power MOSFET
- MOSFET driver
- DC/DC LED driver
- Digital Controller
- Protections



# Smart Home & City Application Focus

## Smart Metering



### Metrology

- Metrology for single and polyphase meters

### Processing

- STM32 32-Bit MCU
- Secure MCU

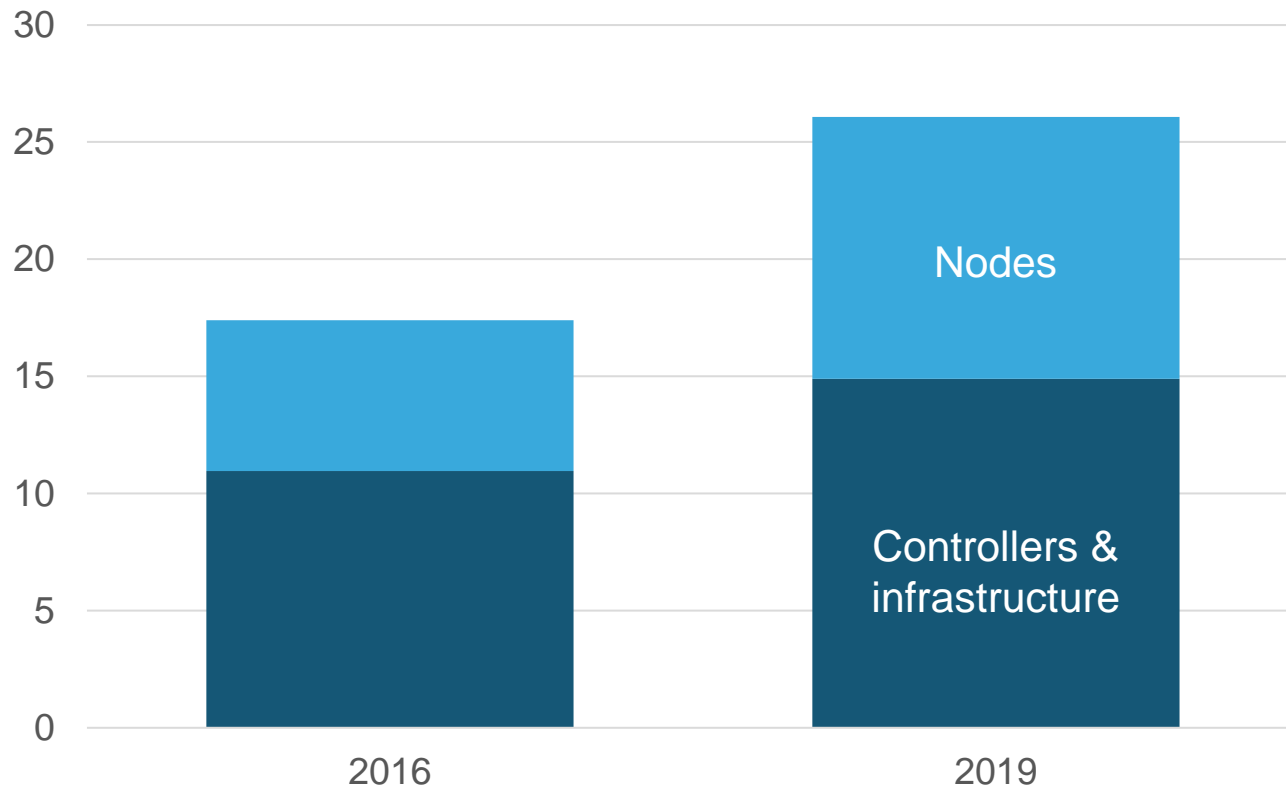
### Connectivity

- Power line modem
- SubGHz connectivity (LPWA)
- NFC and RFID

### Power management

- Integrated SMPS
- AD/DC converters
- DC/DC regulators
- Protections

Billion units installed base

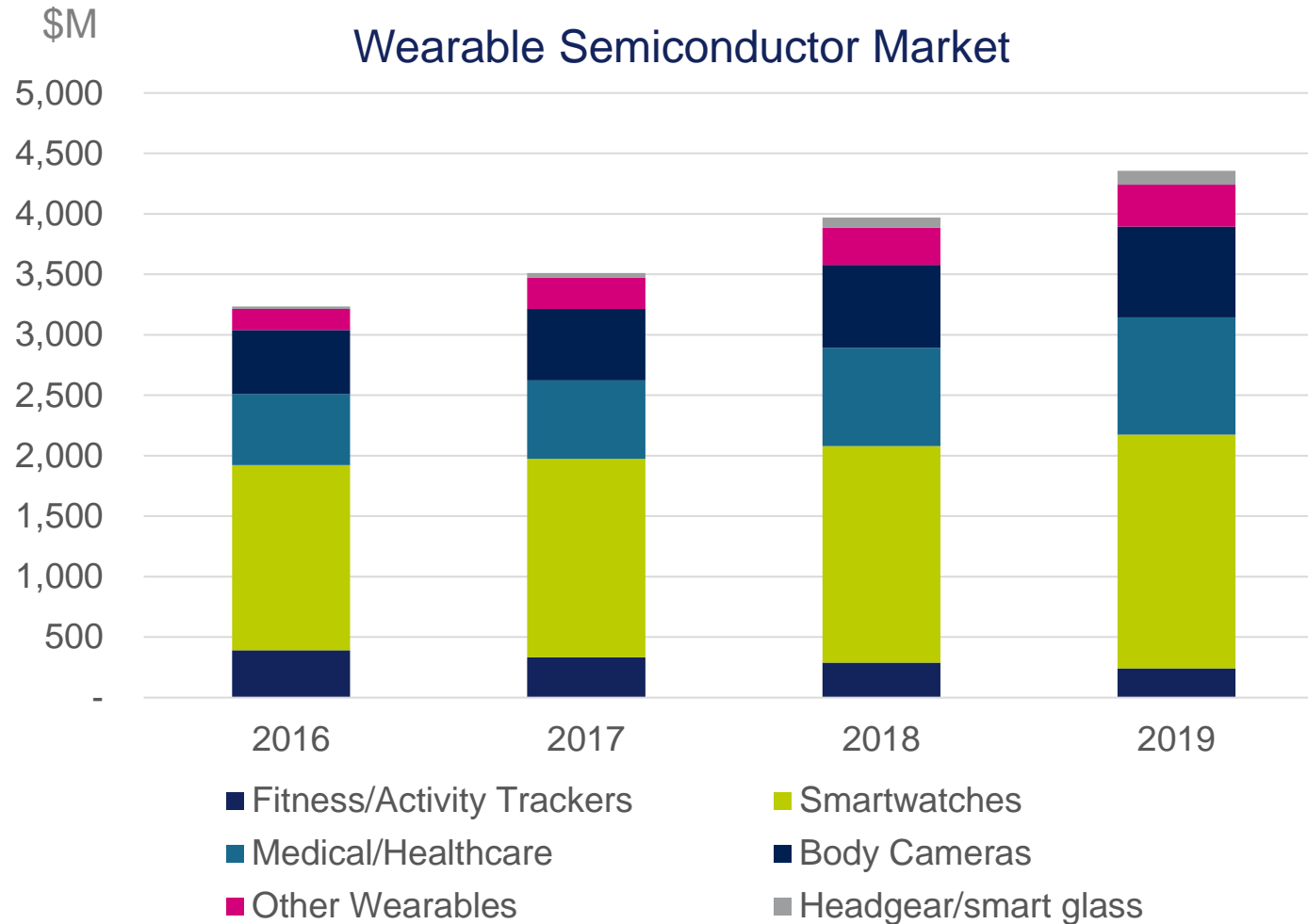


## Key Applications

- Smartphones
- Tablets
- Wearable
- Smart Things

# Smart Things Application Focus

## Wearables



**Smart Sensing**

- Motion sensors
- Environmental sensors
- Acoustic MEMS
- Ranging sensors
- Micro-actuators
- Touch sensors

**Processing**

- STM32 32-Bit
- Secure MCU

**Connectivity**

- Bluetooth Low Energy
- Wi-Fi modules
- NFC

**Power management**

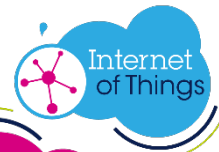
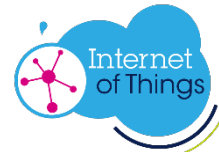
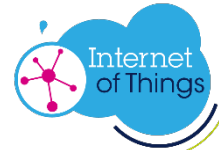
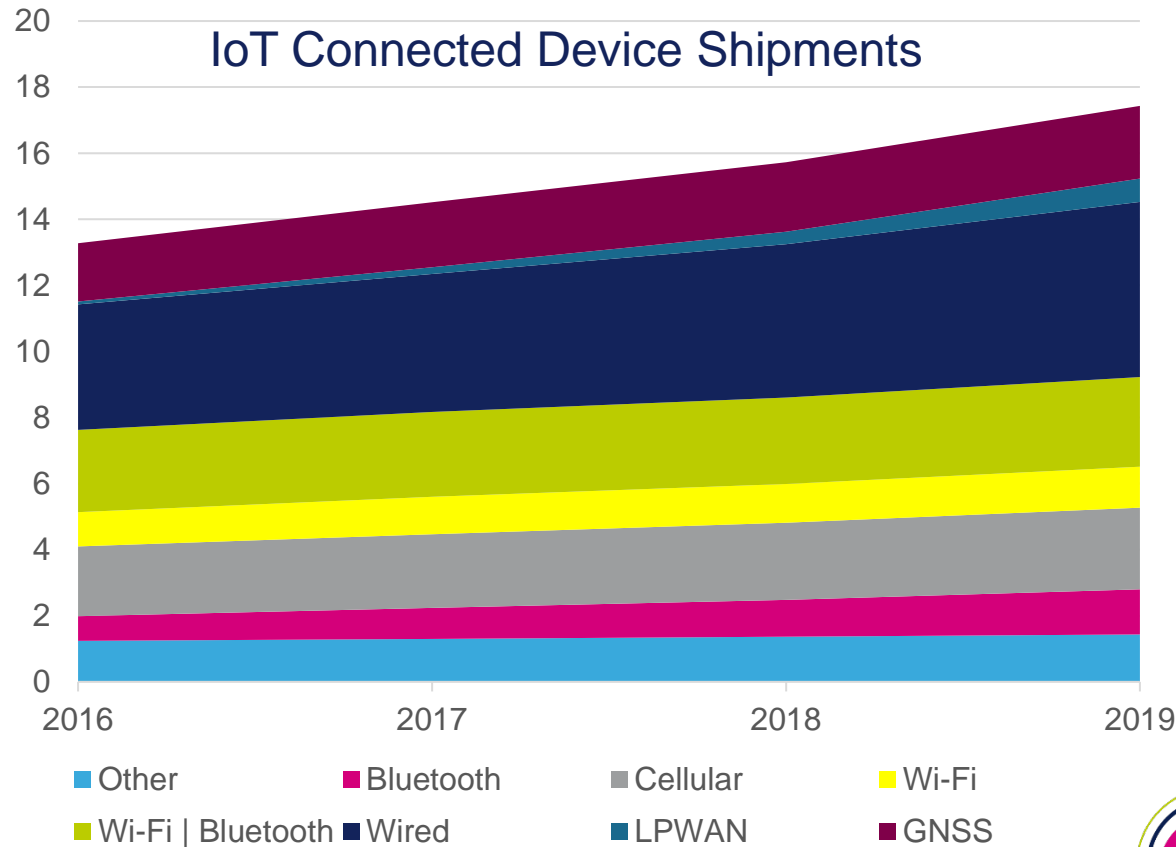
- Energy Harvesting ICs
- OLED power management
- Thin-film battery
- Power management ICs
- Protections



# Connectivity Needed Everywhere

Billion Units

IoT Connected Device Shipments



## Bluetooth & Wi-Fi

### Bluetooth Low Energy

- BlueNRG - Highly energy-efficient network processor

### Car Wi-Fi

- Partnership with Autotalks for V2X solutions

### High data rate low-power RF

- Partnership for solutions targeting disposable devices

## SubGHz

- **SPIRIT** - Very low power RF transceivers for SubGHz
- **LPWAN (Low Power Wide Area Networks) Partnerships**
  - **LoRa** – Partnership with STM32
  - **SigFox** – Partnering for SPIRIT2



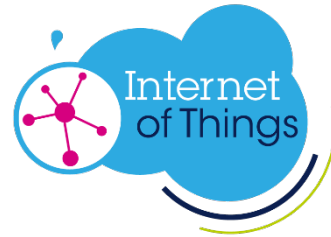
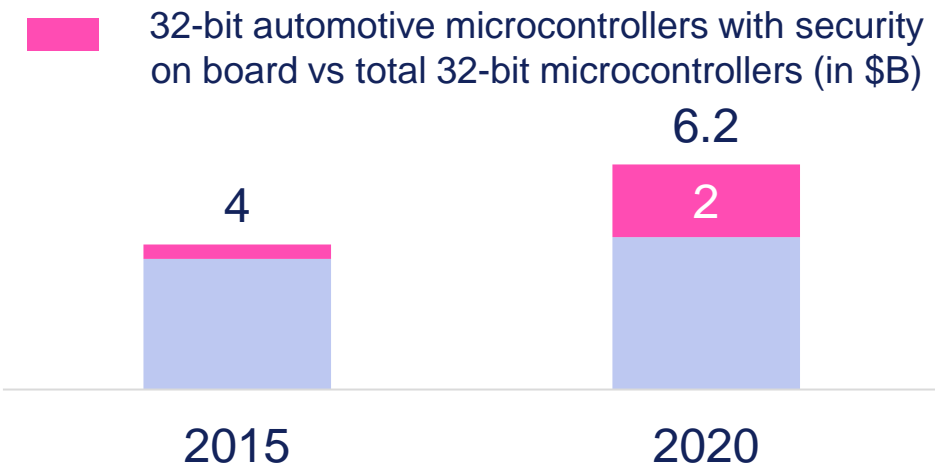
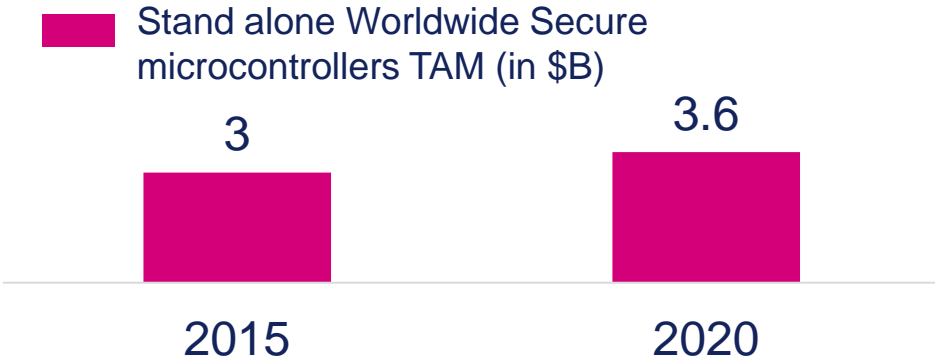
## GNSS

- TESEO – Multi-constellation GNSS solutions

## Power Line Communications

- STARGRID & STCOMET - Solutions covering all the major power line communications protocols

# Security Needed Everywhere



## Secure MCU

### ST54 for Secure Mobile Transactions

- Mobile devices & wearable
- Secure payment, transport, access control & biometry

### STSAFE for Authentication & IP protection

- Brand protection, TPM, metering, accessories, LPWAN, Secure IoT

### ST33 & ST33TPM for Automotive

- Secure communications among peripherals
- Secure firmware upgrade, secure boot
- Secure cellular connections

## Secure Automotive Solutions

### Automotive MCU

- SPC5 MCU with Crypto

### Car Connectivity

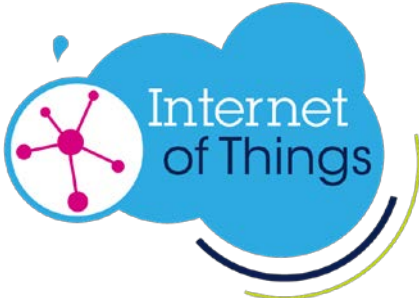
- Wi-Fi Secured for Car-2-X

# Application Strategic Focus

The leading provider of products and solutions for Smart Driving and the Internet of Things



Safer		More connected
	Greener	



Smart Industry		Smart Home	
	Smart City		Smart Things

Addressing a Serviceable Available Market (SAM) of around \$150B

# Internet of Things A Key Driver of Growth

## **Bob Krysiak**

EVP, President, Region Americas, Global Mass Market & Online Marketing Programs

## **Claude Dardanne**

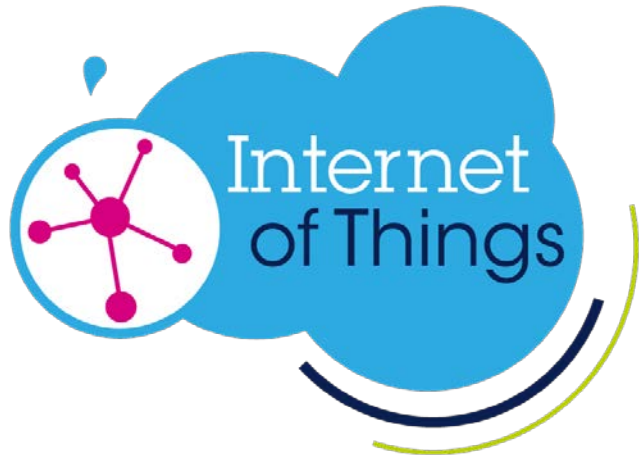
EVP, General Manager, Microcontroller and Digital ICs Group

## **Benedetto Vigna**

EVP, General Manager, Analog and MEMS Group



The leading provider of products and solutions for the Internet of Things



Smart Industry



Smart City



Smart Home



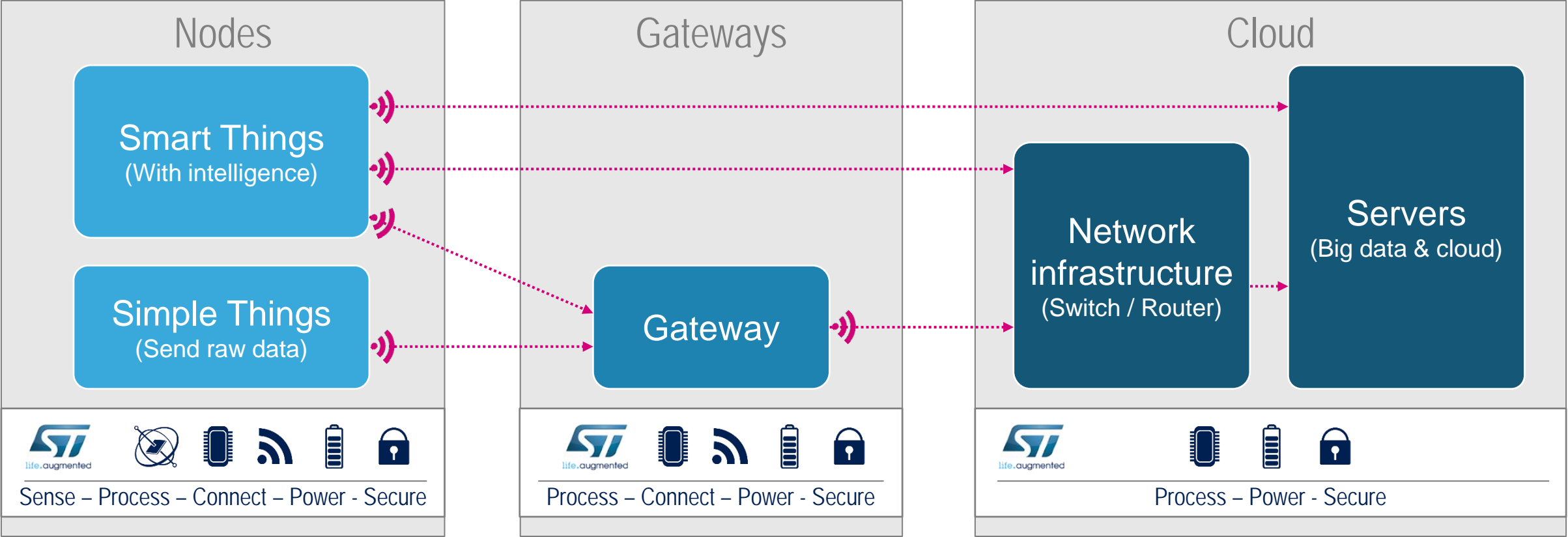
Smart Things



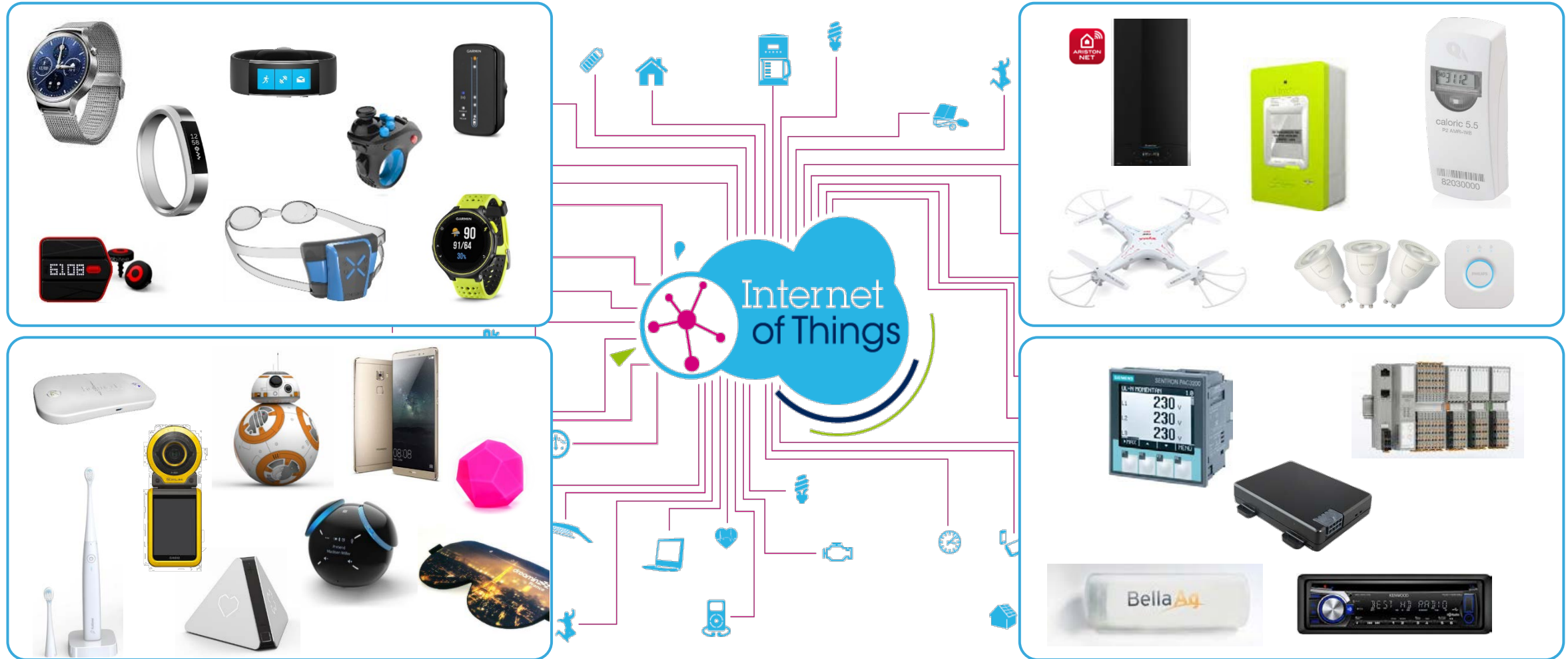


IoT is a movement where any system is able to leverage the Internet and its eco-system

Cloud computing – Low cost embedded computers – Explosion of reliable wireless connectivity – Rapid innovation of low cost sensors



# IoT Devices Come in Many Form Factors



# ...but Their Needs are the Same

## Processing & Security

## Sensing & Actuating

## Connectivity

## Signal Conditioning & Protection

## Power & Energy Management



Smart Things




Smart Home




Smart City




Smart Industry




Ultra-Low Power to High Performance




Scalable Security solutions





Full range of sensors and actuators





10 cm to 10 km

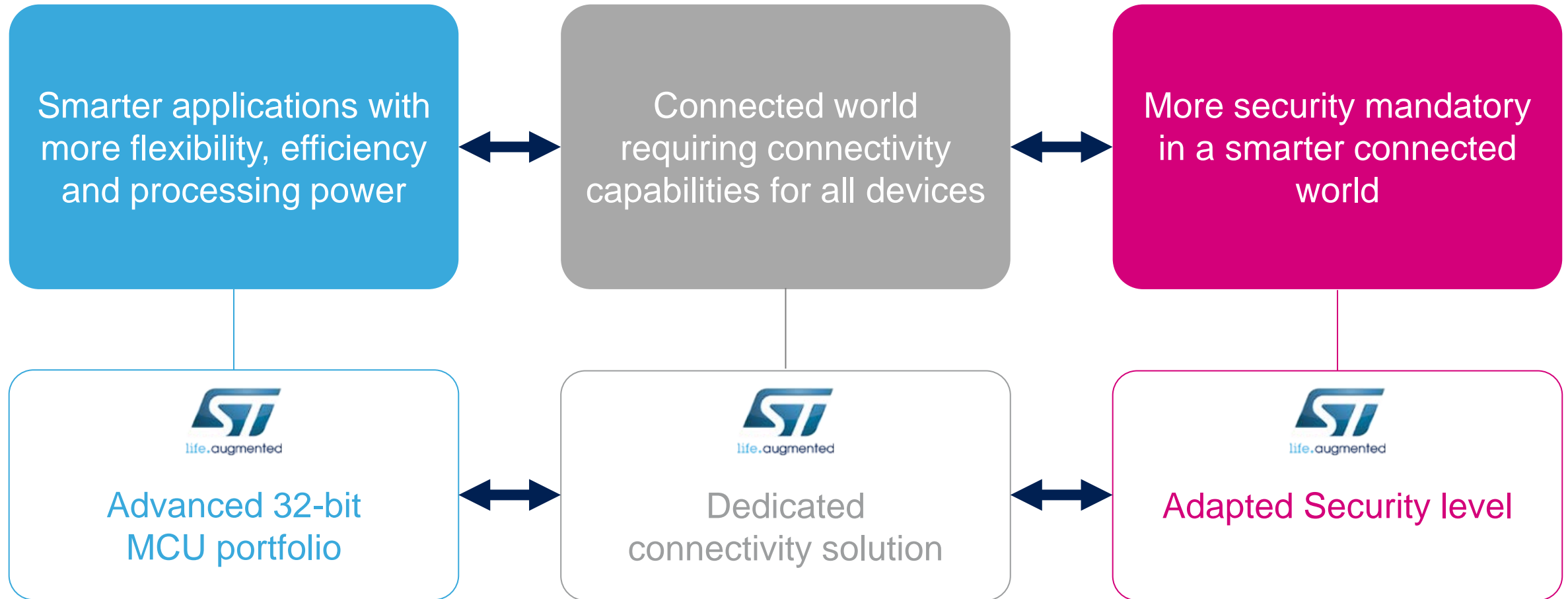
Nano Amps to Kilo Amps

Nano Watt to Mega Watt

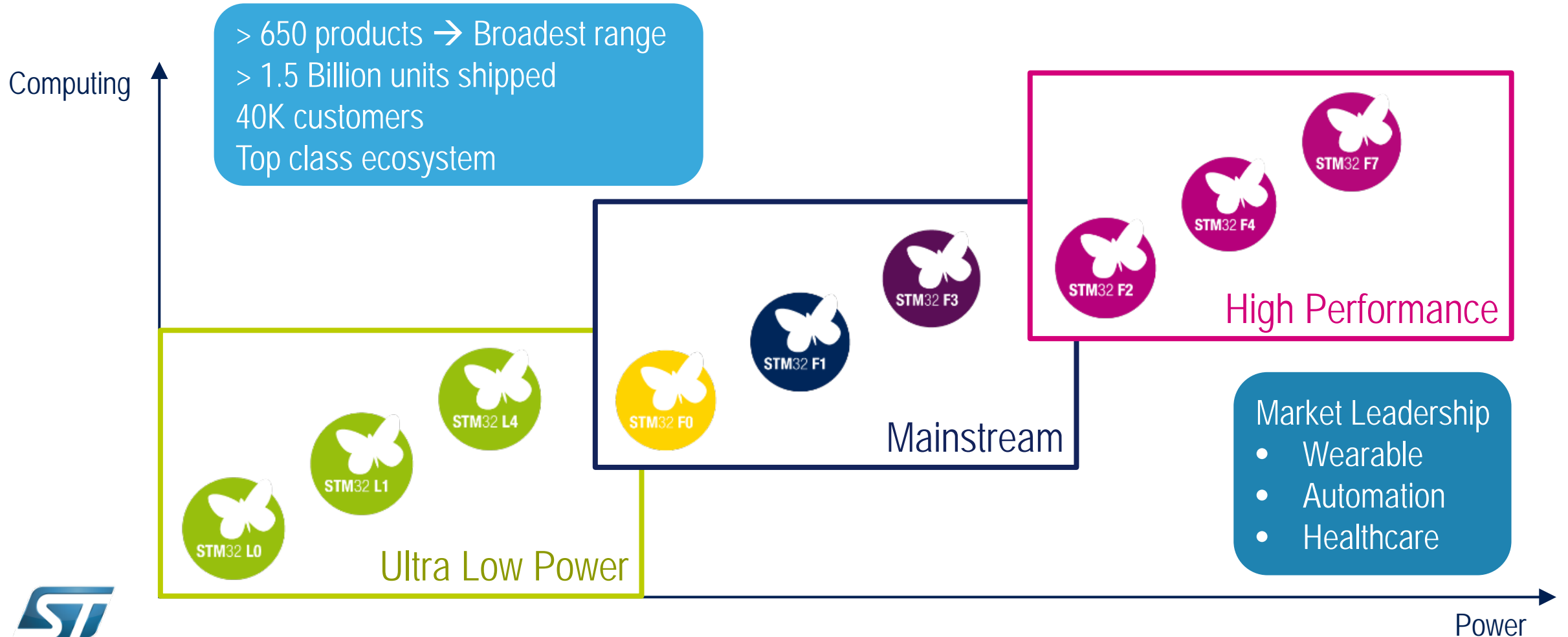


# Microcontrollers Enabling IoT



## Advanced 32-bit MCU portfolio

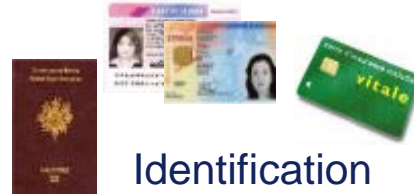
#1 WW 32-bit Microcontrollers supplier (excluding Automotive)



# Adapted Security Level



Payment



Identification

Smart Grid, Industrial gateways

Healthcare



Smart meter

Appliances  
Smart home



Wearables



ST33/31 MCU

STM32 eSE

STM32 MCU

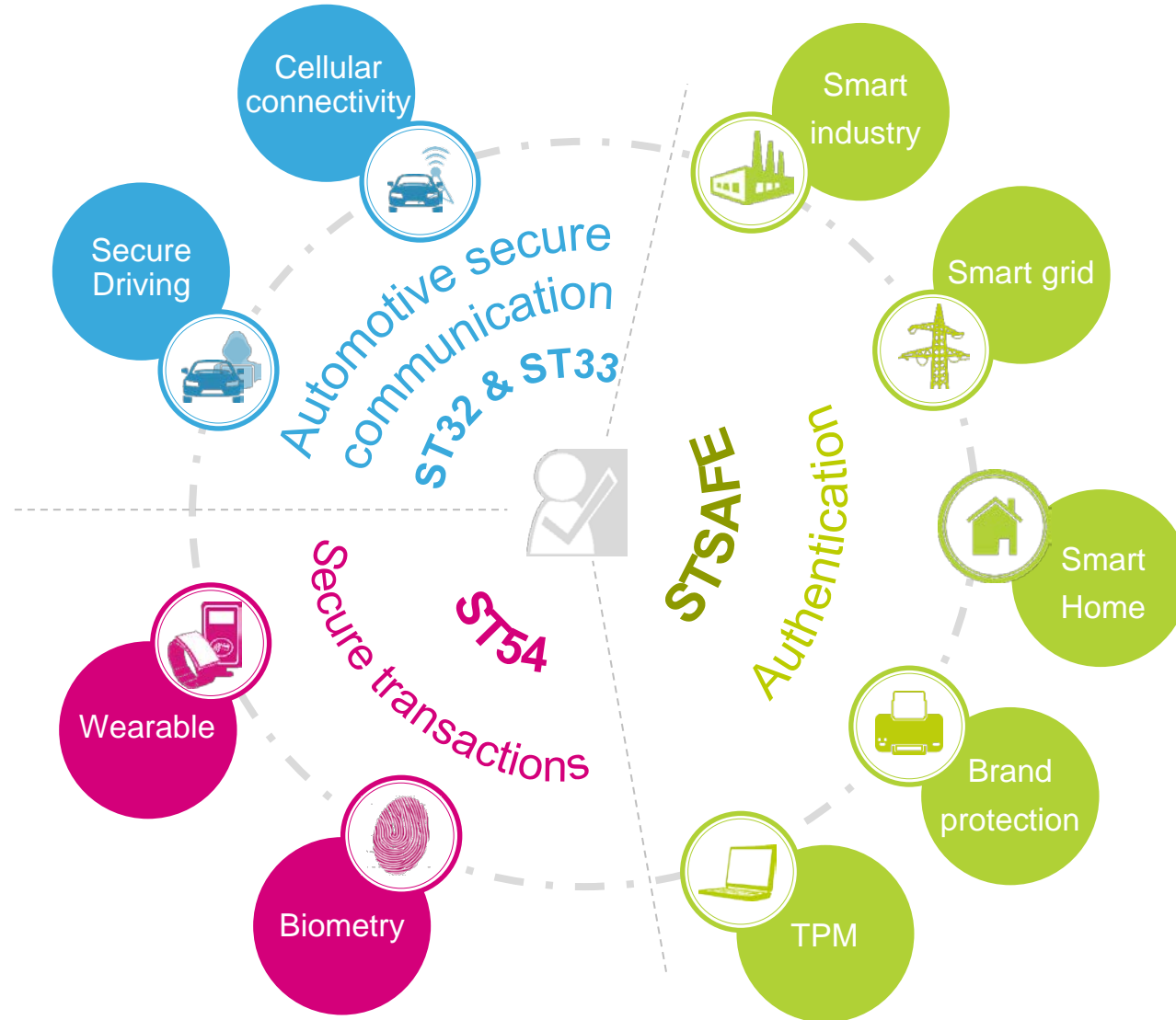
STSAFE

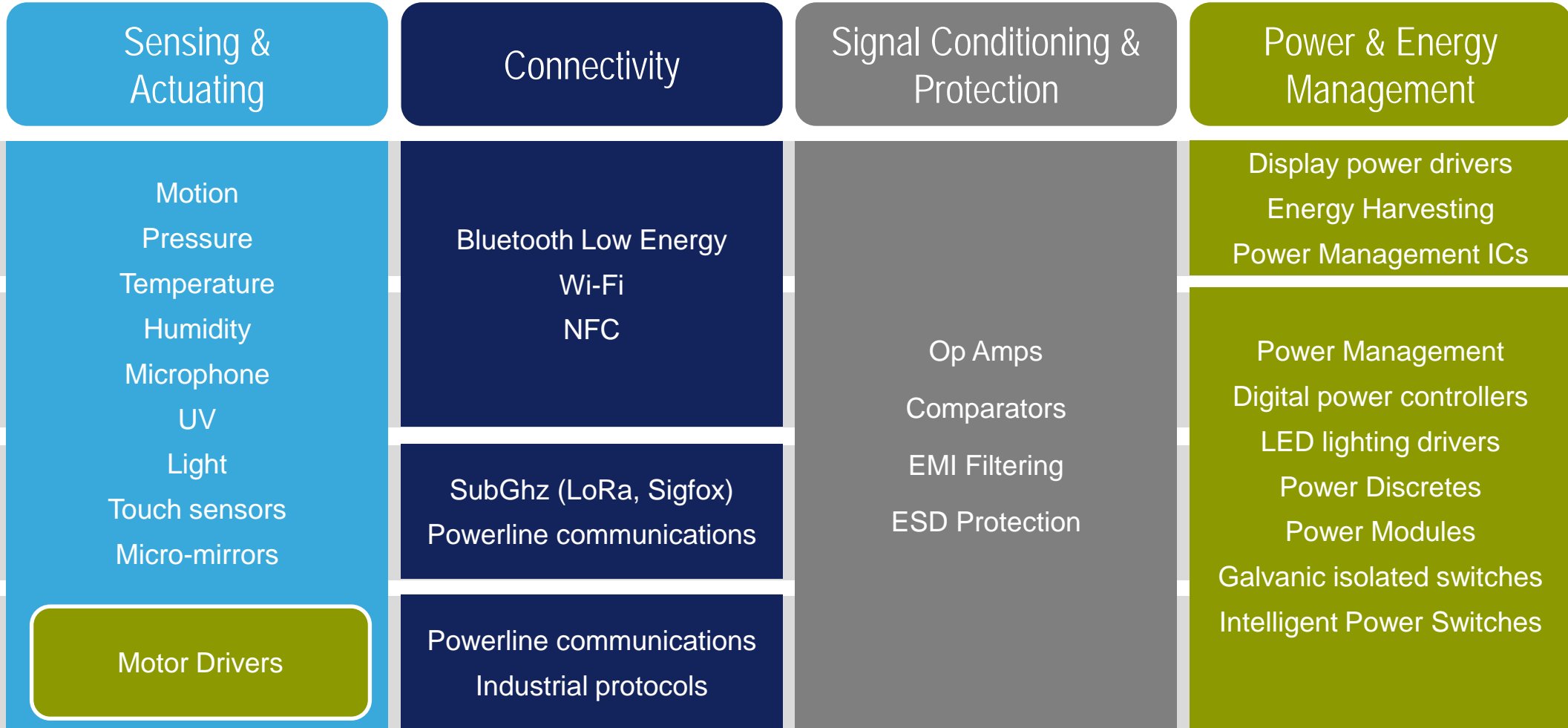
STM32 MCU

STM32 MCU



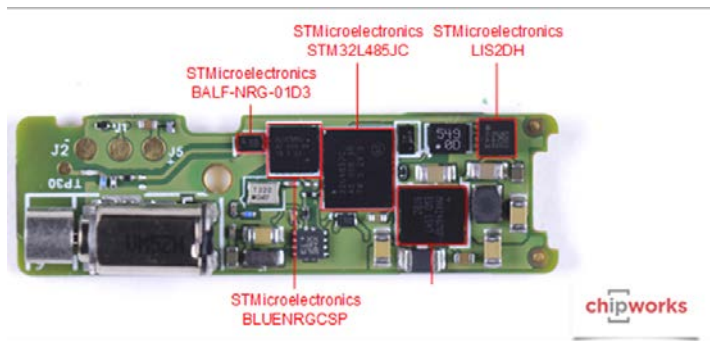
# Secure Solutions for IoT







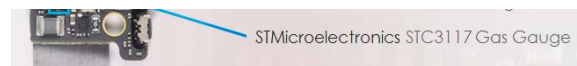
Fitbit alta



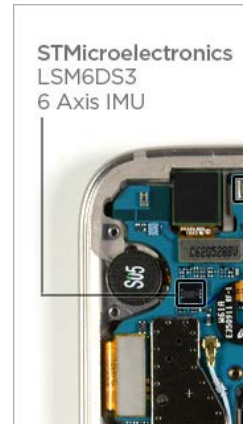
Microsoft Band II



Device Type	Manufacturer	Part
Gyroscope and Accelerometer	STMicroelectronics	LSM6DS2
Barometer	STMicroelectronics	LPS25HB
UV Sensor	STMicroelectronics	No PKG marks



Samsung Galaxy S7



gyroscope (STMicroelectronics) L2G2IS





Smart Water heater

Wireless Connectivity Module



Heat cost allocator

Wireless Connectivity Module

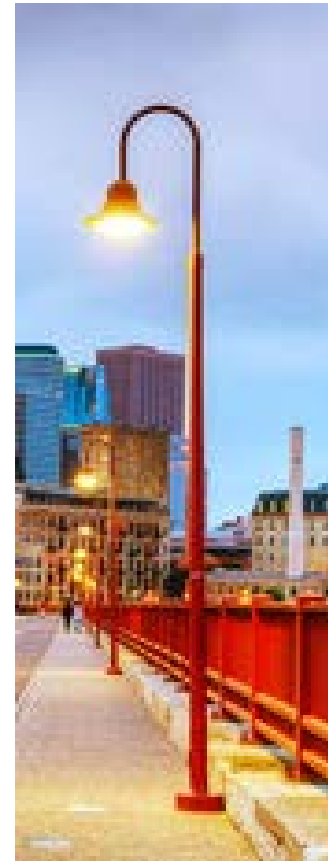


End-to-end Smart Grid program in France



Large-scale Smart meter program in Italy

- STM32 Microcontroller
- STarGRID Power Line Controller
- STCOMET Smart Metering SoC
- Energy Metering IC



Over 100.000 Smart Street light installed in cities in Italy



Innovation smart city infrastructure around the globe

- STM32 Microcontroller
- STarGRID Power Line Controller
- SubGHz RF
- Energy Metering IC

## SIEMENS

### Reliable and precise monitoring of electrical power systems

The SENTRON PAC3200 is a powerful compact power monitoring device that is suitable for use in industrial, government and commercial applications where basic metering and energy monitoring is required. The meter may be used as a stand alone device monitoring over 50 parameters or as part of an industrial control, building automation or global power monitoring system.

Metering and monitoring applications range from simple analog volt and amp meter replacements to stand-alone sub billing or cost allocation installations with multiple

tariffs. The SENTRON PAC3200 can also be used to support LEED certification and provide the needed energy metering data for federal/ local government energy reduction programs.

The SENTRON PAC3200 provides open communications using Modbus RTU/TCP and PROFIBUS-DP protocols for easy integration into any local or remote monitoring system. Simple configuration of the meter can be done from the front display or by using a PC with SENTRON powerconfig setup software, supplied with the meter.



Factory Automation  
Motion Control  
Smart Industrial Meter  
Industrial Power Supply

Microcontrollers  
EEPROM  
NFC EEPROM

Wide Band Power line modem

Voltage / Switching regulator  
Op Amp  
Power MOSFETs  
Power Diodes  
Protection



- Fast
- Robust
- Easy



Realtime I/O

Programmable Logic  
Controller

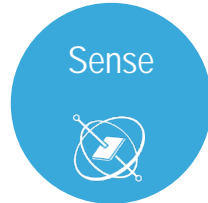
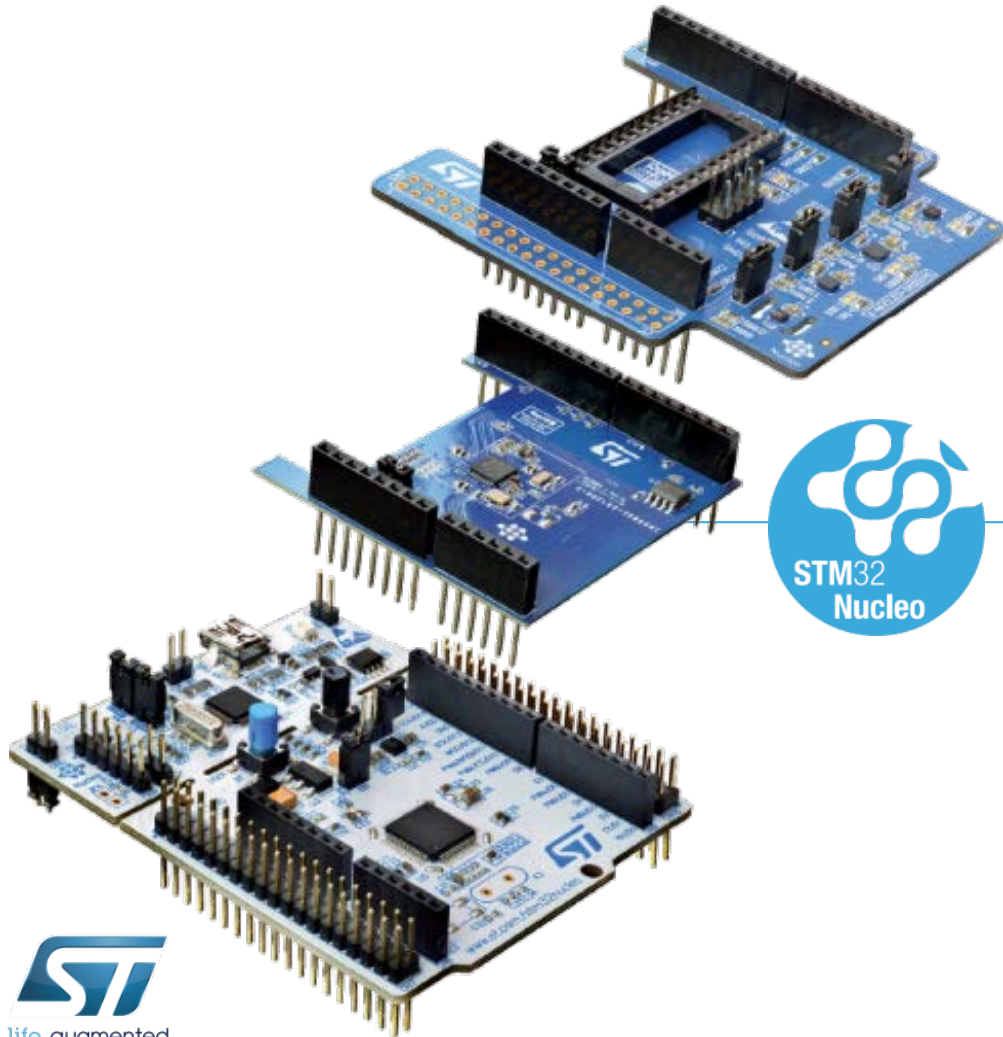
Communications Controller ASIC

Intelligent Power Switches  
Galvanic isolated solid state relay



STM32 Open Development Environment

# Fast, Affordable Development and prototyping



Motion & environmental sensors  
Proximity sensor  
Microphone



BLE  
Wi-Fi  
Sub-GHz  
NFC



Power management  
LED Boost



Motor drive  
Actuator



Audio  
OpAmp



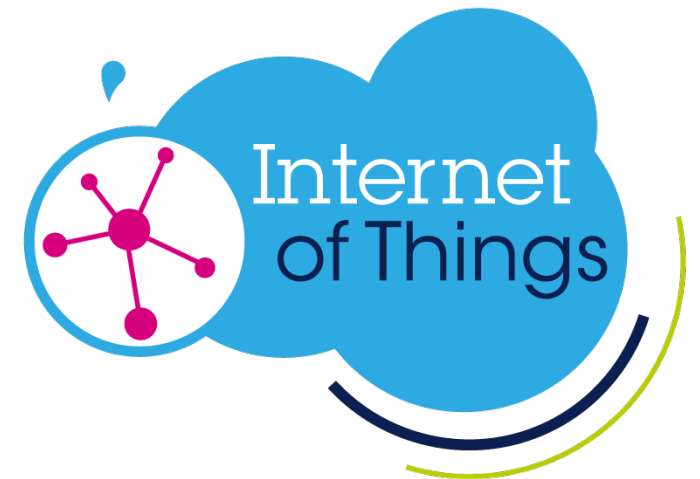
Processing



Scalable Security



- Internet of Things presents a wealth of opportunities for ST
- ST has all the building blocks for the IoT adapted to the different needs of diverse applications
  - Processing and security
  - Sensing and actuating
  - Signal conditioning and protection
  - Wired and wireless connectivity
  - Power and energy management
- ST makes development of devices for the IoT fast and affordable



# Smart Driving ST Leading the Transformation

**Marco Monti**

EVP, General Manager, Automotive and Discrete Group

**Marco Cassis**

EVP, President, Region Asia Pacific

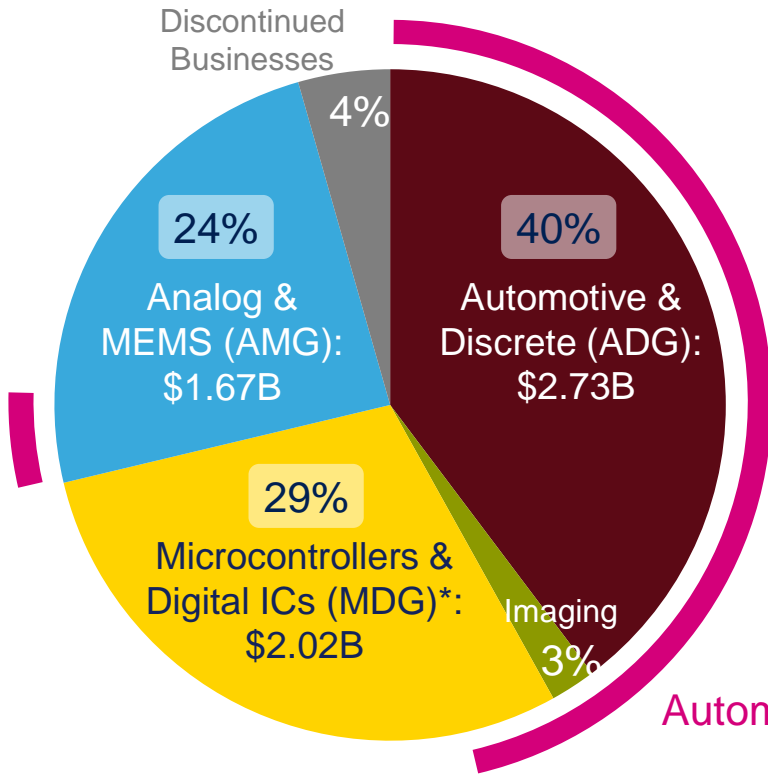
**Paul Cihak**

EVP, General Manager, Sales and Marketing, Europe, Middle East and Africa



# ST: a Global and Diversified Automotive Leader

with over 30 years experience



2015 Auto Revenues  
**\$2.1B**



2015 SAM  
Market Share  
**9%**

**Automotive**

- Automotive Microcontrollers
- Infotainment and Telematics
- V2X
- Radar & Vision ADAS
- Automotive Sensors
- Power & Smart Power

Automotive

#1  
Engine Management

#1  
Smart Power

#1  
24 GHz RADAR

#1  
ADAS Safety

#1  
Entry & Mid-end Telematics

#1  
Car Audio Amplifiers

#1  
GNSS

#2  
Infotainment





# The Rapidly Transforming Car

The automobile is being transformed by connectivity and technology improving safety, enhancing the driver experience and lowering the environmental impact

## Safer

## More Connected

## Greener

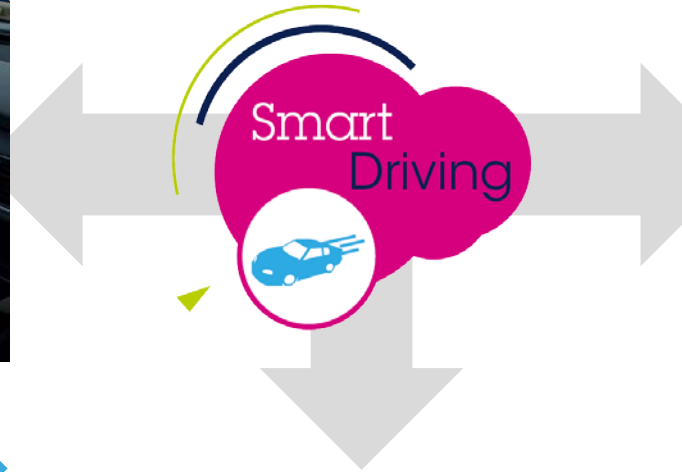
- Assisted driving, autonomous driving
- Enhanced vision
- Precise positioning
- Active safety
- Adaptive lighting, auto braking

- Vehicle to vehicle, vehicle to infrastructure communication
- Smartphone integration
- Enhanced telematics, insurance box
- Data and video streaming
- Cyber security

- Vehicle electrification
- Efficient engine management
- Eco Navigation
- Efficient LED lighting



# Semiconductors are Driving Change in the automotive industry

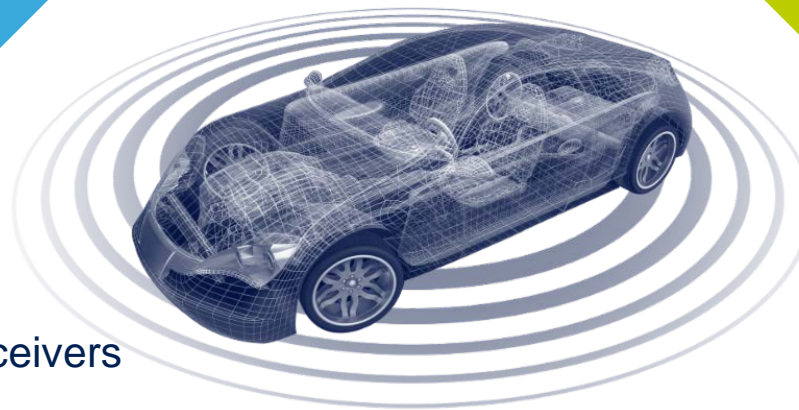


## Car Digitalization

- Multicore microprocessors
- Sensor fusion
- Video processing
- Data streaming
- Infotainment processors
- Radio Frequency transmitters and receivers

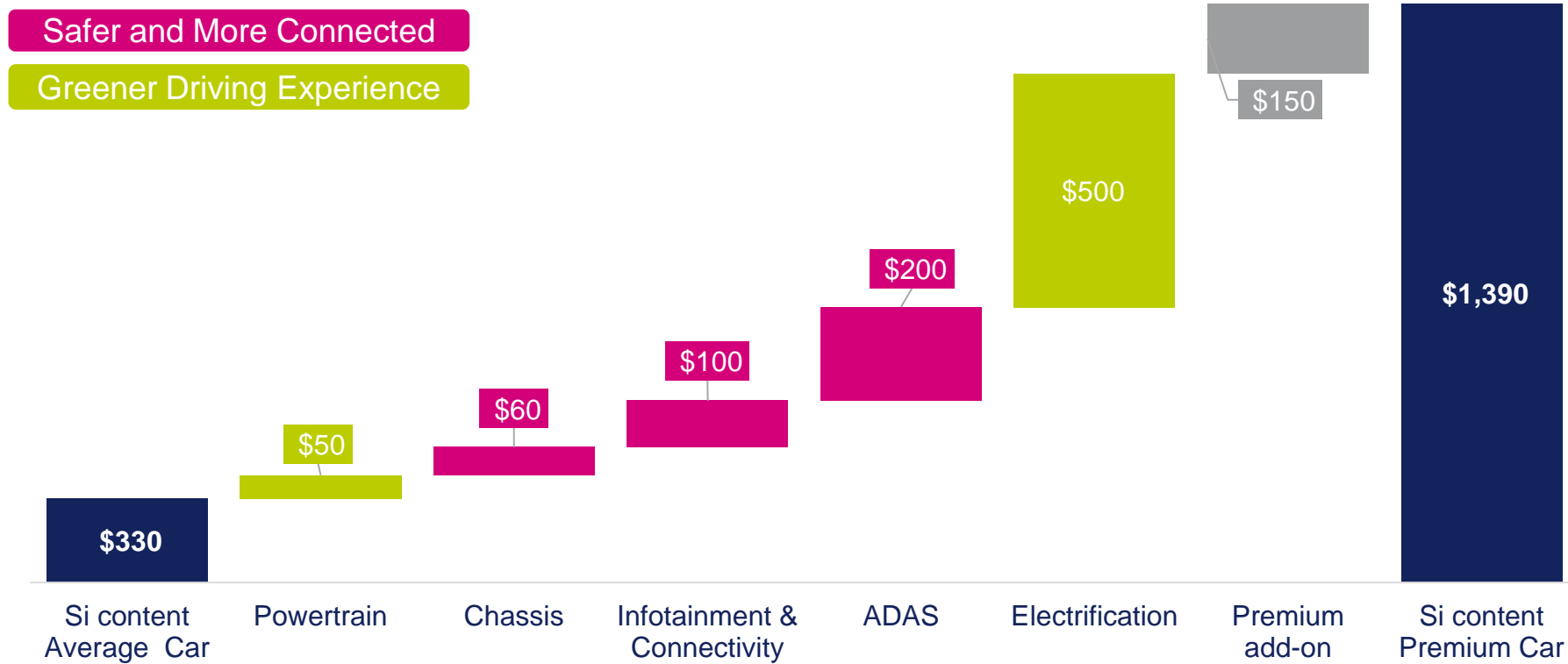
## Analog and Power Technologies

- High integration smart power
  - Power drivers
- High energy motor controllers
  - Battery managers
  - Video cameras
  - Sensors



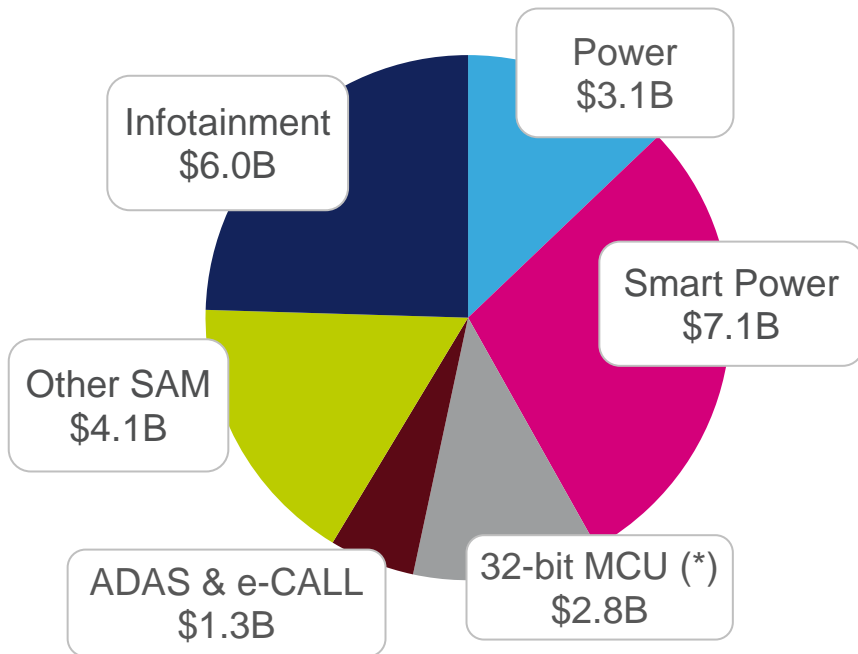
# Semiconductor Content Increasing

Silicon Pervasiveness: 2015 semiconductor content per vehicle



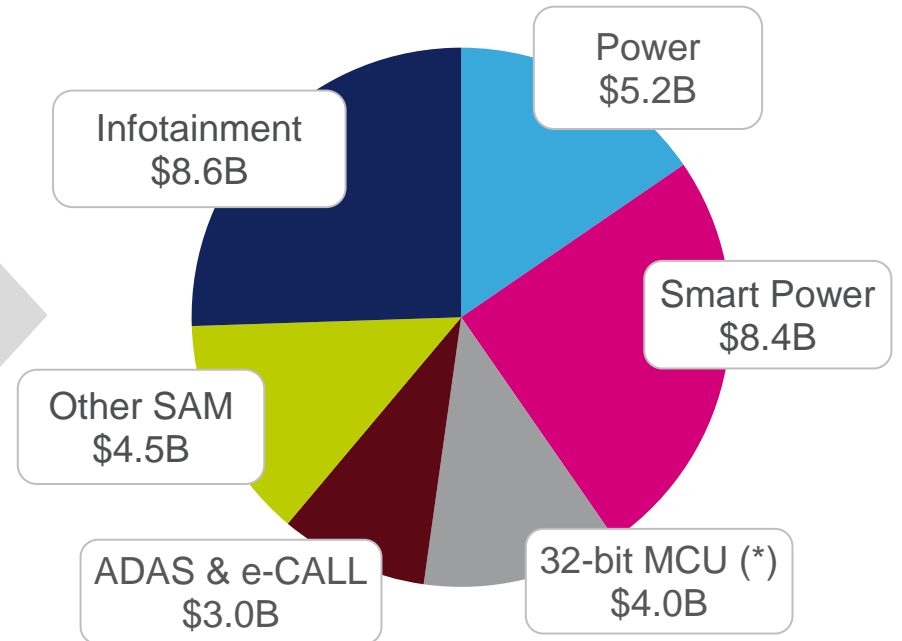
# Semiconductor Market Growth

2015 Automotive Semiconductor market TAM \$27B



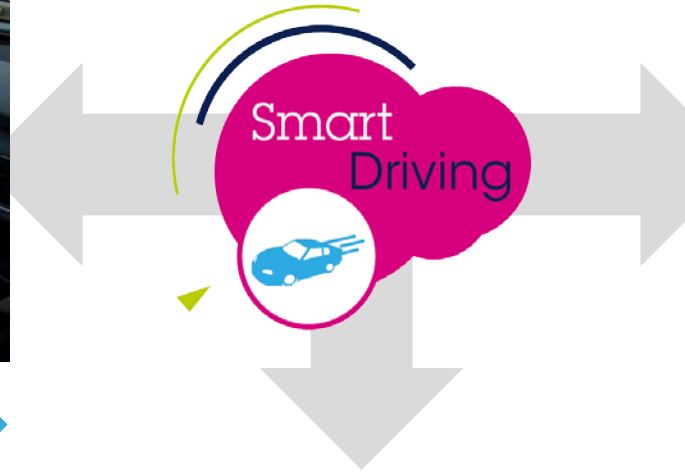
90% TAM addressed by ST

2020 Automotive Semiconductor market TAM \$38B



(\*) 32-bit embedded flash MCUs for powertrain, chassis, airbag, ADAS & body ; Infotainment included audio amplifiers Source: Strategy Analytics, ST

# ST have all the Key Technologies to drive automotive change: digital, analog and power



## Car Digitalization

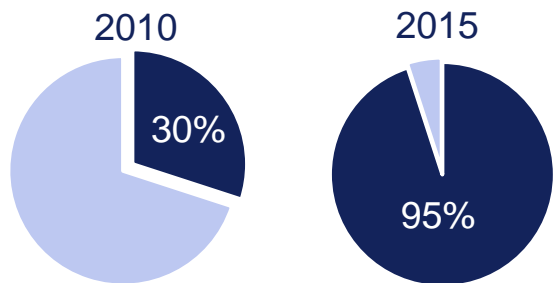
- Sensor fusion processors
- 77GHz/24GHz RADAR processors
- Machine vision processors
- 32-bit MCUs specific for automotive
- Infotainment processors
- Telematics processors
- Positioning, Wi-Fi, tuners
- V2X connectivity

## Analog and Power Technologies

- Smart Power ASIC's
- Smart Power ASSP
- Image and MEMS sensors
- Battery management IC's
- Motor controllers/drivers
- HV MOS, IGBT power drivers
- Silicon Carbide diodes and MOSFETs

Silicon technologies  
Application knowledge  
Key partners  
Customer portfolio  
Proprietary IP

## Wide application coverage

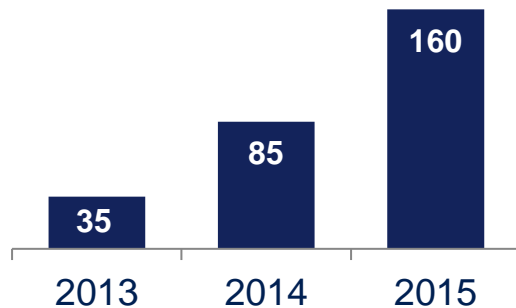


■ ST in ADAS Safety: Application Coverage

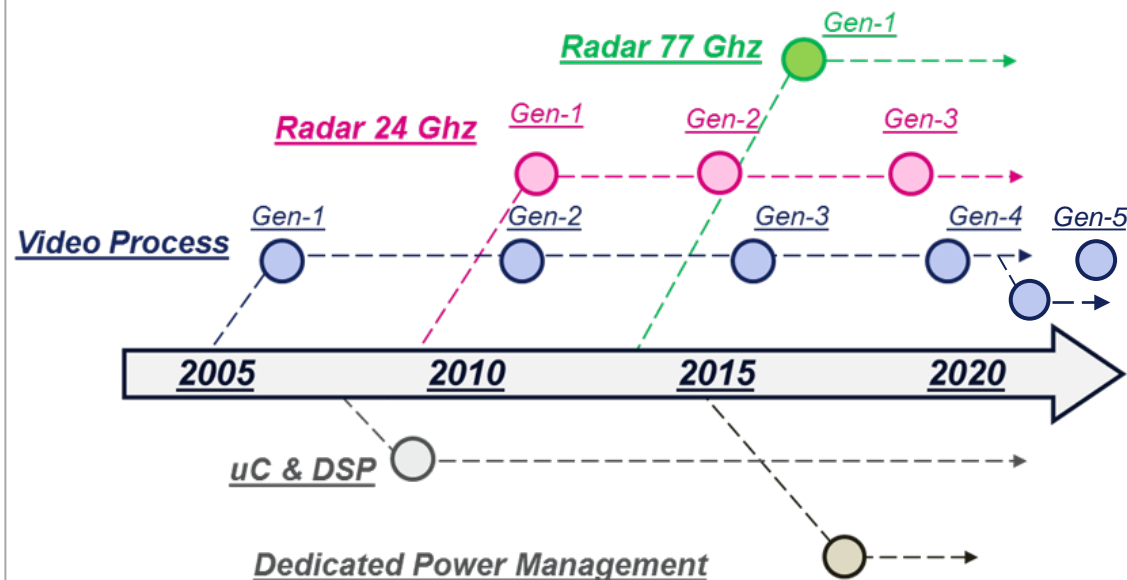
2015 ADAS Safety TAM ~\$550M (\*) (\*\*)

**#1** in ADAS  
29% ADAS Safety market share in 2015

ST Sales in ADAS (M\$)



### Continuously evolving roadmap



**FD-SEI** Radio frequency for RADAR

Recent Press Announcements made with..



(\*) Core apps: Forward collision warning, lane departure warning, pedestrian detection, adaptive cruise control, blind-spot detection  
(\*\*) TAM excludes camera, memories and optoelectronics

Estimated Market Share Evolution with business already won


ADAS System Components	2015	2020
Vision based TAM \$300M (*)	68 %	Leader →
Short Range Radar (24 GHz) TAM \$150M (*)	60 %	Leader →
Long/Short Range Radar (77 GHz) TAM \$207M (*)	4 %	Mid teen →
Microcontroller & DSP TAM \$408M (*)	3 %	Mid teen →
Power Management TAM \$90M (*)	7 %	Mid teen →

Vision Processing


270 car models equipped

EyeQ4 → Assisted Driving

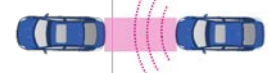
New! EyeQ5 → Fully Autonomous Driving



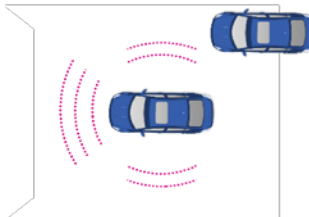


Adaptive Cruise Control



Collision Warning



Blind Spot Detection

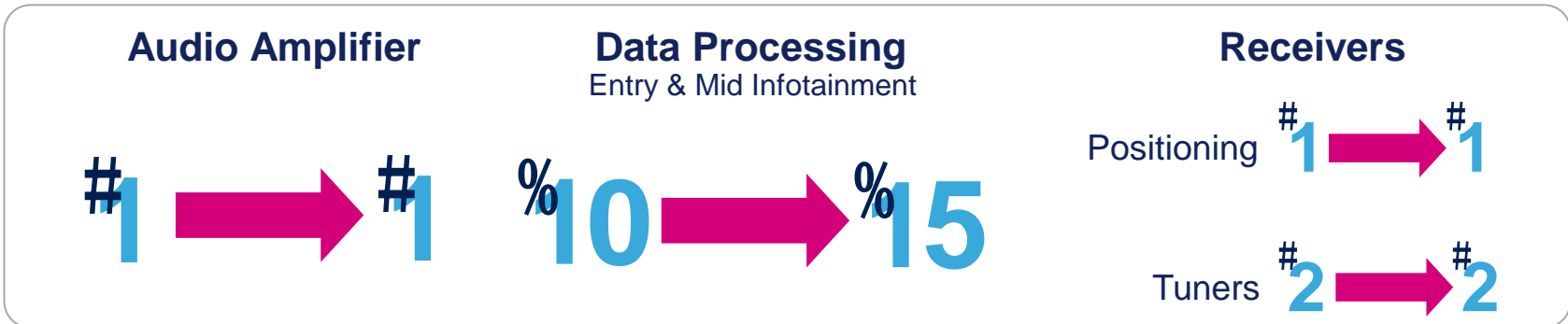
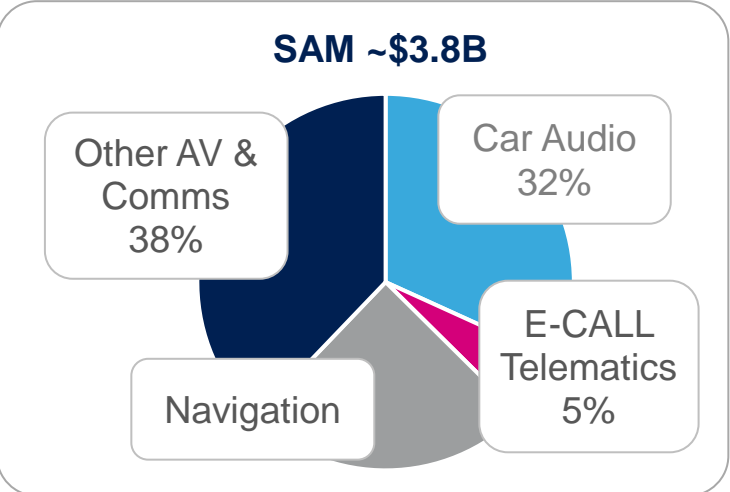
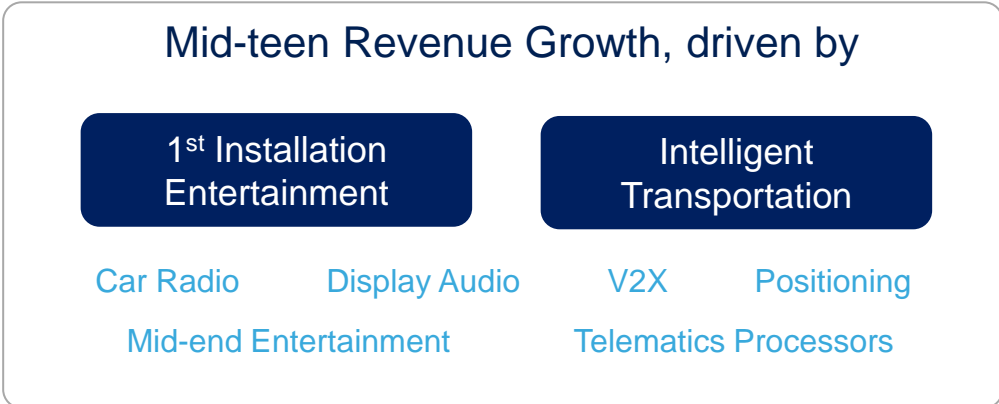
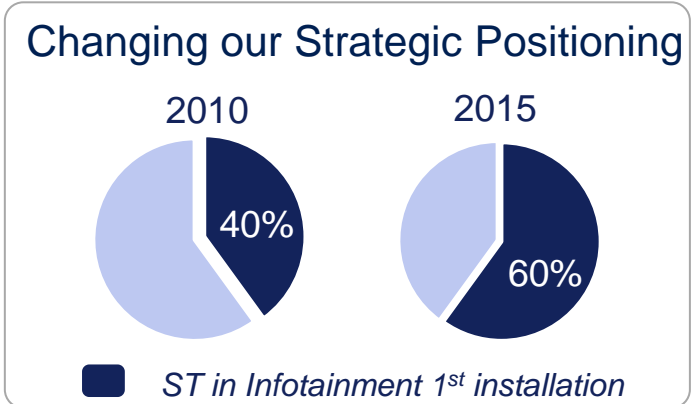
24/77 GHz Radar System

(\*) Estimated Market size in 2020 – Strategy Analytics , ST



## Addressing a growing and differentiated market

**#2 in Infotainment**  
 20% market share  
 in Infotainment specific ICs 2015



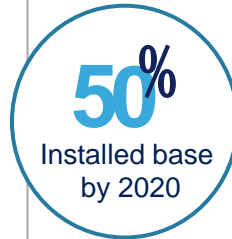


## Additional \$700M Opportunity by 2020(\*)

### Wi-Fi

#### Car-to-X: Craton2 with Autotalks

- Single chip automotive Wi-Fi processor
- V2X and internet hot-spot
- Remote SW-update ready
- Enabling cloud connectivity
- Awards from 4 major car makers targeting >50% of installed base by 2020



### Satellite



#### Navigation: Teseo III

- 3<sup>rd</sup> generation in production
- Multi-constellation, BeiDou-2 ready

#### ADAS: Teseo-P

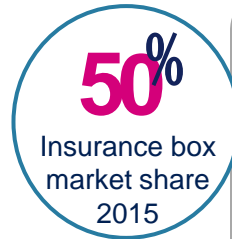
- Sub-meter precision for ADAS

#### Satellite data stream

- SiriusXM partnership
- FD-SOI for low-quiescent current

### Terrestrial Broadcast

- Market leader
- Digital tuner audio and data stream: Multi-standard digital radio receiver



### Cellular



#### Emergency Call and




#### Insurance-Box: TELEMACO

- Multi-core ARM processor

#### Infotainment & Internet Access: Accordo 5

- Android auto & car-play ready
- Enabling cloud connectivity



-  **ST33 Secure Element**
-  **SPC5 MCU with Crypto**
-  **Secure Wi-Fi for Car-2-X**



**Firewall to cloud**



**Secure communications among peripherals**

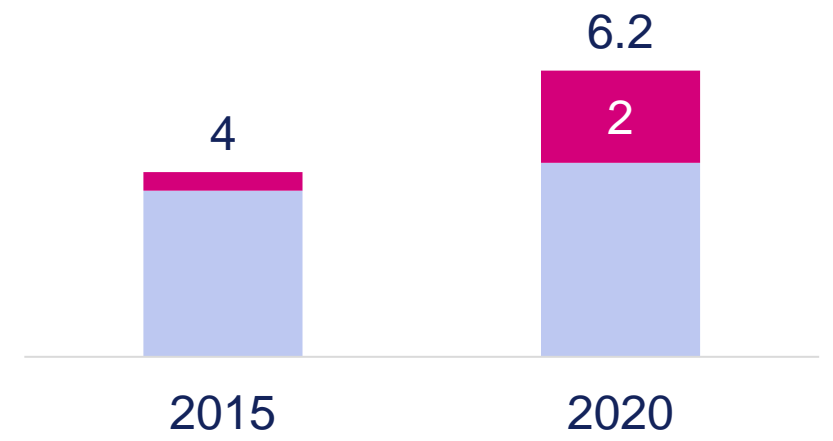


## Security in Automotive needs two levels of protection

**1<sup>st</sup> Level:** Authentication and a secure gateway with the external world

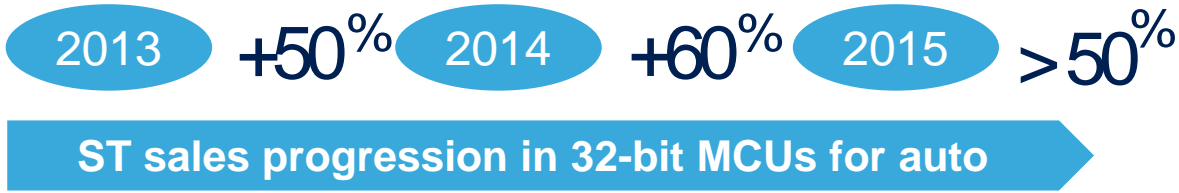
**2<sup>nd</sup> Level:** Data integrity and secure communication inside the car and in the car sub-systems

**> \$2B with security functions in 2020**



32-bit automotive microcontrollers with security on board vs total 32-bit microcontrollers (in \$B)

# Solid Progression in 32-bit MCUs



Estimated Market Share Evolution with 4B\$ business already won

32-bit MCU	2015	2020
Body and Gateway TAM \$0.7B (*)	6%	Leader
Powertrain TAM \$1.2B (*)	4%	Low teen
Chassis and Safety TAM \$2.1B (*)	1%	Low teen

### ADAS and Powertrain

High performance multicores with dedicated timing, security and ASIL D safety

New ARM multicore with 5x performance vs current offer



### Security

80% 40nm devices with hardware security 

### Body and Gateway

Largest scalable family covering all body applications

### Key enablers

Power architecture

Crolles 300 manufacturing

ARM V8-R architecture

Scale factor with GP MCUs

Security

Customer network

Unique differentiated technology (28 FD-SOI & PCM)

System knowledge



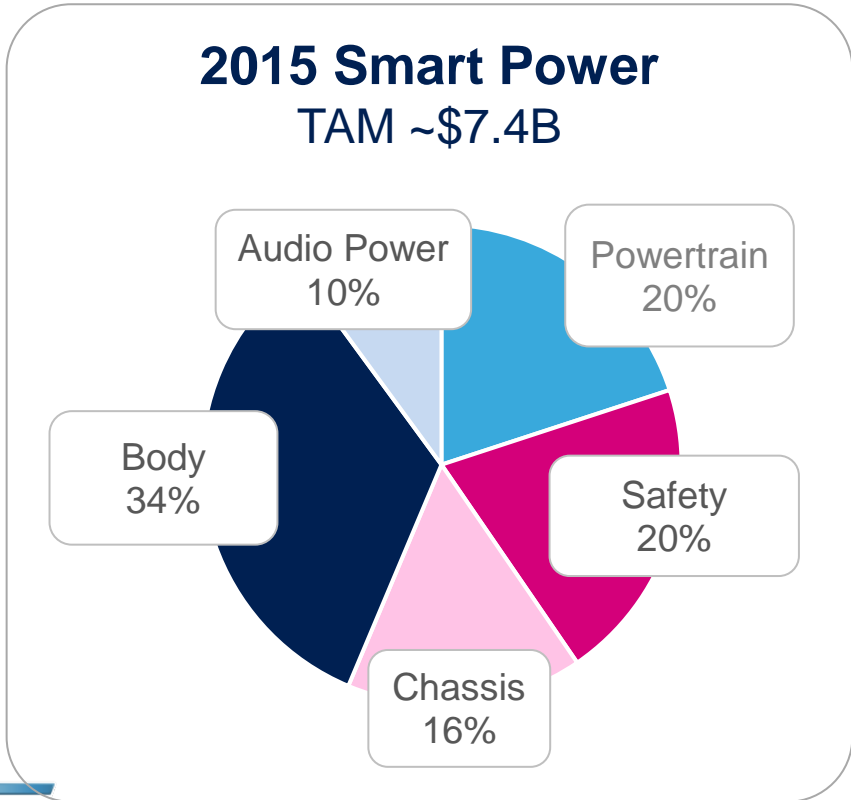
(\*) Estimated Market size in 2020 – Strategy Analytics, ST

# Leaders in Automotive Smart Power

Market leader in a large TAM sector with steady growth

**#1 in Smart Power**

2015-2020 market  
CAGR: 3.2%



Estimated market share evolution with business already won

Analog contents	2015	2020
<b>Powertrain</b> Smart power TAM \$1.7B (*)	26%	Leader
<b>Safety and chassis</b> Smart Power TAM \$3.2B (*)	11%	Leader
<b>Body and Audio</b> Smart Power TAM \$3.7B (*)	20%	Leader

Technology enablers

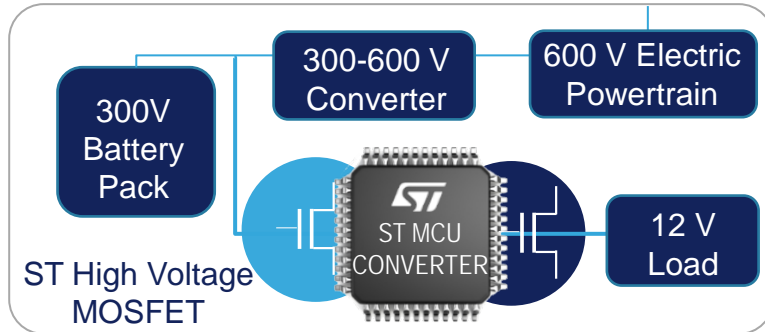
BCD9 110nm production	M07 180nm production
BCD10 90nm R&D	M09 130nm R&D



(\*) Estimated Market size in 2020 – Strategy Analytics

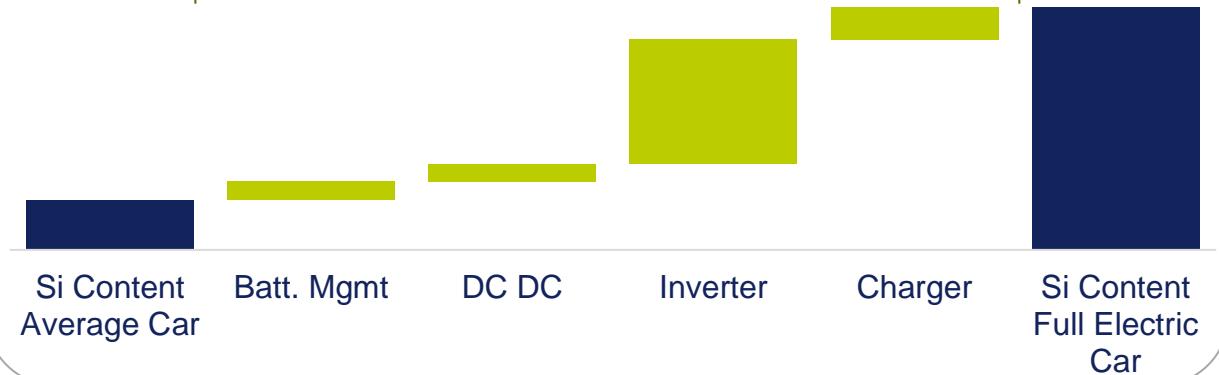
a great opportunity to expand market TAM

ST is already a strong player in car electrification leveraging its strategic partnerships

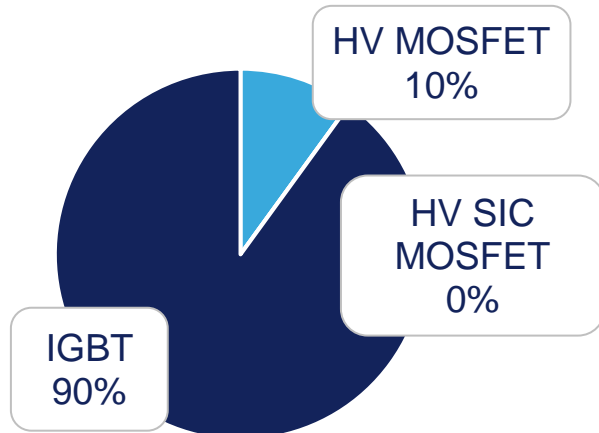


## Silicon Pervasiveness in Car Electrification

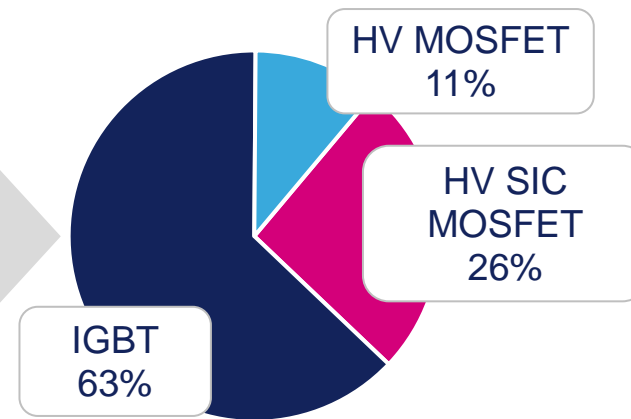
500+ \$ Silicon Content per Car



2015 TAM\* \$140M



2020 TAM\* \$600M



(\* Pure EVs, Hybrid Plug-in)

# Key Challenge in Electric Vehicles

## Mileage extension

### Industry Challenge

### Market Trends and Benefits

### ST Positioning

#### Mileage Extension



#### More Efficient Power Conversion (\*)

Reduced Battery Cost

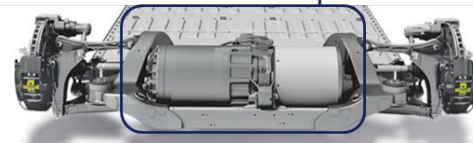
Extended Mileage

-20%

Traction Inverter



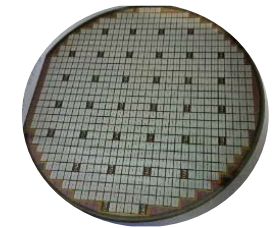
+20%



#### SiC MOSFETs

4X more efficient than IGBT

#### SiC Diodes



6 inch wafers from 2017

Cost competitiveness

#### Smart Battery Controllers

Extended Mileage

+8%



#### Smart Power ICs

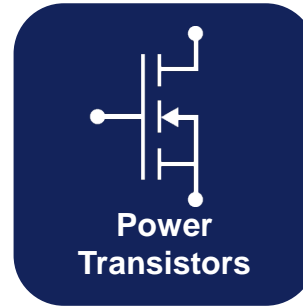
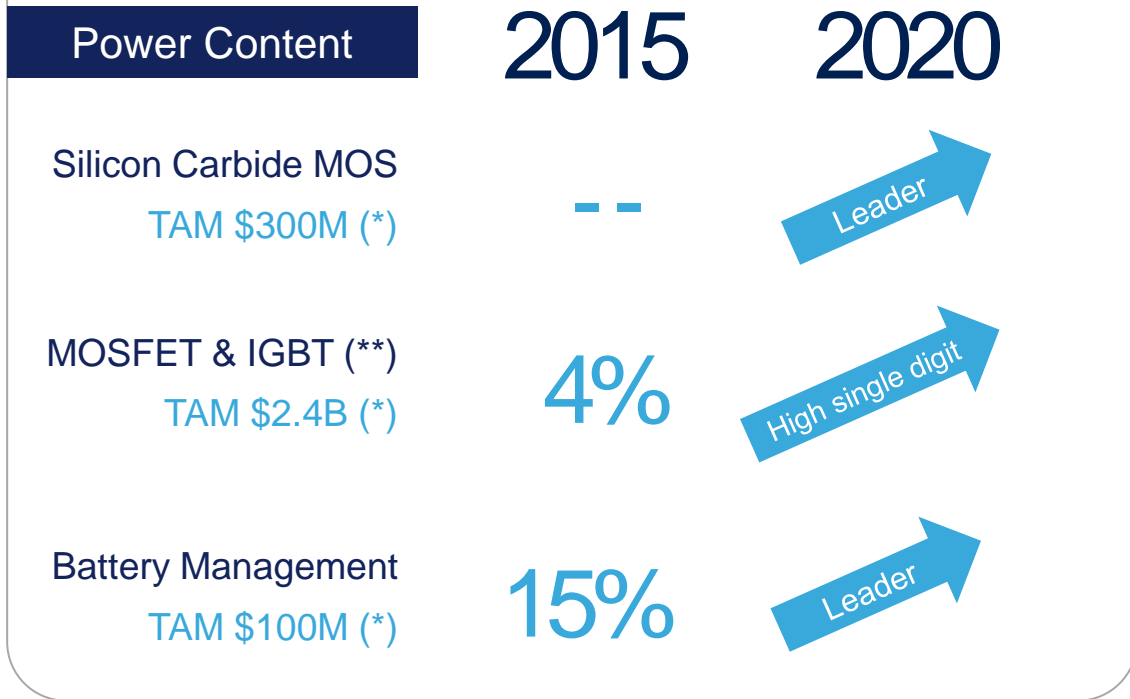
Innovative active cell load balancing



(\*) 20% power savings can result in gains of over \$6,000 in battery cost, or 8% of the vehicle cost

# ST Strong Focus on Car Electrification

Estimated Market Share Evolution  
with business already won



**HV MOSFETs**

300V – 1700V

**LV MOSFETs**

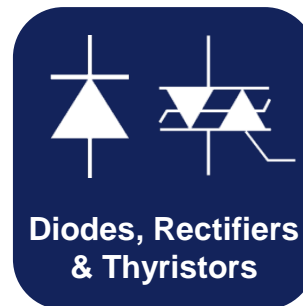
OFT from 30 up to 150 V

**Silicon Carbide (SiC)**

From 650 up to 1200V

**IGBT**

HEV and motor control  
up to 1700V



**Silicon Carbide Diodes**

**Field Effect Diodes**

**Silicon Diodes**

**HV Triacs**

(\*) Estimated Market size in 2020 – Strategy Analytics , ST

(\*\*) Break Down voltage above 400V

- ST is a global leader in the Automotive market
- Car connectivity, increased safety and green concerns are rapidly boosting the semiconductor content per car
- ST is leader in ADAS technologies and in Infotainment, ready to enable autonomous driving and the pervasion of car connectivity
- ST is leader in smart power technologies and will extend its market share profiting from car electrification







# Automotive and Discrete Group (ADG)

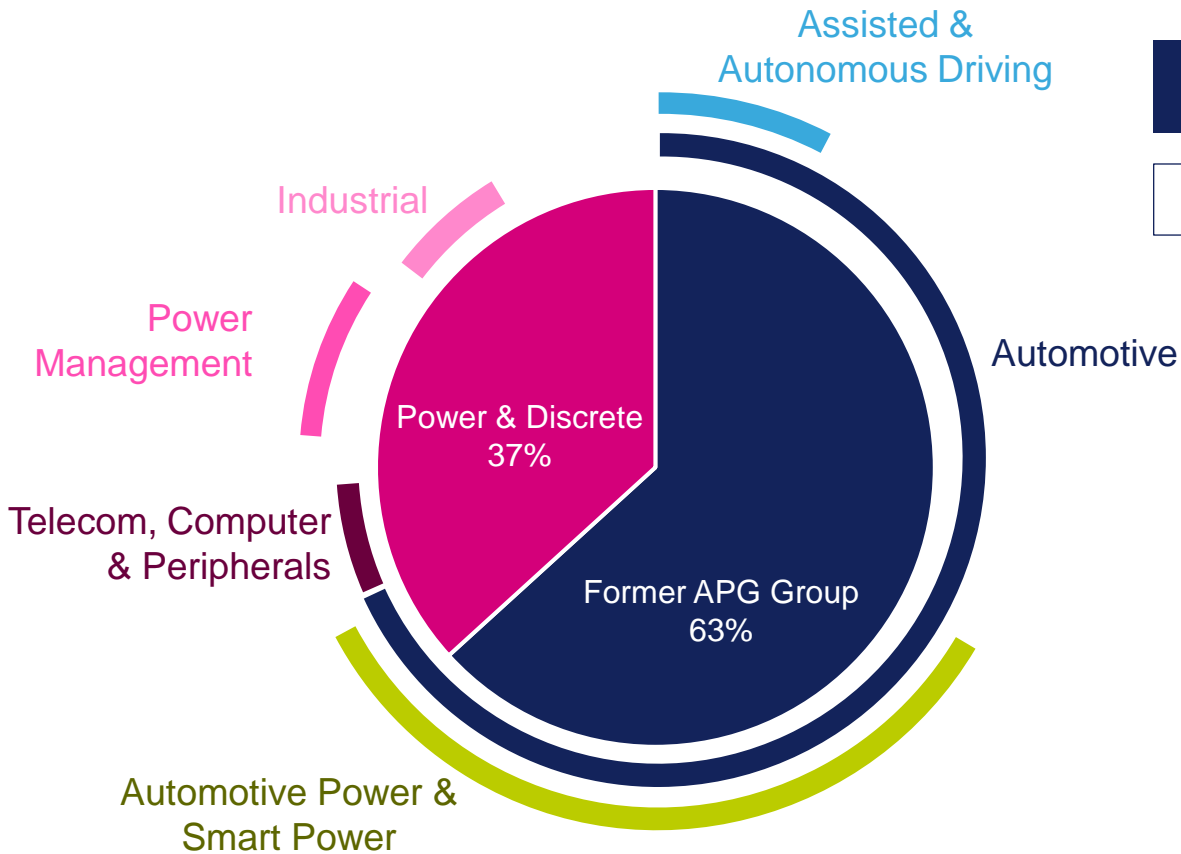
**Marco Monti**

Executive Vice President, General Manager, Automotive and Discrete Group



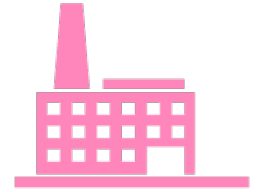
# From APG to ADG: \$2.7B in FY'15

## Group Revenues by Core Application



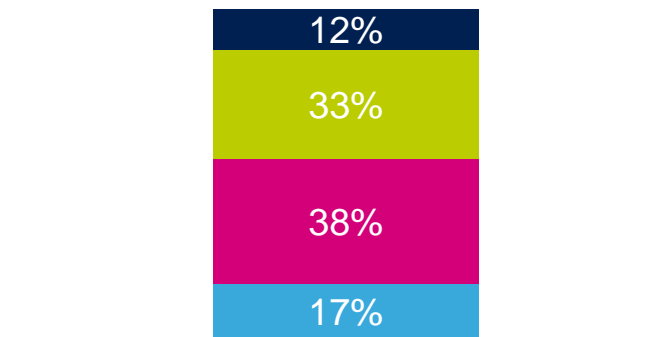
### AUTOMOTIVE

FY '15 Revenue: \$1.9B

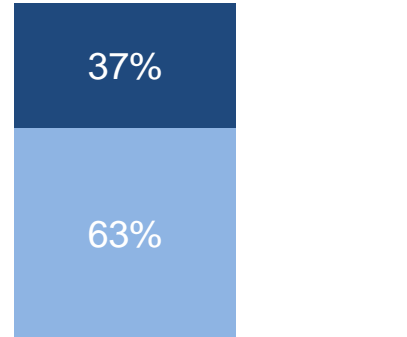


### POWER & DISCRETE (\*\*)

FY '15 Revenue: \$0.8B



Sales by Country of Shipment



Customer Type



(\*) Power Schottky, Ultrafast & SiC diodes EOS, ESD, Lighting protections & IPAD's (\*\*\*) Non Automotive

America EMEA GC&SA Japan&Korea

OEM Disty

# New Organization Synergy

99

## Boost Top Line

### Product Synergies

- Increase focus in automotive leveraging on traditional APG system know-how, customer intimacy and extended set of portfolio technology and product

### Expand Customer Base

- Increased customer presence and efficiencies leveraging on combined marketing and support teams

Capture opportunities in new markets for ADG product derivatives



## Competence Synergies

### Manufacturing

- Wafer probing assets optimization

### Technology

- Centralized technology R&D, exploiting synergies between MOSFETs, SiC, VIPower and Smart Power in automotive and other markets

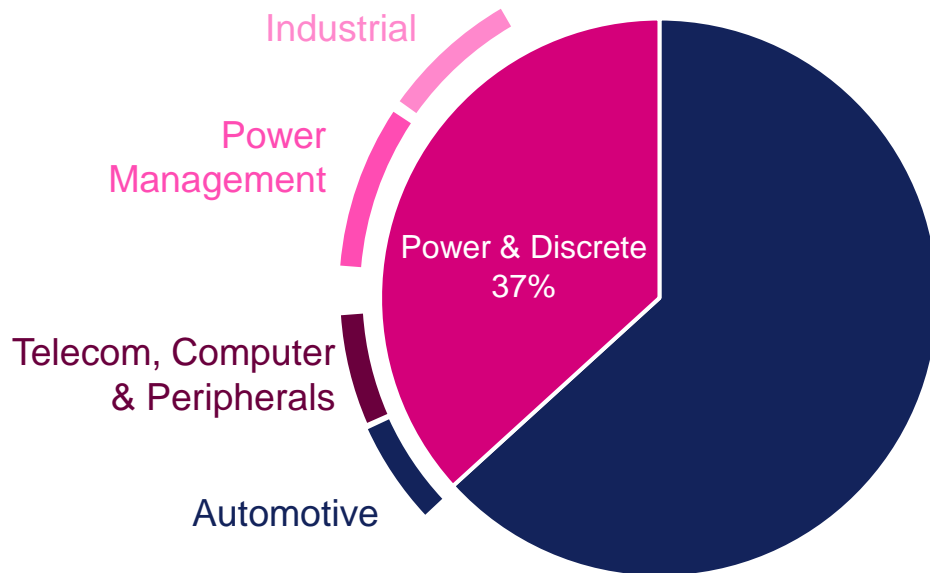
### Quality

- Rationalization in quality and supply chain to address automotive segment

### Extended R&D bandwidth and synergies



Portfolio delivering complementarity for target end markets, and synergies in R&D and manufacturing



#1 High Voltage Power MOSFETs

#1 Thyristors and Triacs

#1 Power Rectifiers SAM\*

#1 Protection and IPAD SAM\*

- **Application driven product development strategy with objective of growing in differentiated products vs competition**
  - Fast portfolio renewal (>20% of sales on new products)
  - Capitalize past investments in new emerging technologies (SiC/GaN)
  - Focus on new **Power Packages** for high-power applications with optimized power density including **Intelligent Power Modules, High Power Modules**
- **Wide and scalable product offer to support customer as one stop shop**
- **Strong cooperation with distributors to boost demand creation in mass market**
  - Tangible results in STM32 associated product program (1+x)
- **Focus program to boost sales in standard products**

Group Focus	Application Segment	Selected Technology
-------------	---------------------	---------------------

**Automotive Electric Charger**

Up to 1500V



Industrial Motor Control, Solar Factory Automation, Metering, Fast Automotive Chargers



IGBT, SiC MOSFETs, Power MOSFETs (MDmesh™), ACEPACK™, Power Bipolars

**Industrial Motor Control**

Up to 700V



Home Appliance, Power Management, LED Lighting, Automotive Electric Traction



Power MOSFETs (MDmesh™), IGBT, SiC MOSFETs, Intelligent Power Module (SLLIMM™), Power Bipolars

**SiC for Automotive Traction**

40V - 150V



Automotive Electronics, E-Bikes, UPS Power Mgmt



Power MOSFETs (STripFET™), Power Bipolars

**Server Farm**

Up to 60V



Server, Computer Peripherals, Telecom



# Protection, Integrated Passive & Active Devices

## Market & Positioning

2015

TAM ~\$640M

#1

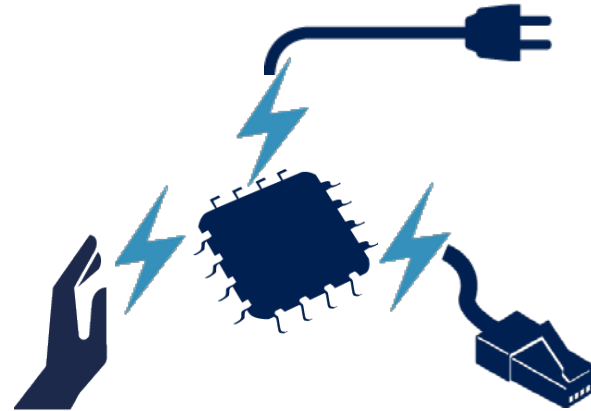
Protection SAM  
EOS,ESD, Lighting

#1

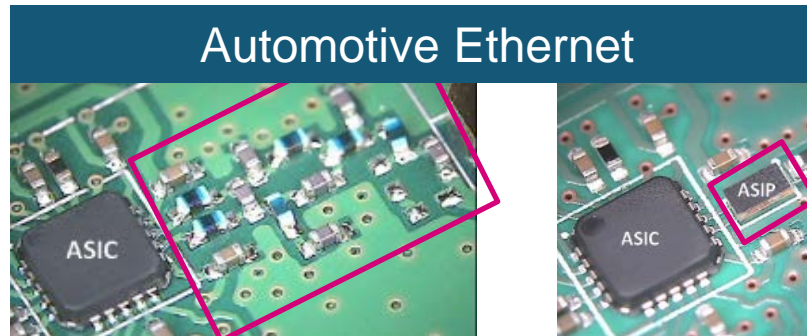
IPAD™



## Industry Domain

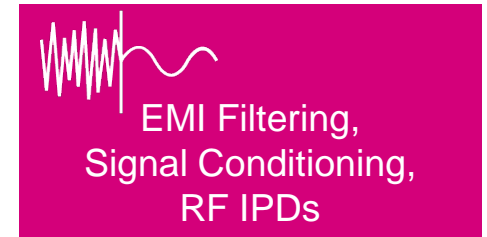
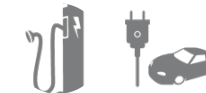


IPAD™ Integrated Passive & Active Devices



Improves performance and drastically reduces space (-70%)

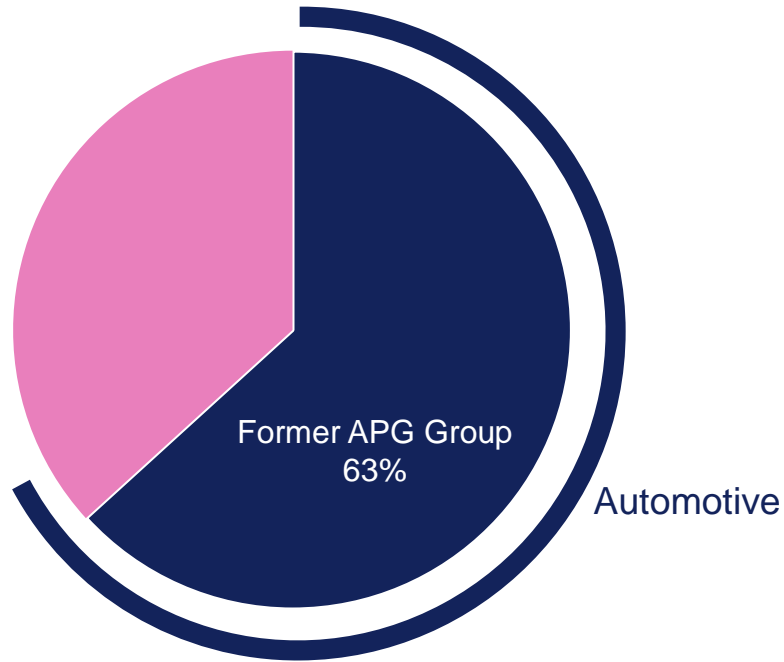
## Selected Technology



Antenna Tuning  
RF Coupling interfaces (WiFi-BT)  
Signal Filtering



Consumer high-speed ports,  
Automotive CAN, LIN, FlexRay



- Strong Market presence
  - 30+ years leadership in automotive
  - Continuous gains in market share in all regions
  - ADG provide 90% of ST revenue in automotive
- Significant Innovation breakthroughs
  - Strong focus on new materials for power electronics (SiC), advanced digital products for ADAS, 32-bit MCUs and solutions for telematics, eCall, V2X...
  - Reinforcing strong smart power market position with the introduction of the most advanced BCD and VIPower technologies in the industry
  - Proprietary and independent manufacturing, mastering quality and automotive requirements
- Strong cooperation with car makers and market leaders

2015 Auto ADG  
**\$1.9B**

Power & Non-Power Analog

**14%**

2015 ADG SAM  
**\$24B**

Automotive Digital

**7%**



Source: Strategy Analytics, ST





# The Rapidly Changing Car

The automobile is being transformed by technology and connectivity. ST is making driving safer, greener and more connected through a fusion of technology.

Safer	Greener	More Connected
<ul style="list-style-type: none"><li>• Assisted driving, autonomous driving</li><li>• Radar and machine vision</li><li>• Precise positioning</li><li>• Active safety</li><li>• Adaptive lighting, intelligent braking</li></ul>	<ul style="list-style-type: none"><li>• Vehicle electrification</li><li>• Efficient engine management</li><li>• Eco navigation</li><li>• LED lighting</li></ul>	<ul style="list-style-type: none"><li>• Vehicle to vehicle communication</li><li>• Smartphone integration</li><li>• Premium telematics</li><li>• Data and video streaming</li><li>• Full digital entertainment</li><li>• Greater communication security</li></ul>

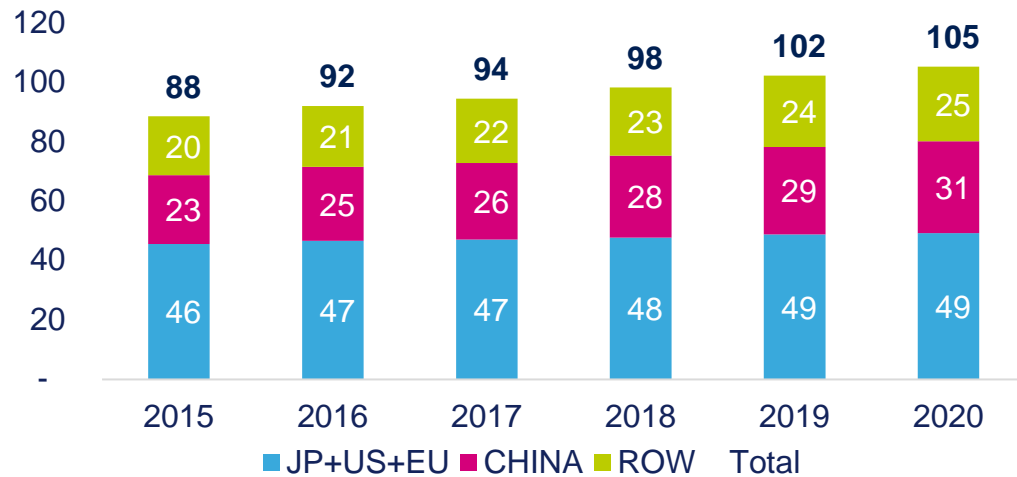




# Automotive Market: Solid Foundations

Continuous steady market growth

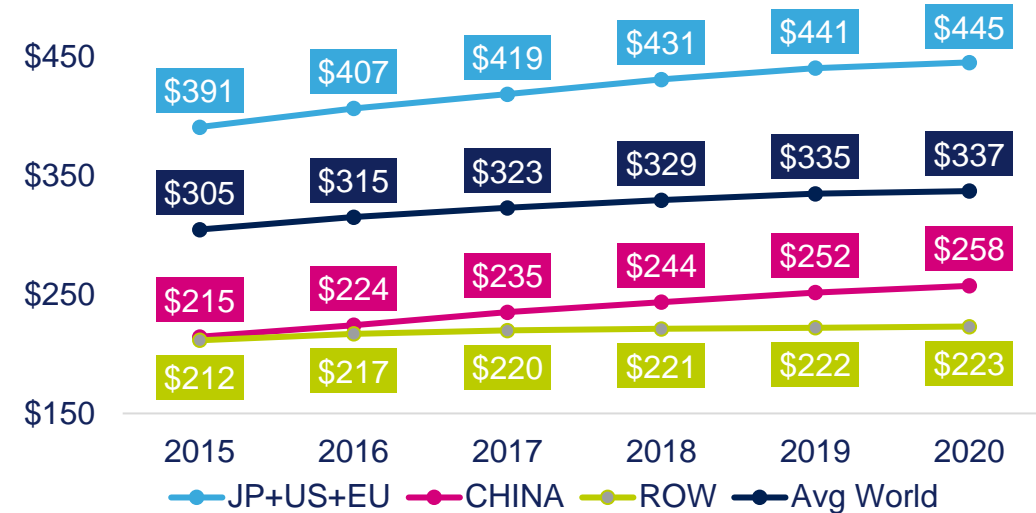
Vehicle Production



 '15-'20 CAGR @ 3.5%

 '15-'20 CAGR @ 6.0%

Silicon Content Value per Vehicle



 '15-'20 CAGR @ 2.0%

 '15-'20 CAGR @ 3.7%

#1 in China

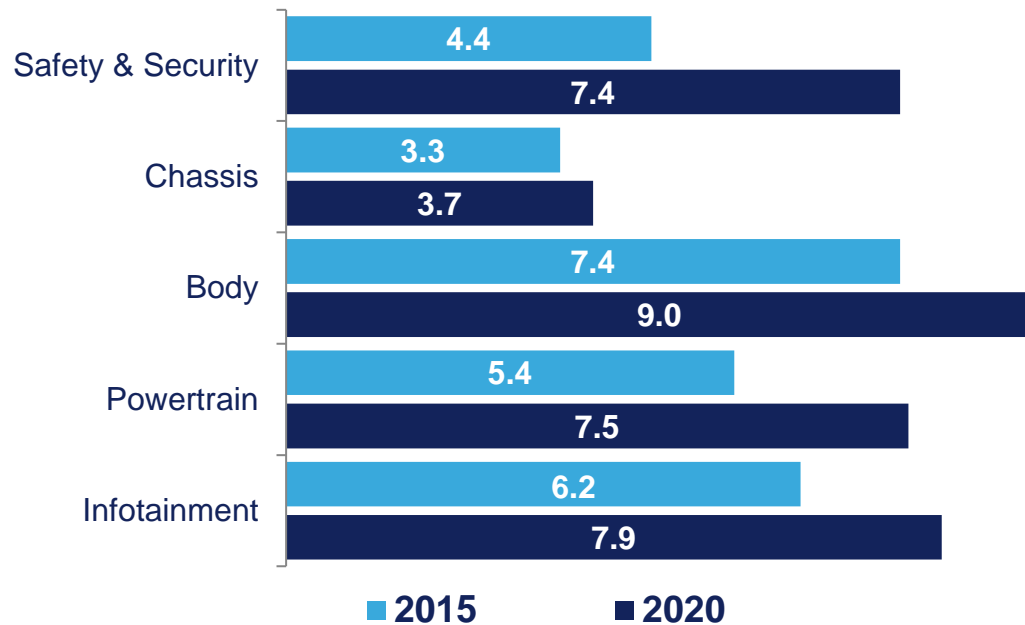
#2 in EMEA & USA

#3 in Japan & Korea

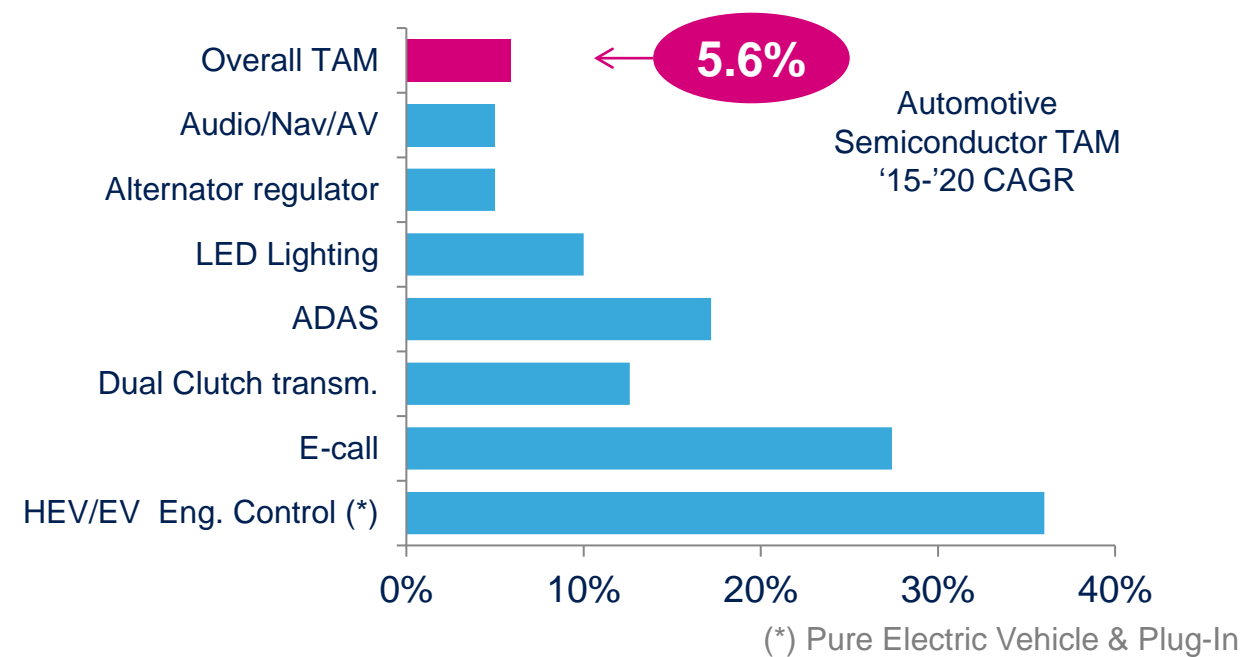
# Automotive Market: The right place to be

## Addressing a \$27B market

### All Segments Growing B\$



### Emerging Applications



# ADG: Broad Coverage of Automotive Applications

## Car Infotainment & Connectivity

Car Radio

Satellite Radio

ADAS

Digital Tuners

Car Infotainment Processors

Positioning

V-to-X Connectivity

Car Wiring and Networking

Telematics

Road Tolling

Secure Communications

Wireless Connectivity

On average

# 120

independent ECU's per vehicle



## Automotive Electronics

Thermal Engine Control

Electrical Engine Control

Automatic Transmission

Charging (12V)

Airbag

Braking (ABS, VDC)

LED Lighting

Adaptive Lighting

Body Control

Door & Mirror control

Suspension

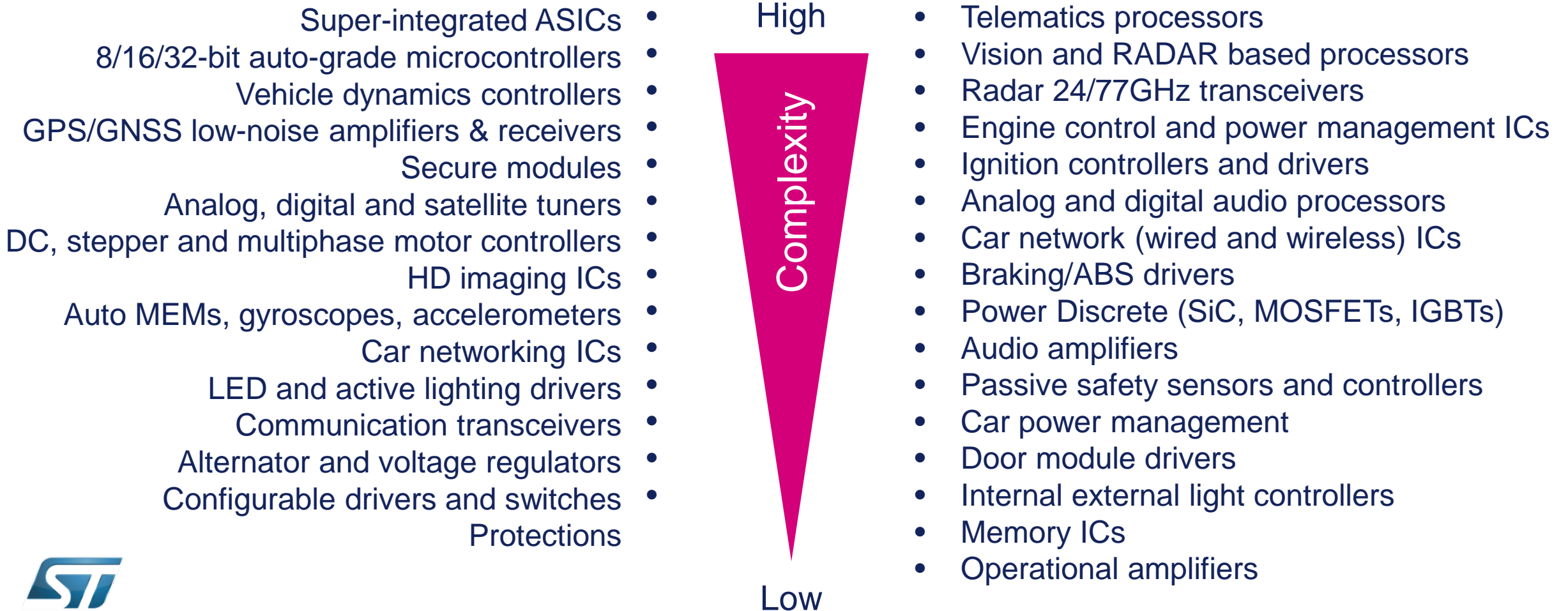
Steering (EPS)

ST portfolio covers the majority of control unit requirements

# Comprehensive Product Portfolio to Lead in Focus Markets

108

from commodity to super-integrated ASICs



# Leadership in Smart Power

109

## Market and Positioning

### 2015 SMART POWER

TAM ~\$7.4B

#1

ST in Smart Power

26%

Share in Powertrain

48%

Share Lighting

11%

Share Chassis & Safety

## Key Products and Design Wins

**Engine Control:** Direct injection system increasing semiconductor content (+40%) per Car

- Dedicated ASSP & ASIC product roadmap to meet EURO-6 requirements



### Dual Clutch Transmission

- Fully Integrated ASSP market solution for high-performance automatic transmission



### Passive Safety

- 130+ M\$ award for high-end (up to 40 loop) airbag U-chip for a premium Japanese carmaker
- 110+ M\$ ESC U-chip award for leading braking supplier in Japan



### Body & Lighting

- Full deployment in volumes of drivers for lighting with 350nm ViPower technology
- Roadmap expansion on LED lighting solutions



## Key Customers



**DENSO**

**HITACHI**



Key Asset

**Functional Safety ISO 262262 Compliant**

**Unique proprietary IP Portfolio**

**BCD 110nm production, 90nm Under Development**

**ViPower 180nm production, 130nm under development**

**30+ years Strategic Partnership with system leaders & OEM**

## Market and Positioning

### 2015 Electrification

TAM ~\$3B

#1

in High Voltage MOSFETs

#1

in Thyristors and Triacs

#1

in Power Rectifiers(\*)

#5

in Automotive Power Transistors



## Key Products and Design Wins

### SiC MOSFETs

- New 650V product family tailored for motor control
- Full internal manufacturing for quality & competitiveness
- 75% improvement on power losses vs IGBT
- 200°C junction temperature for improved reliability

### LV MOSFETs

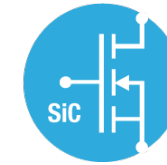
- STripFET F7 LV MOSFET trench product family perfectly fitting automotive motor control applications
- Optimized diode performance for motor control applications
- High robustness and reduced emissions
- Large package portfolio

### SiC Diodes

- Fast, Efficient, High temperature
- Chargers and DC-DC converters

### TRIACS, Thyristors

- Largest product portfolio in the industry
- For on-board charges to limit in-rush current at system connection



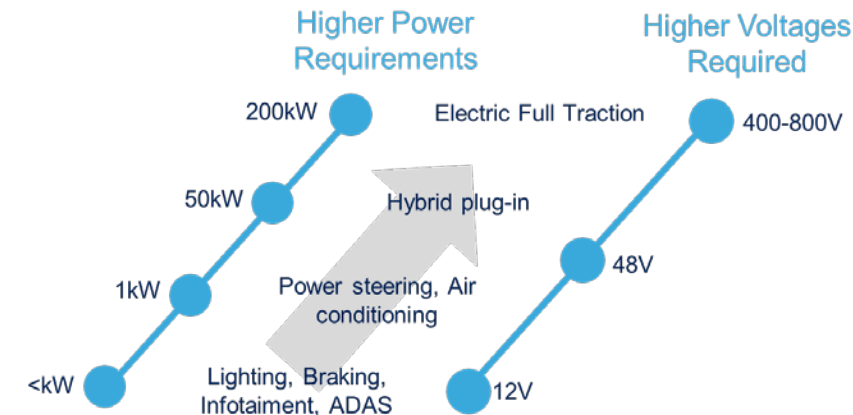
Plug-in / On-Board Chargers

Power Converters

Traction Inverters

Steering

Braking



(\*) Power Schottky, Ultrafast & SiC diodes

# Automotive 32-bit MCUs

111

## Market & Positioning

### Fastest Growing Product Family in ADG

**5B** \$ 2015 TAM in Automotive

**75** % TAM coverage with focus  
on Body, Powertrain,  
Chassis and Safety

**4B** \$ Business awarded since  
2007

## Key Products and Design Wins

- Strong progression in design wins on existing and new products reaching 4B\$ : Secure gateway, ADAS and powertrain are main driving applications
- Announced new 40nm product family to address gateway and body application leveraging on 2x performance vs previous generation, large family scalability, multiple high speed interfaces and embedded security module
- Continuous expansion of product family with Power Architecture guaranteeing customer scalability to current solution to address ADAS, powertrain, gateways and body segments
- Started the design of new high-end family with ARM v8R core, embedded phase change memory in 28nm node in cooperation with a leading tier-1



## Key Customers

**Continental**

**BOSCH**

**UAES**

**Valeo**

**LEAR**  
CORPORATION

**ZF** **TRW**



### Key Assets

Power Architecture  
& ARM V8R Core

Customer Intimacy &  
System Knowledge

Internal Manufacturing  
Crolles 300

Low Power FDSOI 28 &  
embedded Phase Change Memory

## Market and Positioning

### 2015 ADAS Safety

TAM ~\$550M (\*) (\*\*)

**#1** ADAS Safety Segment  
in 2015

**#1** Machine Vision in 2015

**#1** in 24Ghz RADAR RXTX

**#2** in RADAR Transceivers  
Market in 2015



## Key Products and Design Wins

### Machine Vision

- Machine Vision MPU is the core enabler for autonomous driving
- EQ4 samples to customer on-time
- ST and Mobileye announced the start of development of EQ5, the most advanced MPU to enable Stage 4 autonomous driving

### RADAR

- Focus on BiCMOS technology to ensure customer best performance in range and precision
- Major award on 77GHz transceivers with leading market player
- 24GHz adoption growing due to system costs lower than 77GHz

### ADAS ASICS

- Started design of products for new application fields

### Power Management

- Most advanced solution to enable application miniaturization designed to address major players need
- Sampling majority of machine vision and RADAR unit manufacturers

### Microcontrollers

- New awards by major players for 24GHz/77GHz (Processing and fusion MCU)

## Key Partners



(\*) TAM excludes camera, memories and optoelectronics

(\*\*) Core apps: Forward collision warning, lane departure warning, pedestrian detection, adaptive cruise control, blind-spot detection



## Market and Positioning

### 2015 Infotainment

SAM ~\$3.8B

**#1** in Positioning

**#2** in Infotainment ASSPs

**#1** in Audio Amplifiers

**#1** in Digital Tuners



## Key Products and Design Wins

### Accordo & Telemaco: Infotainment and telematics processors

- Accordo 2 strong pipeline of awarded business. Aftermarket in production, OEM production start in Q3'16
- Accordo 5 samples delivered to early adopters within Q2'16
- Telemaco 2 starting production in Q3'16



### Class D Amplifiers

- Larger product portfolio and development pipeline than any competitor. 80+ M\$ awards in the pipe, OEM programs



### Terrestrial Tuners

- STAR and DOT family offering system flexibility vs competition for multi-standard receivers. STAR production starting in Q4'16 with several leading OEM



### Satellite Tuners

- Extended cooperation with SiriusXM on next generation satellite receiver as leading strategic supplier

### Positioning

- Leading multi-constellation technology with excellence in dead reckoning sensor fusion
- Opening the new frontier of precise positioning for autonomous driving in parallel with car manufacturers



## Key Customers



## The most comprehensive and technically advanced offering for V2X Market

**V2X**  
TAM ~\$200M in 2020

**V2C**  
(Vehicle-to-Cloud)

**V2I**  
(Vehicle-to-Infrastructure)

**V2V**  
(Vehicle-to-Vehicle)

**V2P**  
(Vehicle-to-Pedestrian)



**Security**



**GNSS**  
Precise Positioning  
< 20cm



- Supports the reduction of road fatalities by more than 90% when combined with other ADAS technologies
- Best technical solution to address the challenge of volume V2X technology deployment
- Most advanced solution to handle cybersecurity risks
- Secured participation in trials preparing technology introduction into the market
- Sampling V2X 11-p Wi-Fi processor to Autotalks in Q3'16

# Leadership Technology & Manufacturing

## Power and Analog

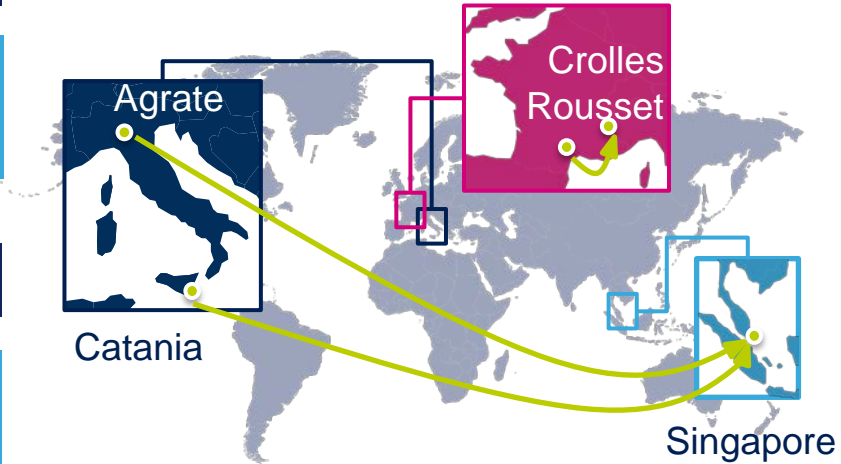
**Power Transistors**  
(LV, SiC & SJ MOSFET, GaN)

**Other Discrete**  
(FERD, Si)

## Mixed Signal

**BIPOLAR CMOS DMOS**  
(90nm ePCM)

**Vertical Smart Power**  
(110nm)



## Digital

**Advanced CMOS**  
FD-SOI (28nm)

**Specialized CMOS**  
Imaging Sensor

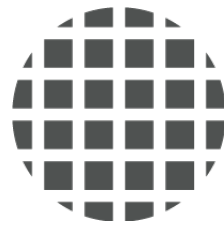
**eNVM**  
GP & secure MCU Automotive MCU EEPROM  
(FD-SOI 28nm ePhaseChangeMemory)

**AMS/RF CMOS**  
(40nm RF)

**BiCMOS**  
(FD-SOI28 ePCM)



6" SiC



8" Smart Power,  
Power, BiCMOS



12" CMOS  
and eNVM

## Key Objective

Grow revenues and achieve >10% margin in mid term

### Revenue Drivers

- Continuous expansion of ADAS portfolio
  - Machine vision processor
  - Radar 24GHz, 77GHz
  - Power Management
- Market share gain in 32-bit microcontrollers
- Pervasion of Infotainment
  - Entertainment with Accordo2/5, Tuners, Satellite radio, Digital Audio
  - Telematics with Telemaco, GNSS (Teseo), V2X
- Power and Discrete market share growth
  - Automotive (car electrification driven by SiC, MOSFET)
  - Server farm and industrial applications (35~40V, 700V MOSFET)

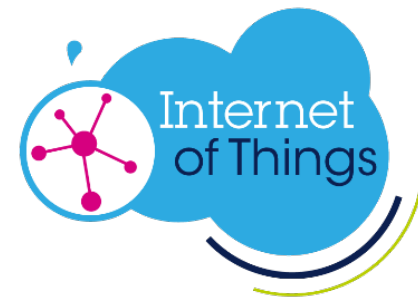
### Operating Margin

- ADAS, Entertainment, Connectivity revenue growth
- Smart Power 110 nm (BCD9)
- New generation 55/40nm 32-bit Microcontrollers replacing oldest generation
- Power and Discrete new product generations
  - SiC
  - STripFET/MDmesh
  - IPAD
- Increase sales in distribution and full system solution in the mass market

- ADG organization creates new opportunities for growth, especially in the automotive market, and cost efficiency across functions
- Three Pillars: Automotive Application Specific products, Multimarket Power Discrete and Protections aligned to Smart Driving and IoT strategy
- Smart Driving
  - Focused on 3 main market drivers (connectivity, safety and green) - can outperform competition by leveraging our digital-power synergy
  - ST's value proposition value has attracted a large and growing network of leading partners among Tier-1's and car makers
- Internet of Things
  - Power Discrete: Differentiated offer vs competition to take leadership in energy conversion efficiency and create stable long term growth drivers.
  - Proving cost effectiveness for SiC, with release to market of SiC product on 6" wafers as a first step
  - Protection & Integrated Passive & Active Devices: Extended sales at customers with complementary functions enabling better system reliability and end product miniaturization



+



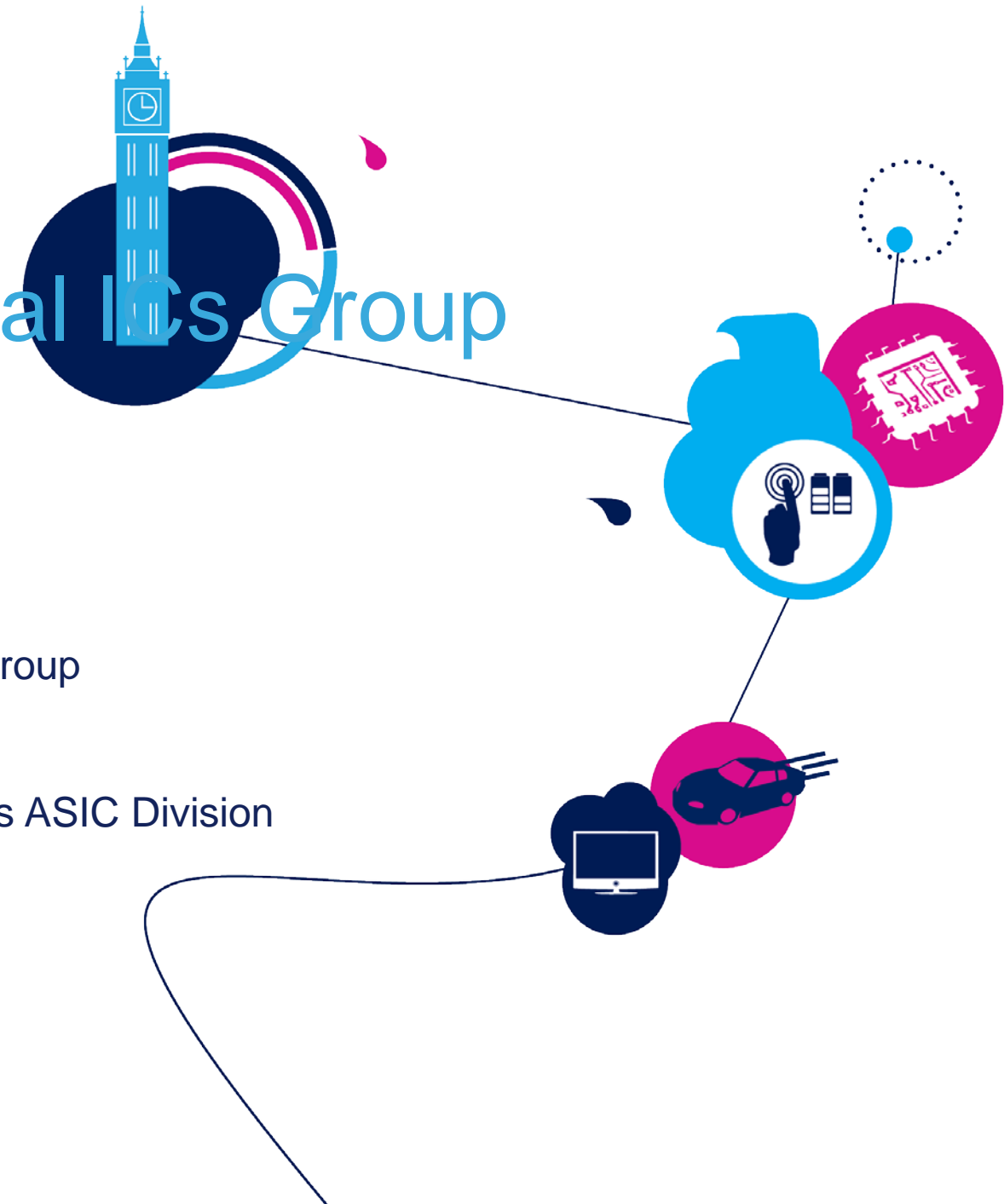
# Microcontrollers and Digital ICs Group (MDG)

**Claude Dardanne**

EVP, General Manager, Microcontroller and Digital ICs Group

**Flavio Benetti**

Group VP, General Manager Digital and Mixed Processes ASIC Division



- General
- Microcontrollers
- Digital & Mixed Signal ASICs
- Takeaways

# Microcontrollers and Digital ICs Group (MDG)

120

## Product Lines



### General Purpose Microcontrollers

- STM32 – 32-bit MCUs
- Ultra-low-power / High performance
- Broad choice of peripherals
- Broadest portfolio
- 10 years longevity for industrial applications



### Secure Microcontrollers

- Mobile Security (SIM, eSIM, NFC ctrl and e-SE)
- Automotive grade Secure MCUs
- Banking, ID and transport
- Authentication for secure IoT & anti-counterfeiting
- Turnkey solutions including certified HW+SW



### Serial & RF Memories & Readers

- High-performance & high-endurance EEPROM
- HF and NFC RFID tags, RF readers
- Advanced packaging options → Wafer Level Chip Scale Package (WLCSP)
- Automotive grade

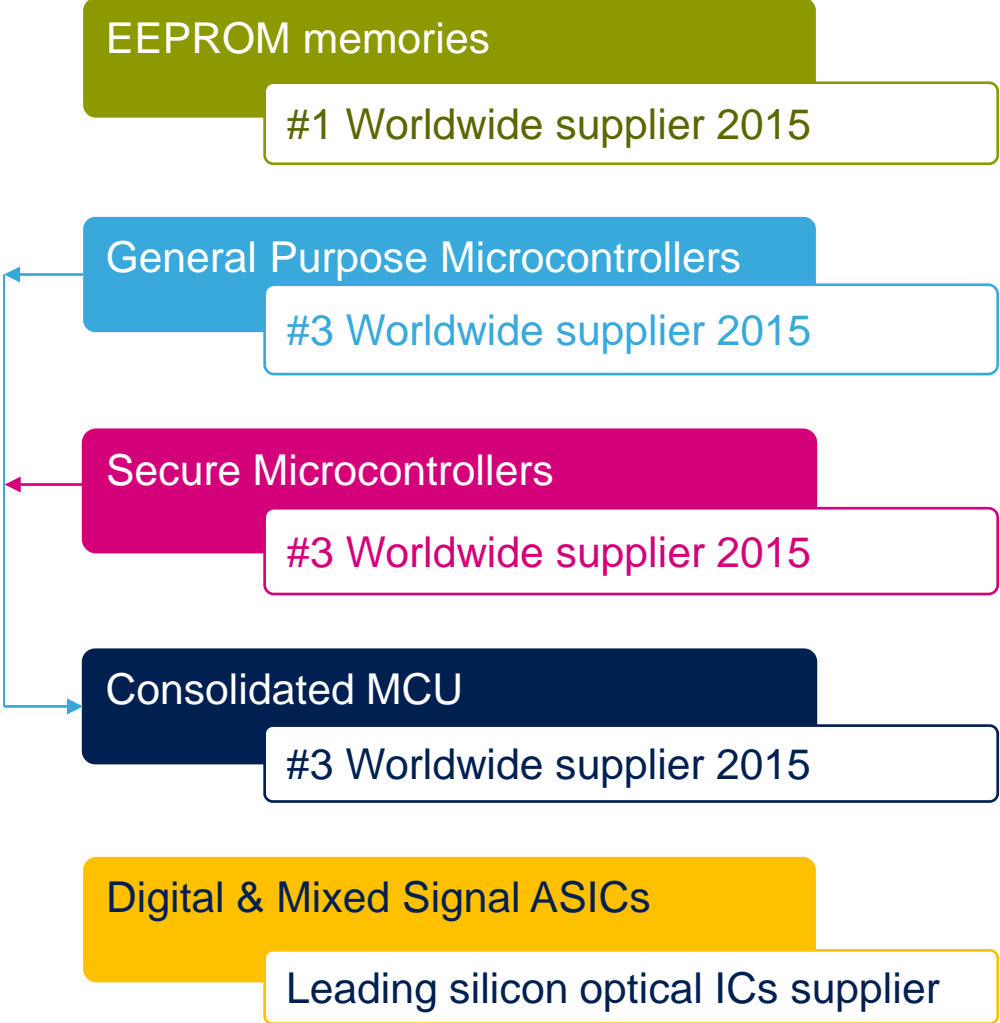


### Digital & Mixed Signal ASICs

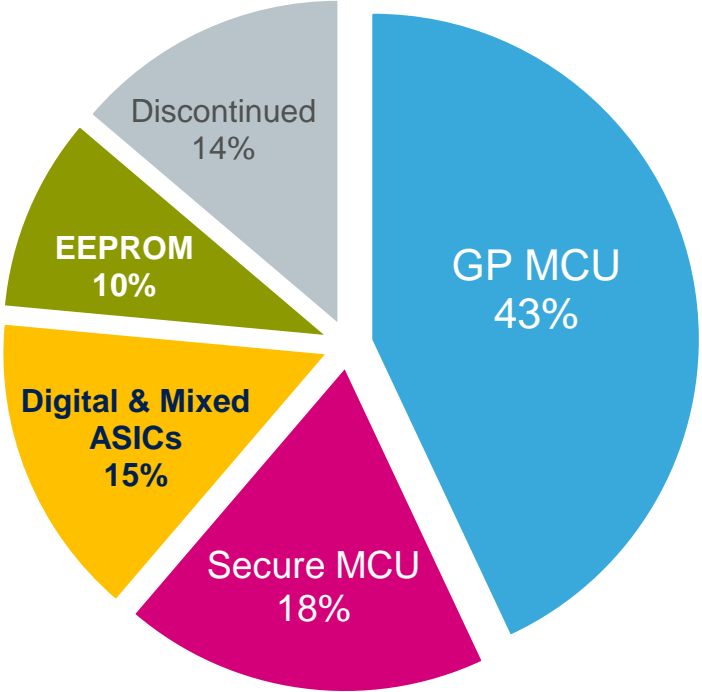
- Electronic & photonics ICs for optical interconnect
- RF-SOI for mobile front end
- RF ICs for base stations and P2P backhaul
- High complexity digital ASICs for networking
- State-of-the-art in house FD-SOI advanced process



# MDG Positioning in 2015



MDG 2015 Business by Activities

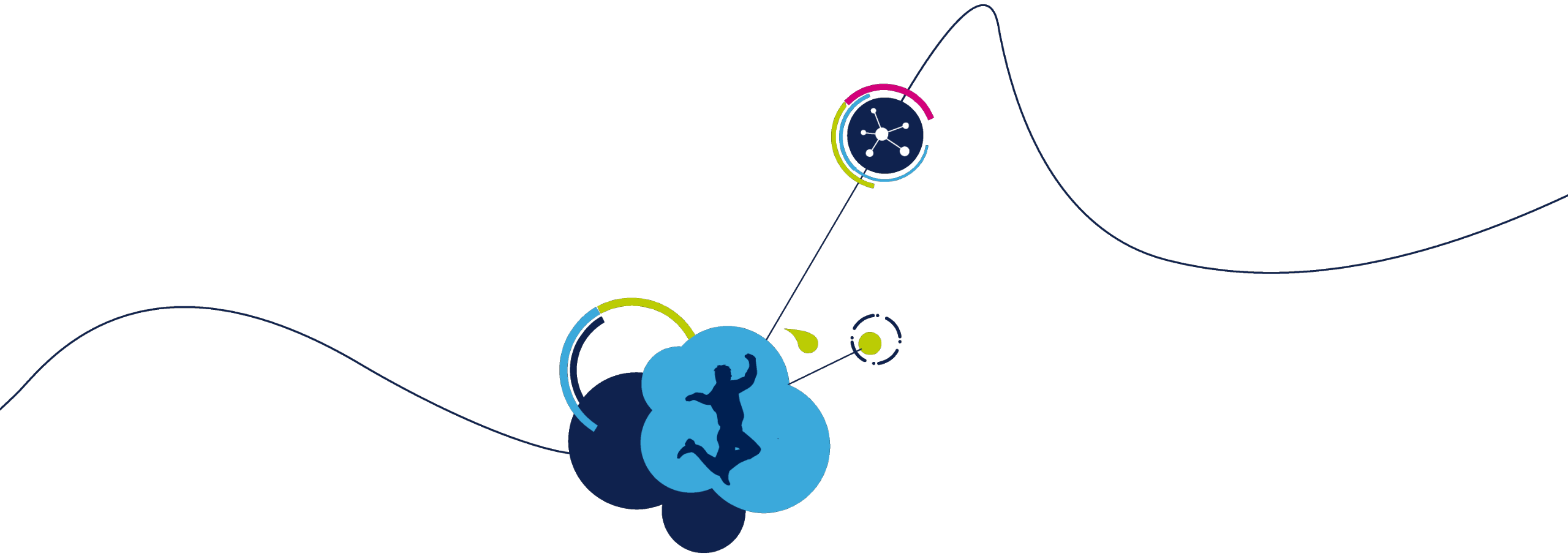


Major growth opportunity :  
General Purpose MCU + Secure MCU

- Discontinued includes business of Set-Top Box & former ST-Ericsson Products
- Microcontrollers excluding Automotive

Source: IHS iSuppli CLT March 21<sup>st</sup> 2016

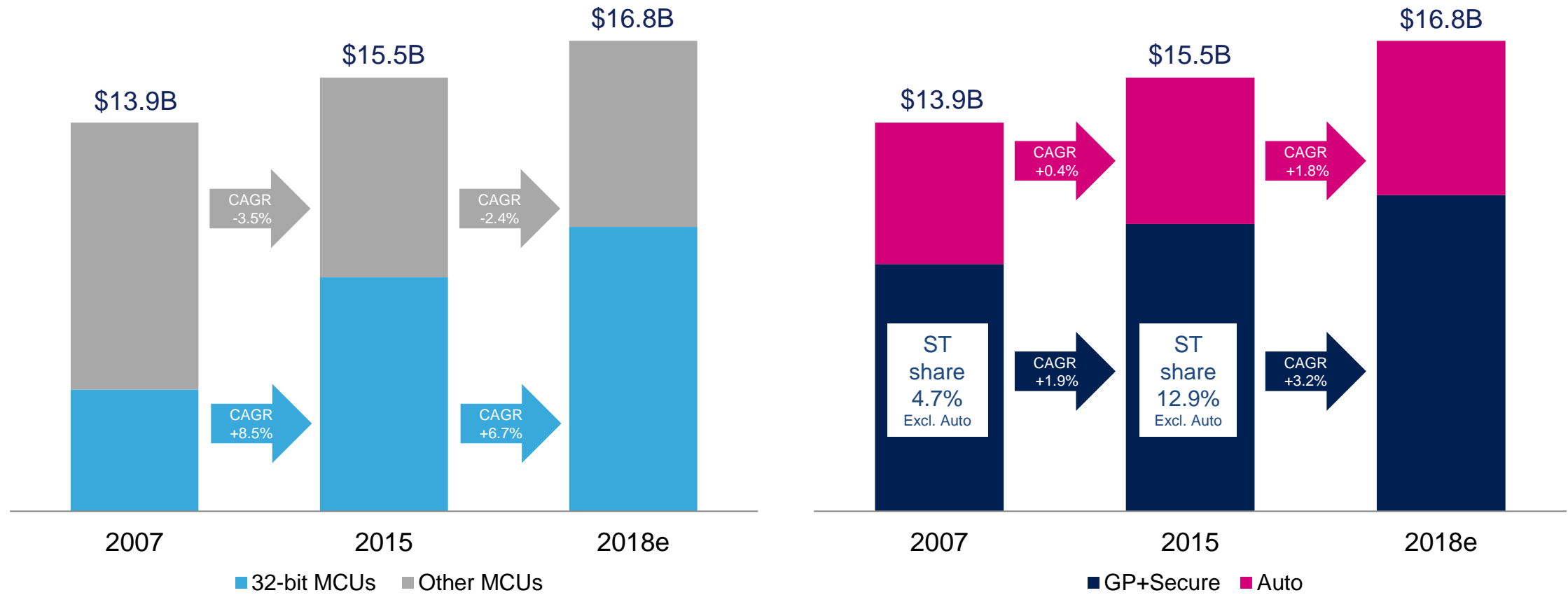




# Microcontrollers

# Microcontrollers Market Trend

Market growth driven by General Purpose & Secure 32-bit microcontrollers → ST Worldwide Leadership



WW MCU TAM (General Purpose + Secure + Automotive)

# GP & Secure MCU Market Trend

Growth driven by IoT deployment

## Market Dynamics

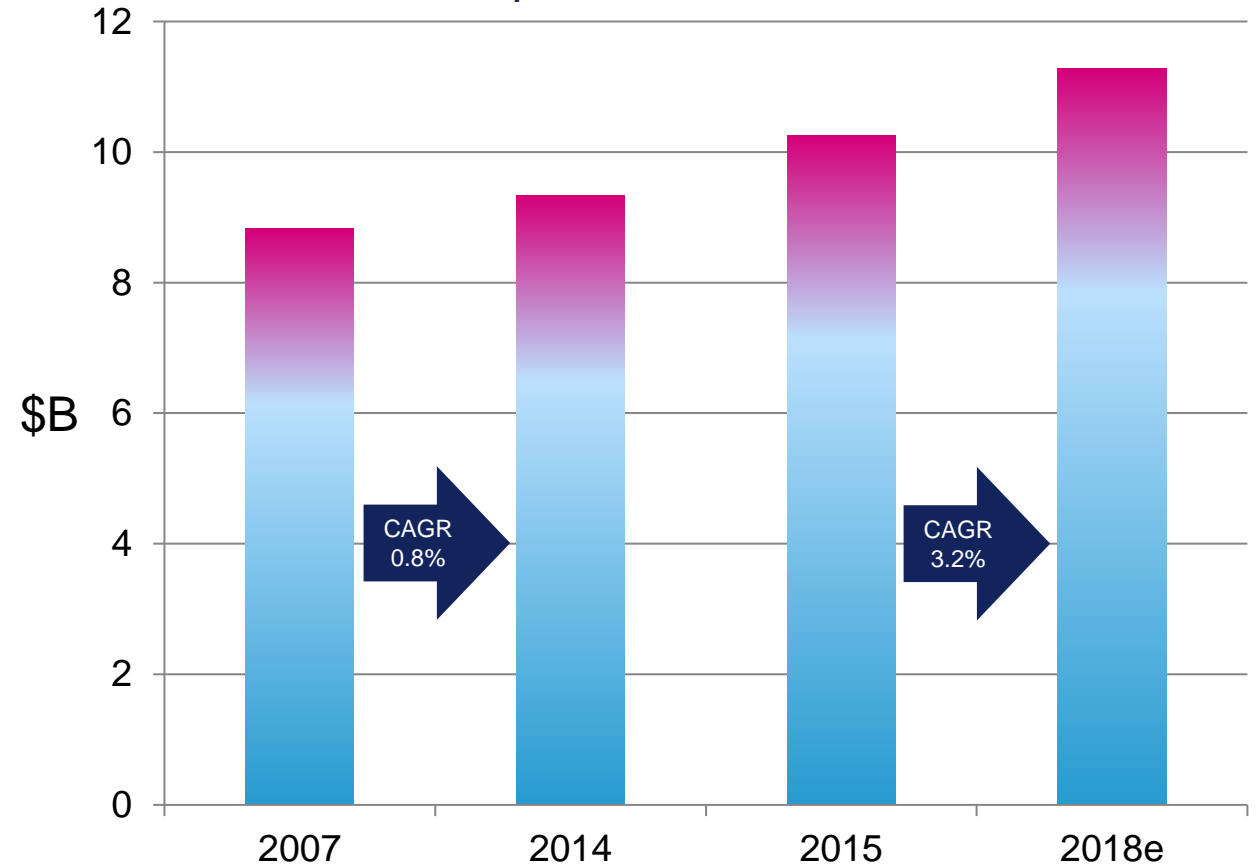
### 2007 – 2014: Limited growth

- General Purpose MCU revenues impacted by \$ ASP trend
  - ✓ 32-bit proliferation
- Secure MCU
  - ✓ Secure Smartcard solutions : Banking, ID
  - ✓ Authentication and IP protection

### 2015 – 2018: Significant growth

- General Purpose Microcontrollers embedding advanced connectivity and security features
  - ✓ Wearables, smart home, smart city ...
- Secure Microcontrollers
  - ✓ Mobile transactions: NFC/Contactless migration...

## General Purpose + Secure MCU TAM\*



\* Excluding Automotive

# General Purpose Microcontrollers

- Addressing multi-application, multi-customer
- STM32 platform with added value

## Performance

- Higher computing power
- Advanced peripherals
- More connectivity & security

## Ultra low power

- Low power consumption
- Optimized functional modes
- Smaller form factor

## Easy development

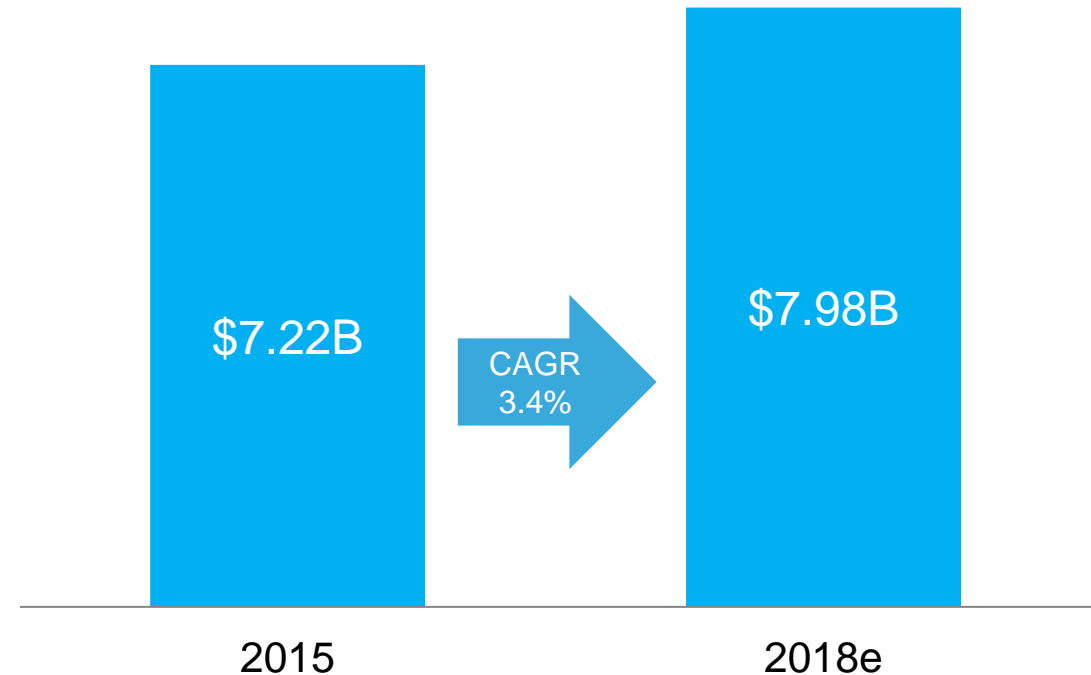
- Extended ecosystem
- Low entry barrier
- Open development environment

## Cost effective

- High level of integration
- Reduced development efforts
- Easy application upgrades

Above features fitting perfectly IoT needs

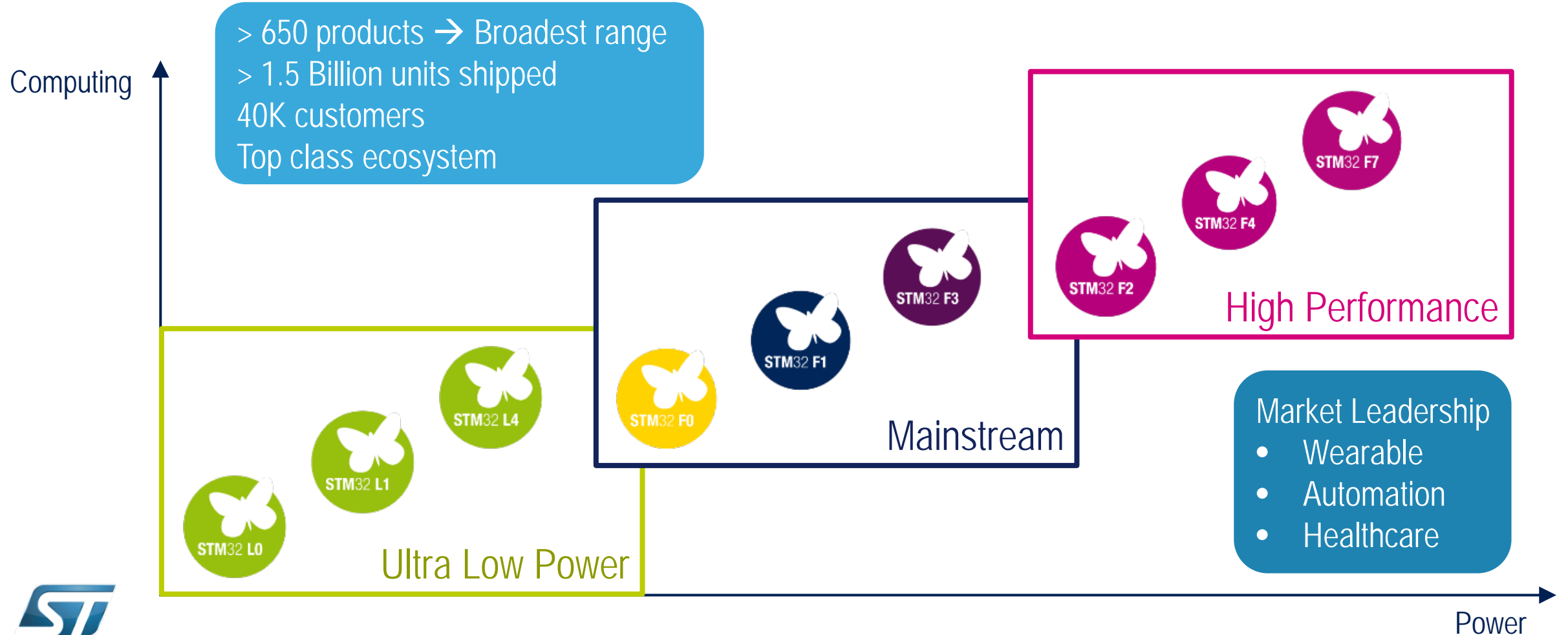
## SAM GP MCUs\*



\* Excluding Automotive

## Advanced 32-bit MCU Portfolio

#1 WW 32-bit Microcontrollers supplier (excluding Automotive)



- Secure Element & Contactless
- ST31 & ST33 platforms with added value

## State-of-the-art security

- Certified HW solutions
- High performance crypto accelerators

## Connectivity

- Best interoperability
- Highest robustness

## Turn-key solutions

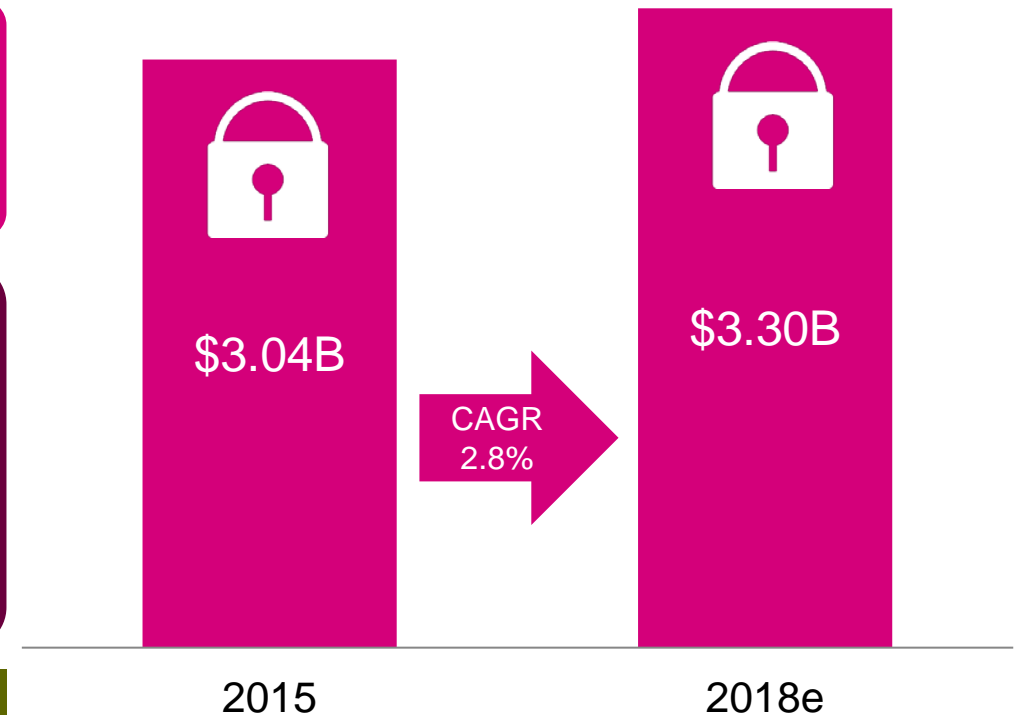
- Certified HW & SW solutions
- Dedicated development tools & support team
- Product customization and personalization services

## Cost effective

- Products based on state-of-the-art Flash process
- Reduced development effort
- Easy application upgrades
- Advanced packaging options

Above features fitting perfectly IoT needs

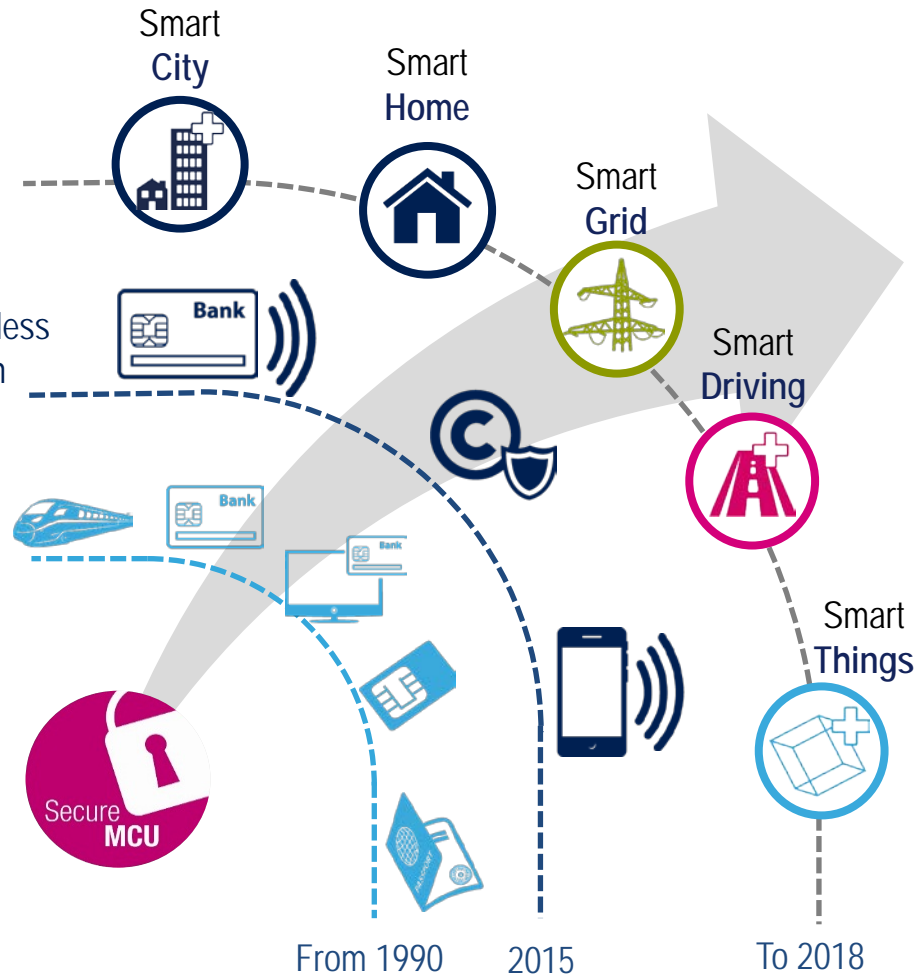
## SAM Secure MCUs



# Market Dynamics Secure MCUs

128

- Authentication
- Healthcare
- Payment
- Fitness
- Banking contactless
- Brand Protection
- NFC – eSE
- Transport
- Banking
- Pay TV
- SIM
- Identification



## ~ 2.8 % CAGR 2015-18

- Growth initially driven by the “Smartcards” business market
- 2<sup>nd</sup> generation addressing contactless payment and mobility as Mobile payment, NFC, M2M
- 3<sup>rd</sup> generation embedding security is emerging in home automation, Trusted Platform, brand protection and all connected devices

## Customers

- Few tens of traditional card makers
- New OEMs require highly secure turnkey solutions (application software in secure hardware platform)
- Mass Market to consider for IoT

## Technology & features drivers

- Strong security (certified and high performances)
- Cost effective solution
- Turnkey solutions
- Secure solution combined with standard MCU



# Complete Secure MCU Portfolio

Turnkey Secure Solution



ST33

Computer Trusted Platform Module Device & accessory authentication consumer brand protection

ST23



Home automation Smart Grid

Turnkey Secure Solution



Banking Identification Transport

ST31 )))

Secure MCU Turnkey Secure Solution



M2M industrial, automotive

Secure MCU

ST33

ST54 )))

NFC Full Solution Controller, Secure Element



Mobile security NFC transactions



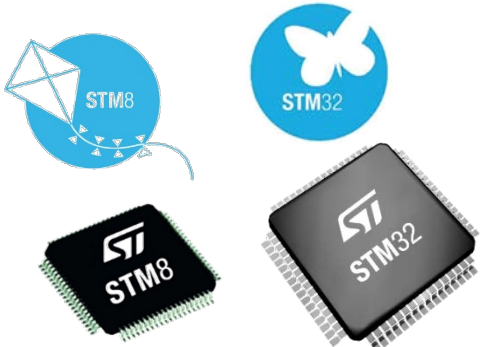
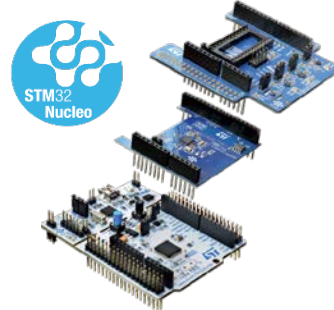




ST33 based on ARM® SC300® Secure CPU core  
ST31 based on ARM® SC000® Secure CPU core

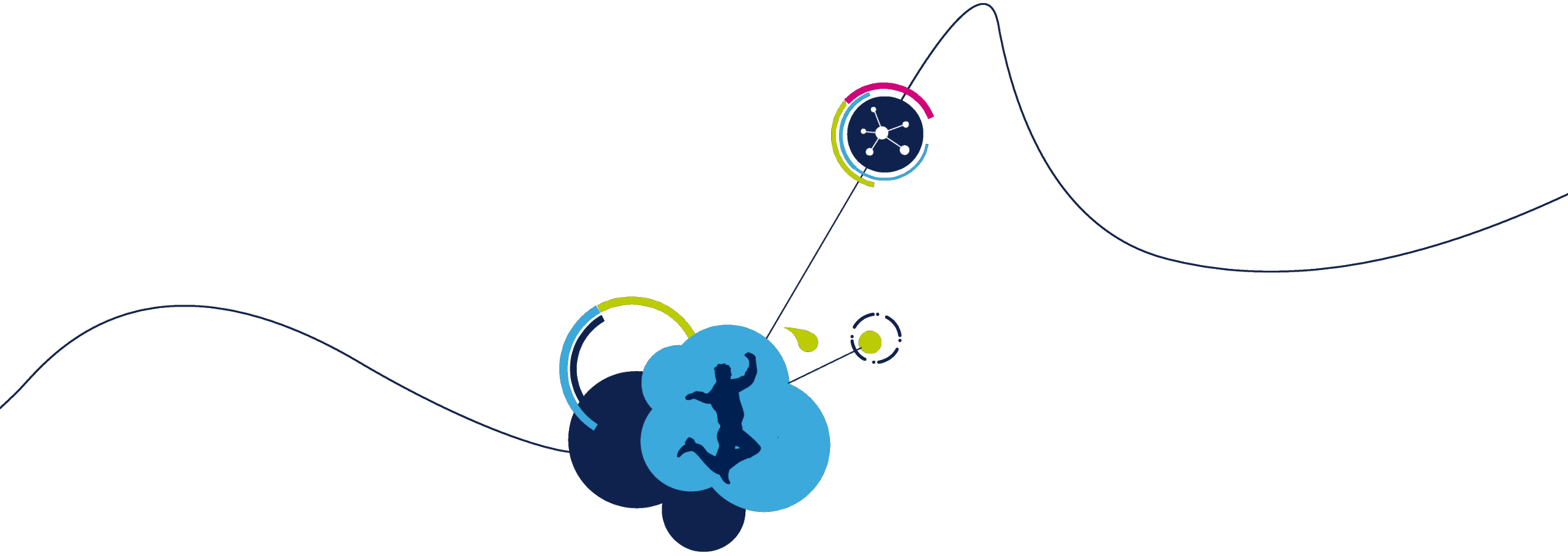
# Products & Tools to match IoT market trends

Market Trends

<b>Smart Things</b> 	<b>Smart Home</b> 	<b>Smart City</b> 	<b>Smart Industry</b> 
Ultra-low power Processing power	Short-range connectivity Advanced peripherals	Long-range connectivity Smart peripherals	Security features and certification

ST Offer

<b>Broad MCU offer</b> 	<b>Accessible ecosystem for application development</b>  <p>STM32 Nucleo expansion boards for connectivity, sensing, actuating</p>  <p>STM32 Nucleo development kits</p>	<b>Secure MCU</b>  <p>Secure MCU</p> <p>STM32</p>
	 <p>Free SW platforms for all OSes</p>  <p>Educational Programs &amp; MOOC</p>	



# Digital

# Digital and Mixed Processes ASICs

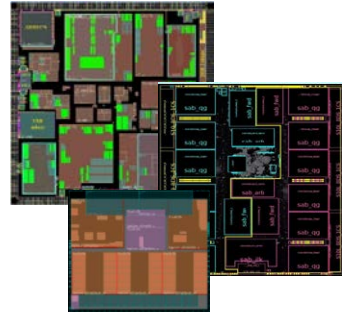
## Market Segments

  
Switching / Routing

  
Networking

  
Consumer

  
IoT



Digital ASICs

Digital & Mixed Processes ASIC

RF Infrastructure

Optical Interconnect

  
4G/5G Base Stations

  
Telecom

  
Data Centers

  
Datacom

# Added Value: The Technologies

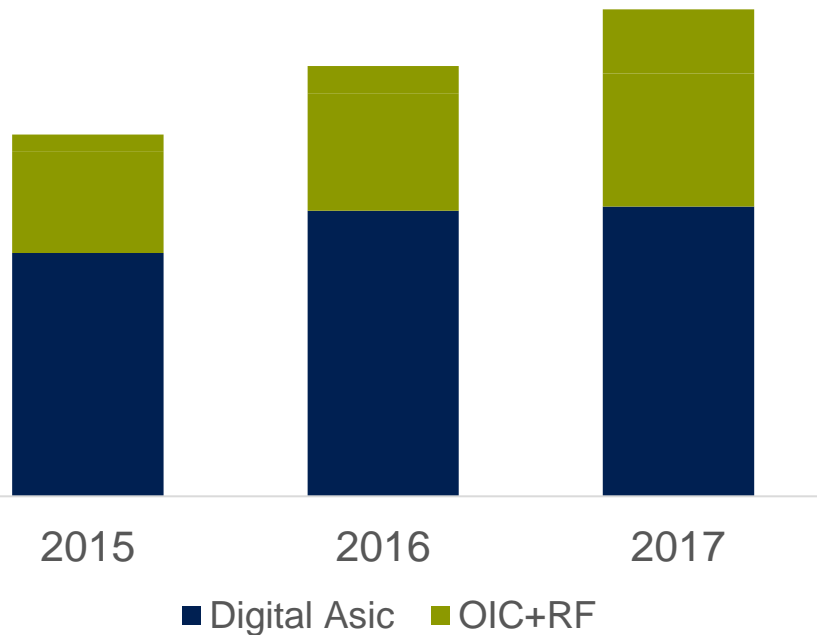


	BiCMOS7/9	BiCMOS55	PIC25	28 FD-SOI
Optical Interconnect	ASIC/COT	ASSP ASIC/COT	ASSP TurnKey	
RF Infrastructure	ASSP ASIC/COT	ASSP ASIC/COT		
Digital ASICs				ASIC

# Revenue Growth Drivers

134

\$M Revenue trend



Infrastructure  
Mobile & data center  
traffic growth

- 100G optical modules volume growth
- Silicon photonics optical engines
- RF mobile FEM and base station synthesizers and transceivers

Increasing  
performance and  
complexity

- Advanced digital ASICs for Terabyte board switching
- Metro and long-haul coherent digital engines
- IoT position trackers

# ICs for Optical Interconnect

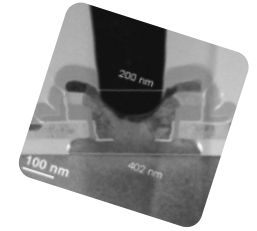
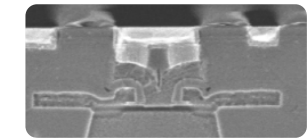
- ST continue to be leading supplier of ICs for optical modules
  - ~300M modules powered by ST BiCMOS technologies in the field today
  - Solid revenue growth continues enabling broad range of applications 10Gbps, 25Gbps, 40Gbps, 100Gbps / SR, LR and Parallel Optics
  - Serving the leaders in the market
  - BiCMOS55 gaining strong market traction
- Enabling the market with
  - ASIC/COT model with BiCMOS technologies
  - ASSP products for 10G Transceiver and CDR
  - ASSP in Silicon Photonics technology domain



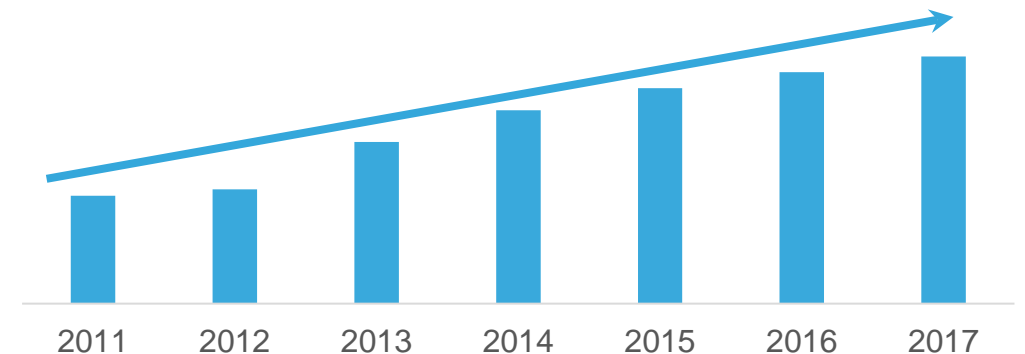
**BiCMOS55**  
55nm CMOS  
SiGe-C HBT  
 $f_T > 300$  GHz  
 $f_{MAX} > 400$  GHz

**BICMOS9MW**  
0.13 $\mu$ m CMOS  
SiGe-C HBT  
 $f_T = 220$  GHz  
 $f_{MAX} = 280$  GHz

**BICMOS9**  
0.13 $\mu$ m CMOS  
SiGe-C HBT  
 $f_T = 160$  GHz  
 $f_{MAX} = 160$  GHz



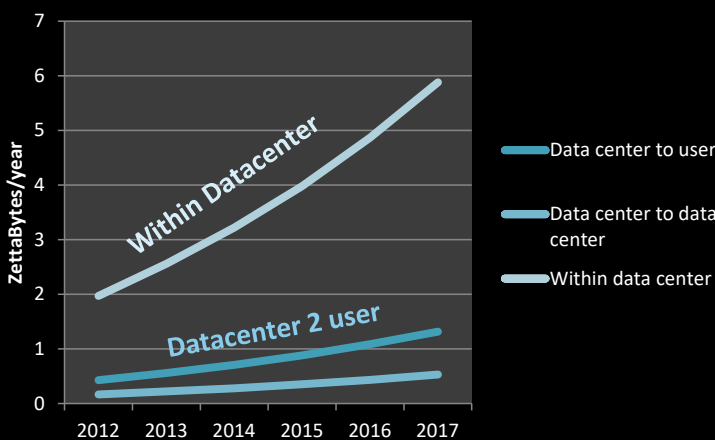
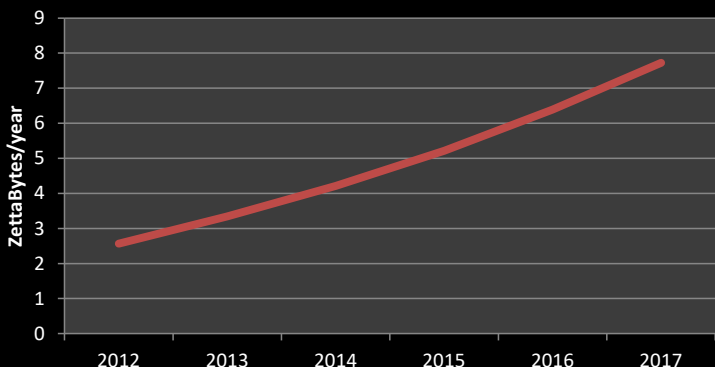
Revenue trend  
CAGR 14%



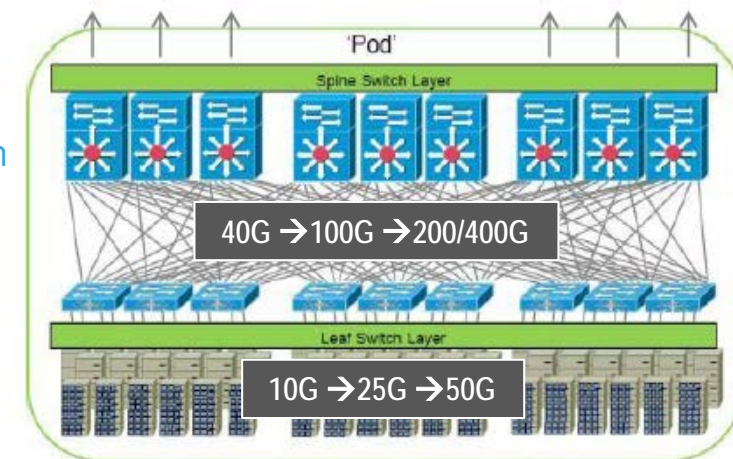
# Hyperscale Data Centers the growth driver

Global Traffic is doubling every 3 years

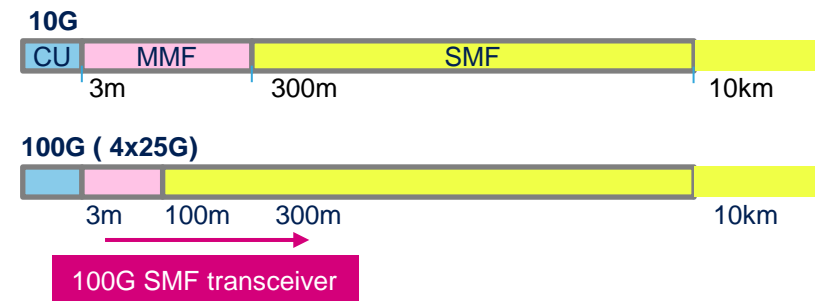
Total data center traffic



- The explosive traffic growth requires bandwidth
  - Server to TopOfRack 10G → **25G** ; distance: <5m
  - Switch to Switch 40G → **100G** ; distance: 85%<500m



- From Multi Mode Fiber interconnect to 100G Transceiver over Single Mode Fiber
  - 100G SR4, VCSEL reach its limit to <100m, not suitable for 100G Switch to Switch links
  - New MSA solutions introduced :
    - PSM4 over parallel SMF @500m
    - CWDM4/CL4 over duplex SMF @2km



- Single Mode Fiber infrastructure is the choice in all Data Center**
  - 100G → 200G → 400G keeping same optical network infrastructure



# Integrated Si Photonics Optical Engine

from development to prototype

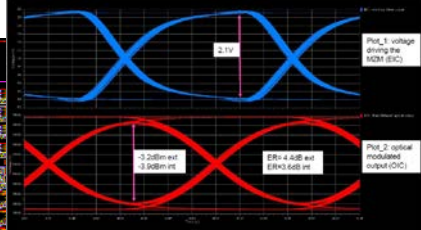
Crolles 200 and 300mm Wafer Fab



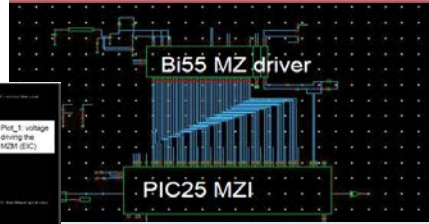
Inline photonics test bench



CAD simulation



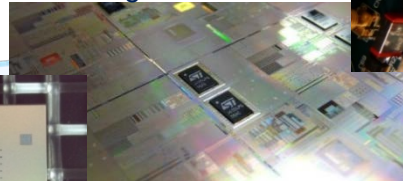
Schematic Capture



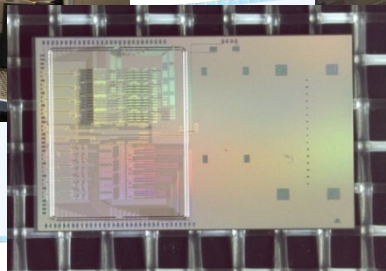
Integrated 3D Optical Engine



Chip on Wafer Bonding



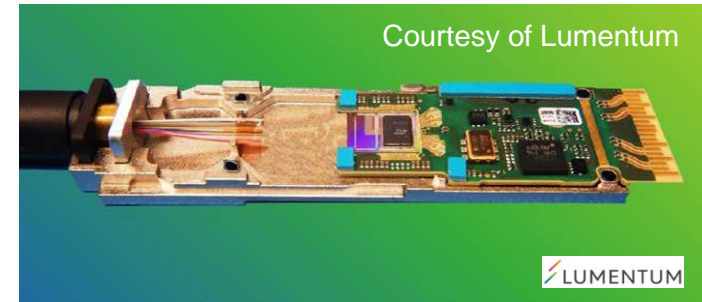
Electro Optical Wafer Sort

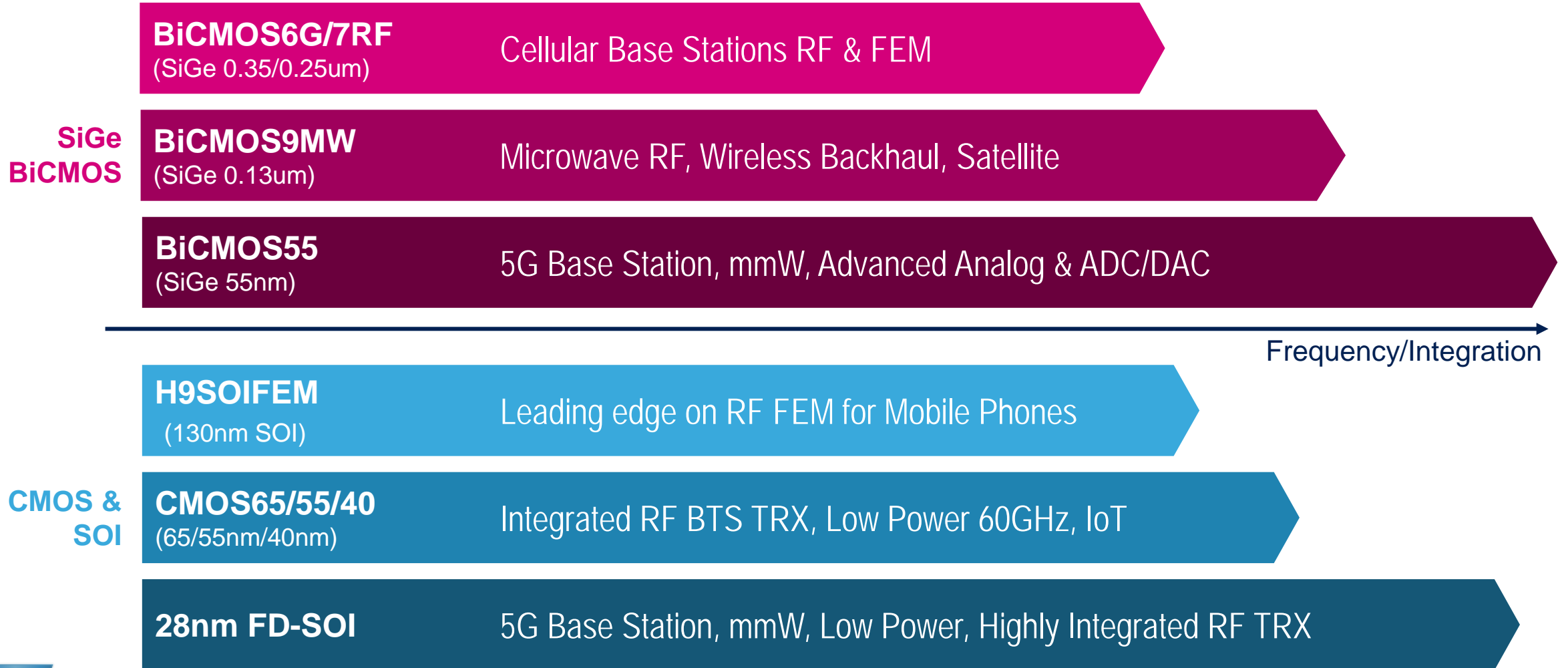


Optical Die

- Silicon Photonics integrated technology is today a reality. It is ramping production in H216
- Use of Silicon Photonics based optical engine in 100G QSP28 shows an outstanding Bill of Materials reduction and assembly ease
- The best way for optical modules to get close to the targets data center applications are looking for

Courtesy of Lumentum





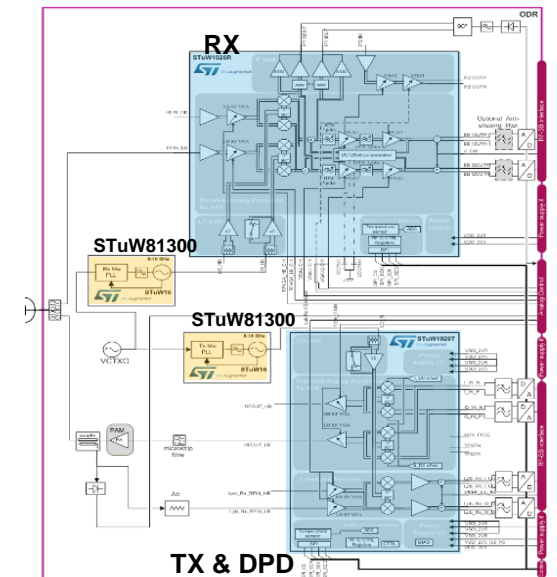
# Microwave Transceiver in BiCMOS

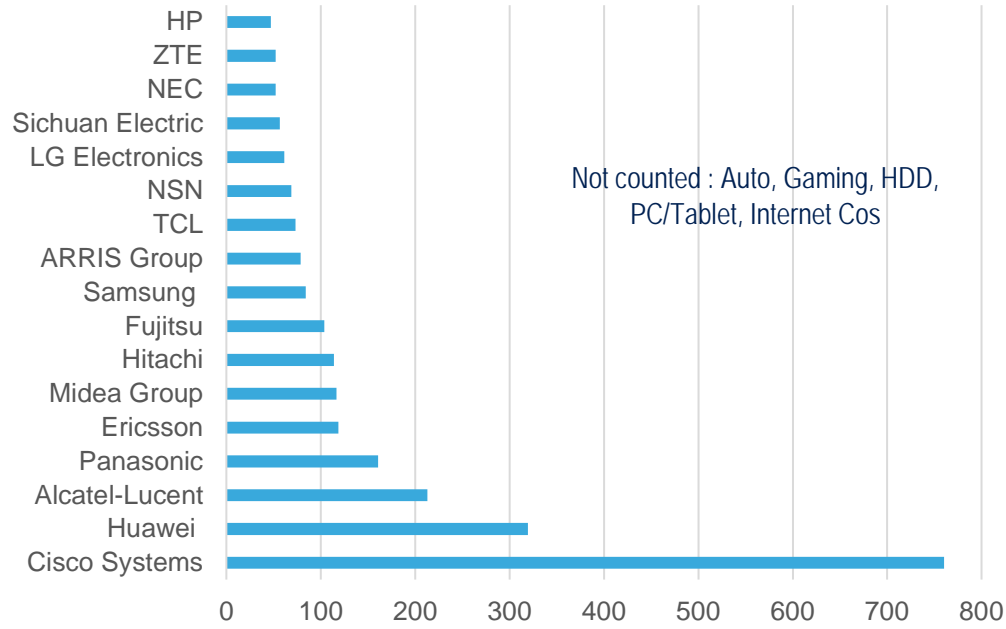
Integrated, cost optimized solution for P2P radio link

STuW1026 10-26GHz integrated transceiver  
STu81300 synthesizer

- Point-to-Point microwave bands
- Targeting direct conversion architecture
- Full outdoor and split mount radios
- Support for super-heterodyne mode
- Supports up to 4096-QAM and 112MHz channel bandwidth

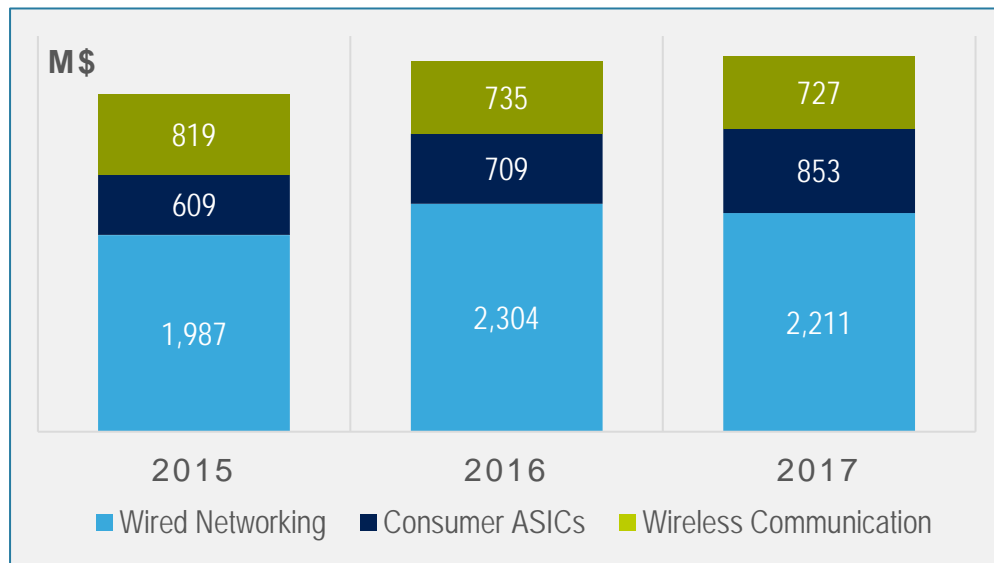
**An ST ASSP system kit fully based on ST BiCMOS9MW and BiCMOS55 technology**





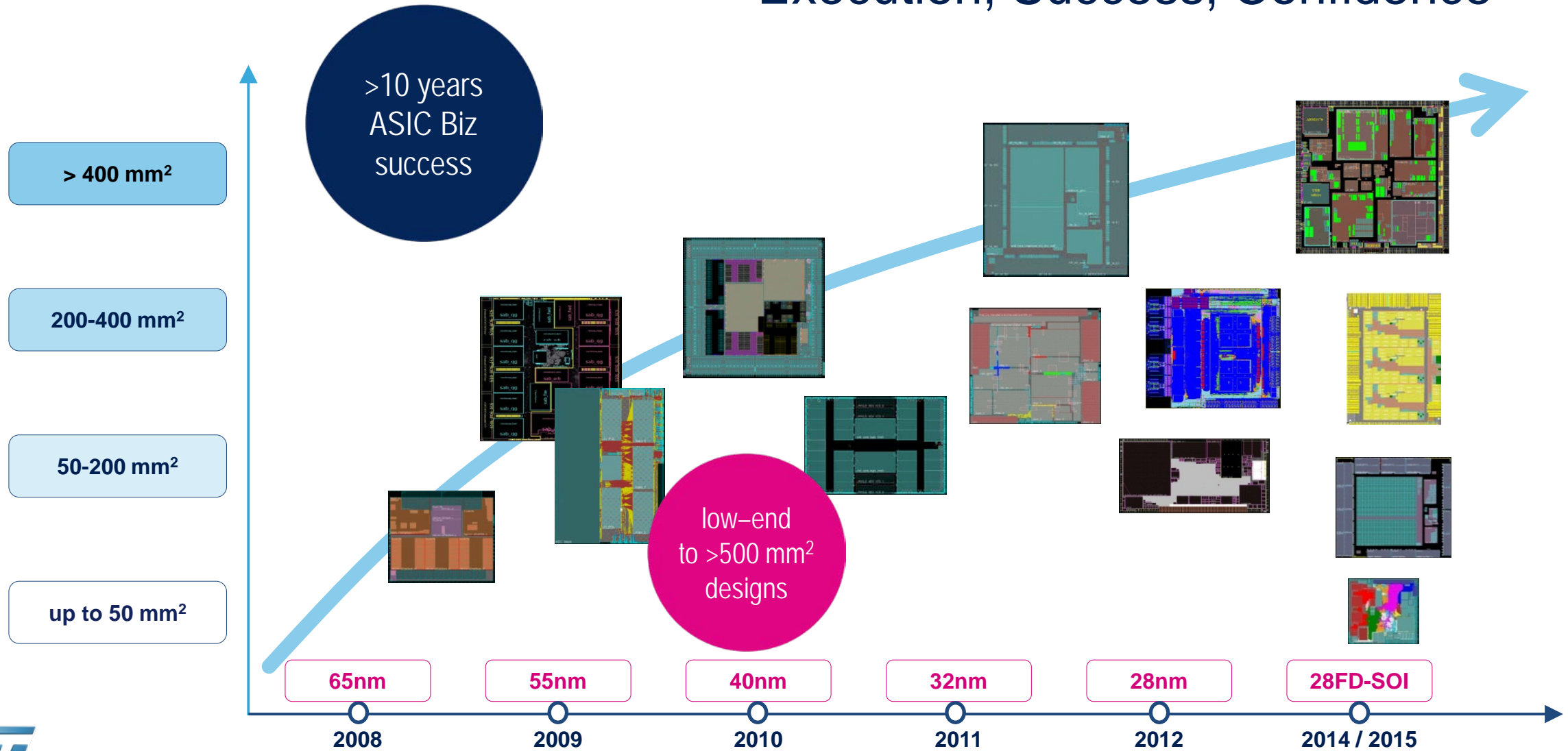
## Competitiveness in Networking ASICs market is driven by:

- Ability to integrate ASICs with die size exceeding 300mm<sup>2</sup>
- SerDes availability to allow switching bandwidth up to terabyte throughput.  
Very high count of SerDes at speed up to 56Gbps
- Ability to design advanced packaging with ball count in the range of thousands also managing high power consumption in the range of 100W and more
- Fast prototyping cycle times and complex supply chain management

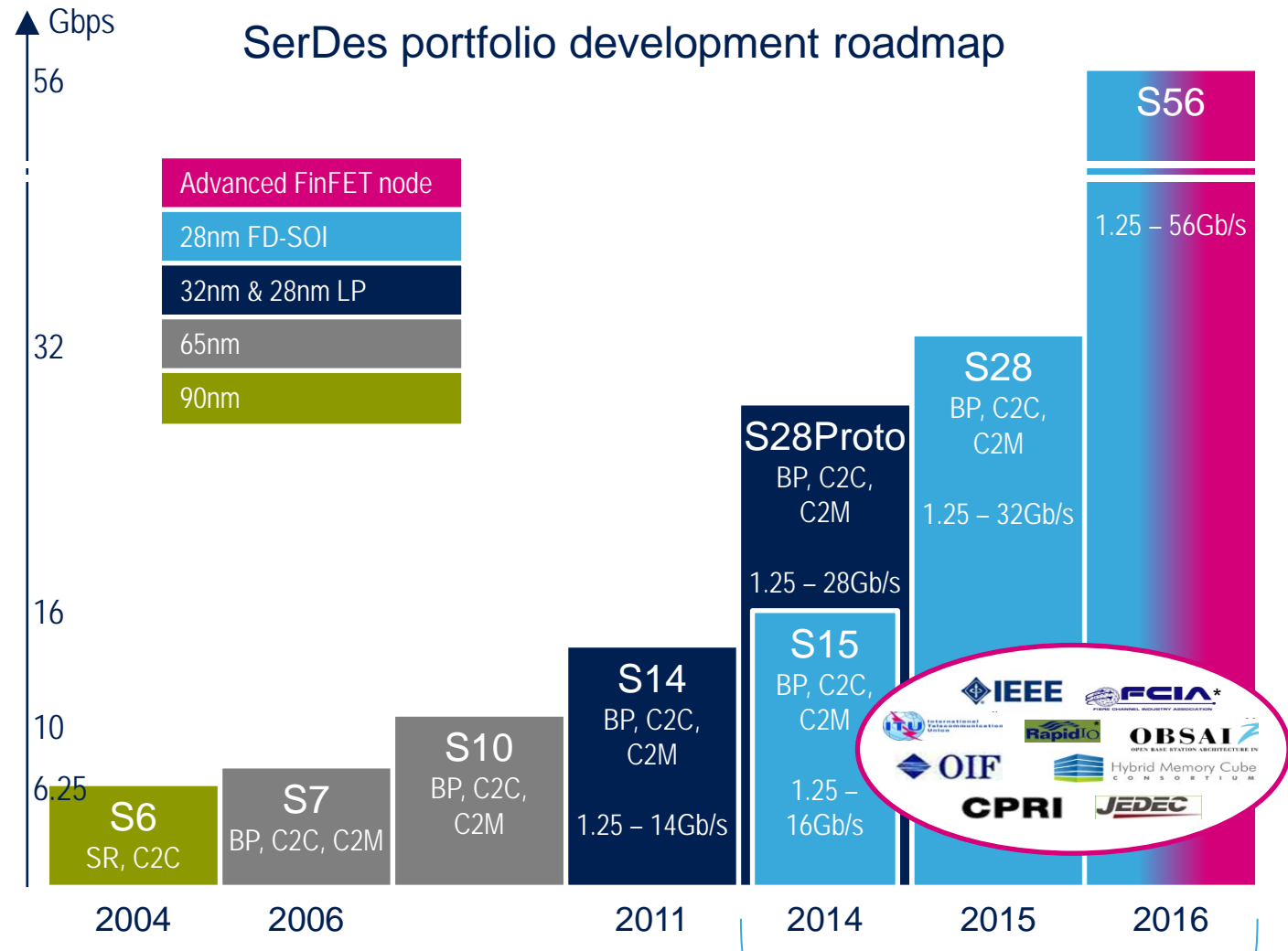


# Advanced CMOS ASICs

## Execution, Success, Confidence

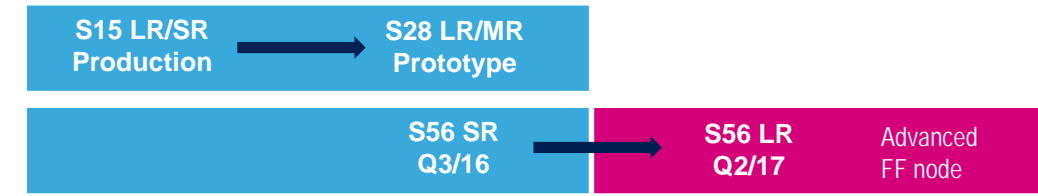


SerDes portfolio development roadmap



## ST Networking IP

- Broad variety of SerDes up to 28Gbps (available now) and 56Gbps prototype in Q3/16
- DDR 2/3 and 3/4
- USB2 and USB3
- PCIe, SATA and Ethernet
- ARM 32-bit and 64-bit processor family
- ADC/DAC
- TCAM
- UHS SRAM



## Key Objective

Grow revenues and achieve >10% margin in mid term

### Revenue Drivers

- Leverage on technology leadership in eNVM, FD-SOI and RF
- General Purpose STM32 MCU
- Advanced Secure Element
- Secure contactless: banking / ID
- RF EEPROM
- Digital ASICs on FD-SOI
- Optical module ICs leveraging Silicon Photonics and BiCMOS

### Operating Margin

- Leverage on revenue growth
- Technology mix in Crolles 12" (eNVM)
- 8" to 12" products evolution
- Assembly cost and yields
- Value-add and differentiated new products
- Low margin discontinued products (Set-Top-Box)
- Execution of Set-Top Box restructuring
- Favorable currency effects

## MICROCONTROLLERS

- Pursue double digit-profitable growth and market share gain capitalizing on solid foundation
- Maintain worldwide 32-bit platform leadership
  - General Purpose MCU
  - Secure Element
- Capitalize on application & system knowledge
  - Reinforce & proliferate advanced connectivity solutions
  - Deploy secure software solutions
- Address the microprocessor market to complete our offer
- Drive evolution of IoT market embedding more connectivity and security on top of General Purpose MCU

## DIGITAL

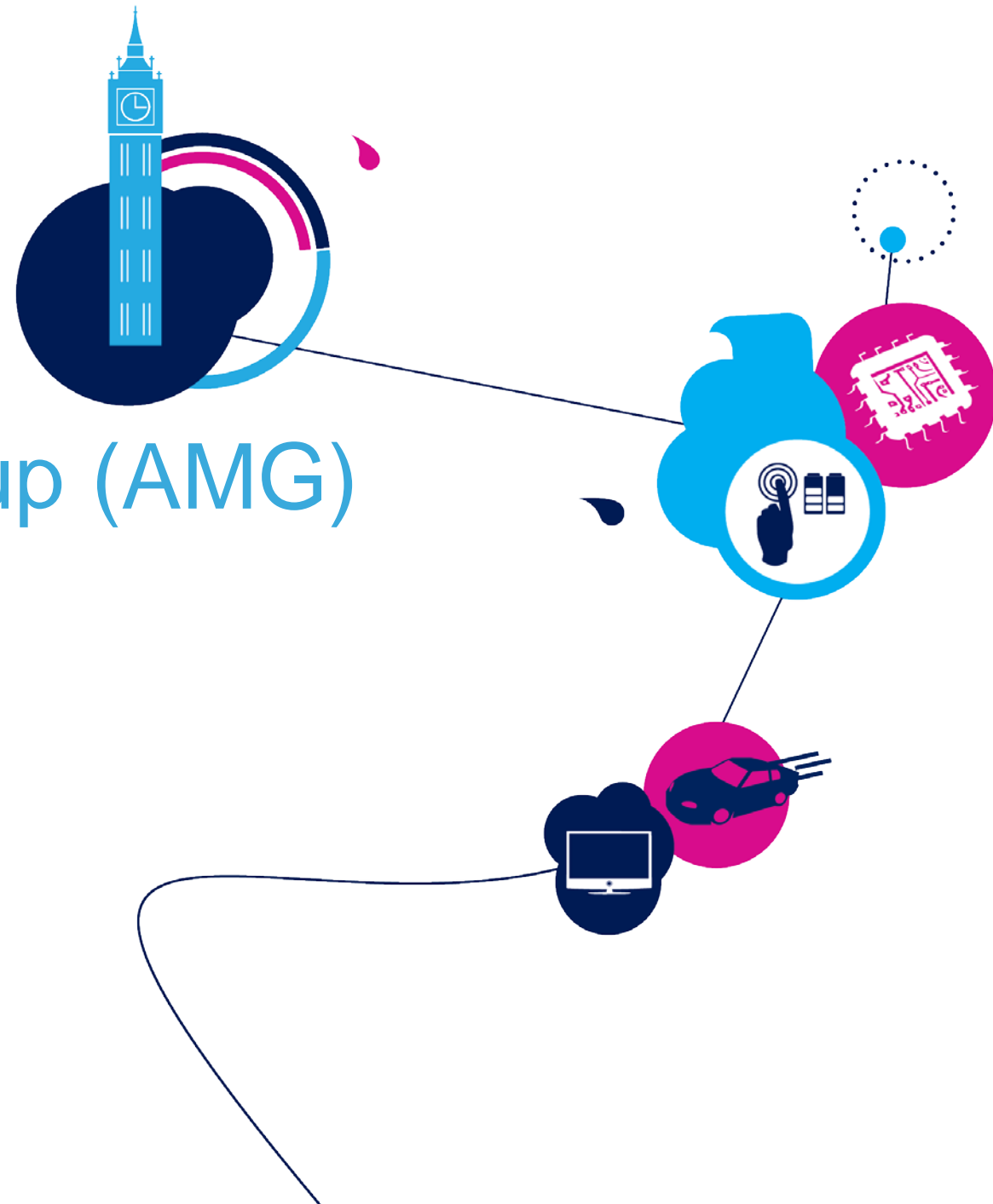
- Accelerate current redeployment to secure profitability ASAP
- Secure Set-Top-Box plan execution
- Capitalize on advanced in-house BiCMOS technology to address the market drivers able to generate significant business growth
  - Data center traffic
  - Mobile infrastructure
- Focus on optical interconnect ICs
- Capitalize on state-of-the-art in house FD-SOI advanced process
- Focus on advanced Digital ASICs dedicated to Networking solutions



# Analog and MEMS Group (AMG)

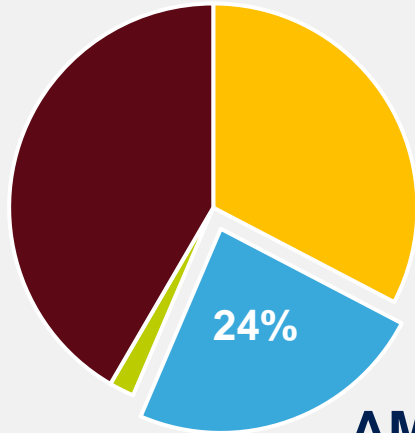
**Benedetto Vigna**

Executive Vice President  
General Manager, Analog and MEMS Group



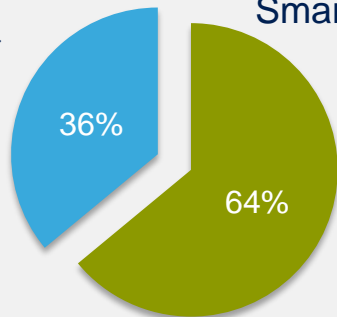
# Analog and MEMS Group (AMG)

### Contribution to ST revenues 2015



### AMG

#### Sensors & Actuators



#### Analog and Smart Power

### Sensors and Actuators

Motion Sensors

Environmental Sensors

Microphones

Actuators

Sensor Hub & Sensor Fusion

### Portfolio

### Analog and Smart Power

#### Industrial

Motion Control ICs

Industrial Analog ASSP

Energy Management ICs

Digital Power Conversion ICs

AC-DC Power Supply

Lighting ICs

#### Custom Analog

PMIC for Data Storage & Server

Portable Power management

#### General Purpose Analog

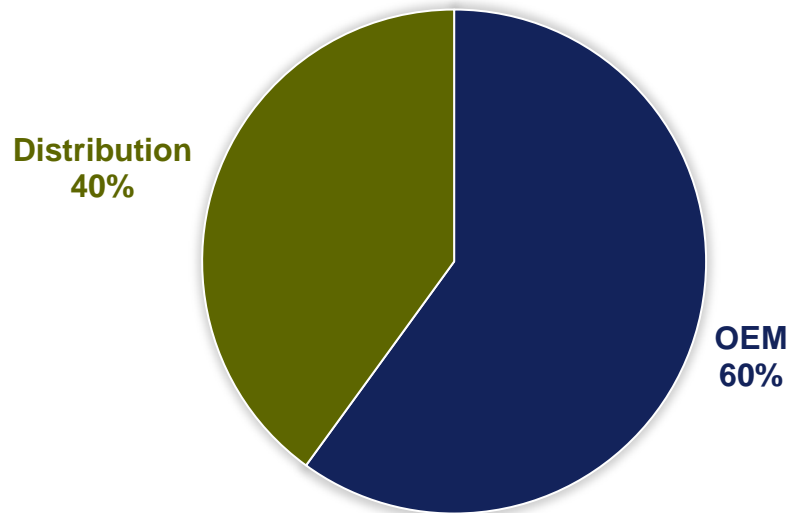
Analog Front-End

RF ICs

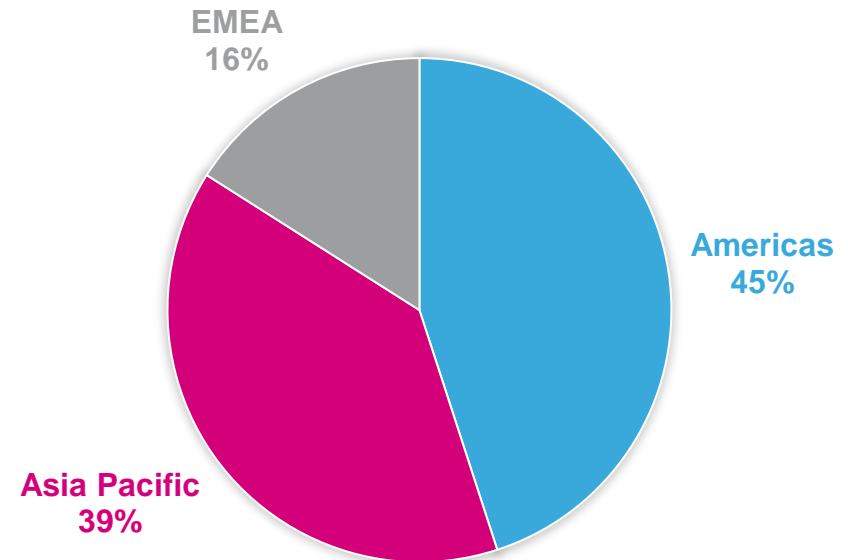
# A Broad and Diversified Customer Base

Well balanced across customer types and markets

2015 Revenue by customer type



2015 Revenue by region of origin



24% of ST Revenues in 2015

- More than 5200 available products

## Leadership Areas

# 1 in MEMS Sensors for Consumer and Mobile

# 1 in AMOLED Display Power Supply

# 1 PMIC for Data Storage

# 1 in Power Line Modem for Smart Metering

# 2 in MEMS Micro-Actuators

# 2 in LED Driver ICs

# 3 in Industrial Analog ASIC and ASSP

## Innovation driven

- **More than a quarter** of sales with products < 2 years old
- **124** new patents filed in 2015
- **220** patents granted in 2015
- **> 134** new silicon lines introduced in 2015

## Broad product portfolio

- Focus on high-end analog
- Sensors and actuators, power management, wireless connectivity
- Ultra-low power, highest accuracy, sensitivity and integration
- Best-in-class product for leading OEMs

## Established worldwide ecosystem for mass market

- Strong system **know-how** to support a global **customer base**
- **> 400** evaluation boards and associated development tools
- **> 1200** software evaluation licenses distributed in the last 6 months

## What did not go to plan

- Intense price pressure in consumer MEMS sensors
- Loss of touchscreen controller in a flagship phone
- Loss of microphone revenues due to:
  - ✓ subcontractor issue
  - ✓ demand reduction
- Hard-disk drive market dynamics

## Where we made progress

2012 Diversification strategy started to yield results:

- Reshaped motion MEMS product portfolio
- Strong growth and key design wins in automotive and industrial
- Continued traction in piezo micro-actuators
- Start of volume sales for low-power connectivity in wearables and smart home

# AMG Turnaround Strategy

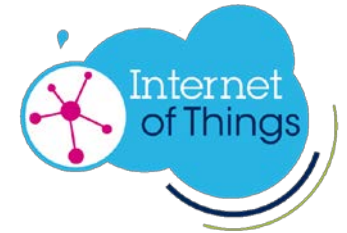
150

## Key Objective

Revenue growth and mid to high single digit operating margin in mid term

## Actions

- **MEMS sensors and micro actuators – Maintain volumes while diversifying**
  - Maintain volumes on consumer MEMS (motion, microphones and environmental)
  - Expand in Automotive (motion and microphones) and industrial MEMS (motion and environmental)
  - Grow in micro-actuators (Piezo)
- **General purpose Analog – Grow market share**
  - Additional Sales & Marketing initiatives with aggressive goals targeting the mass market
  - New dedicated organization to increase focus
- **Dedicated Analog products - focus on Smart Meter solutions, Power Management ICs and AMOLED**



Smart  
Industry

Smart  
City

Smart  
Home

Smart  
Things



IoT applications are changing the way we work and live by saving time and resources, and opening new opportunities for growth, innovation and knowledge creation



## Smart Industry

Factory Automation  
Motion Control  
Industrial Robots  
Industrial Lighting



## Smart Home

Home & Building  
Automation  
Smart Appliances  
Smart LED Lighting  
Heating & Energy Control  
Security System



## Smart City

Traffic control  
Smart Transportation  
Smart Metering  
Street Lighting



## Smart Things

Wearable  
Smartphones  
Tablets  
Smart consumer

Shaping our future with analog, sensors, smart power and connectivity to drive the evolution of IoT



# Smart Industry Success Stories

## Standardized production environments

# SIEMENS

Factory Automation  
Motion Control  
Smart Industrial Meter  
Industrial Power Supply



- Processing ICs
- Communication ICs
- Power Management



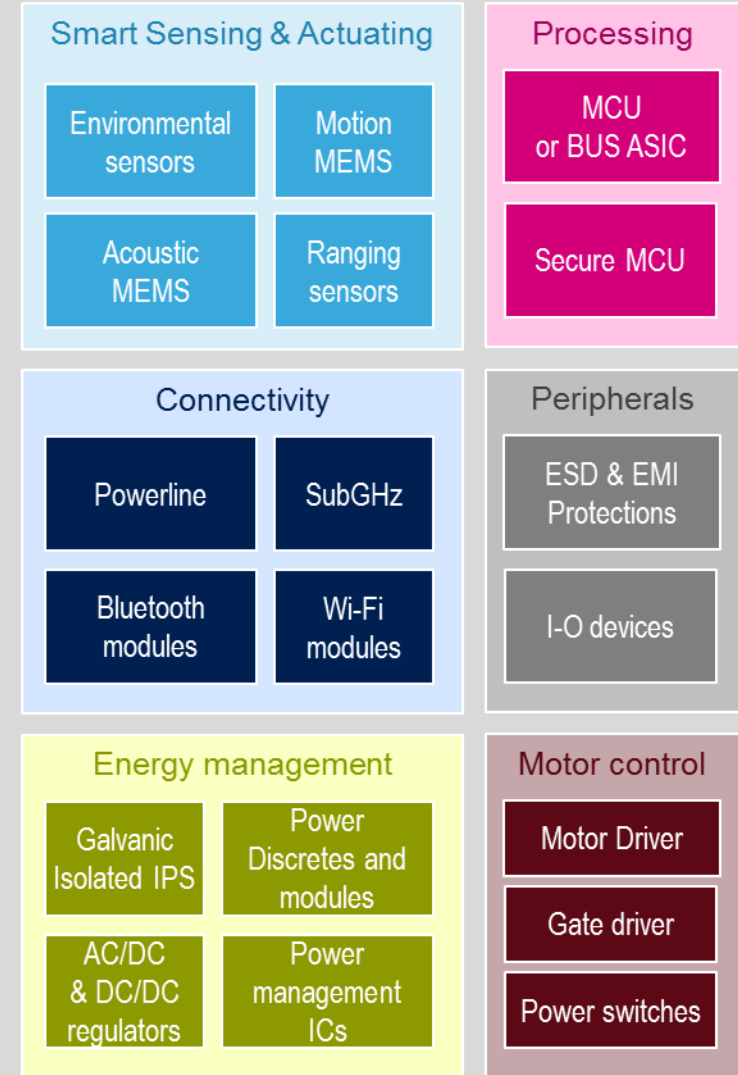
# PHOENIX CONTACT

Programmable Logic Controller

- Fast
- Robust
- Easy



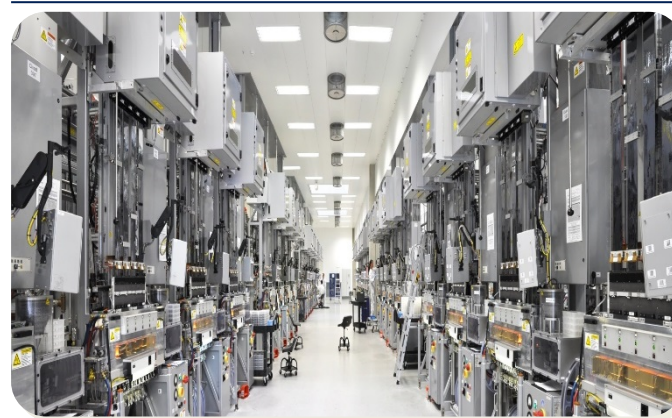
- Processing ICs
- Peripheral ICs
- Communication ICs



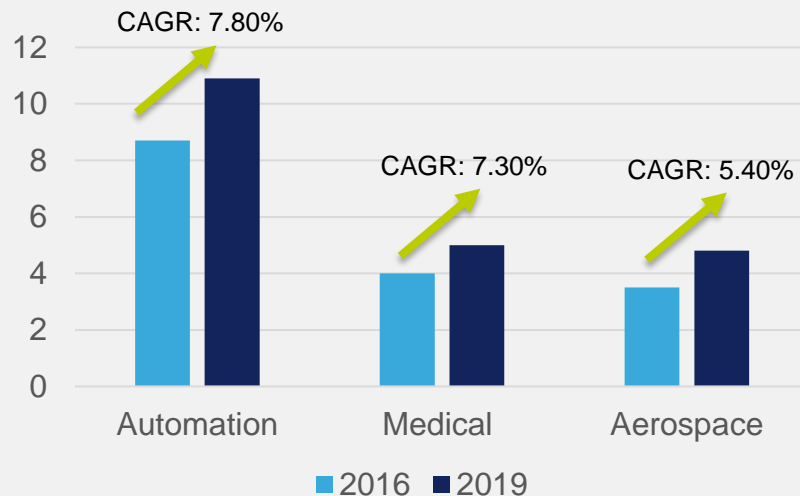


Smarter, safer and more efficient factories and workplaces

### Key Applications



### Market ST SAM \$B



### Key Enabling Products and Technologies

- BCD with Galvanic Isolation
- Real-time Communications & Interface

### Market Leading positions

- Motor Control ICs
- Industrial Analog ASIC

### Key success factors

- Wide range of Industrial protocols supported
- Safety-relevant protocol support
- Advanced motion control know-how

Factory Automation

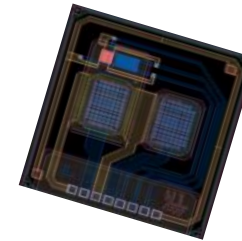
Industrial Robots

Industrial Lighting

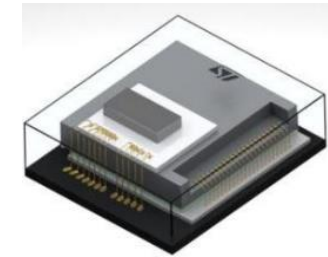
Smarter, safer and more efficient factories and workplaces

### Sensors and Analog Front End

Industrial **sensors** to monitor process variables (proximity, level, flow, pressure, temperature)



Environmental Sensors



Motion MEMS (Inertial Motion Unit)

### Real-time Communication

Wired real-time Communication for control and safety multi-standard and **galvanic isolation** (4 kV, 6 kV and 10 kV)



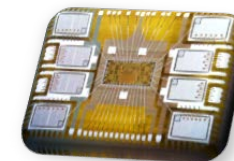
 **IO-Link**



Intelligent power switch  
with galvanic isolation

### Motion Control

Modular, scalable and robust **motor solutions** covering wide operating voltage, current and temperature ranges for industrial applications



STPower System-in-Package  
Motor driver



Galvanically isolated  
gate driver

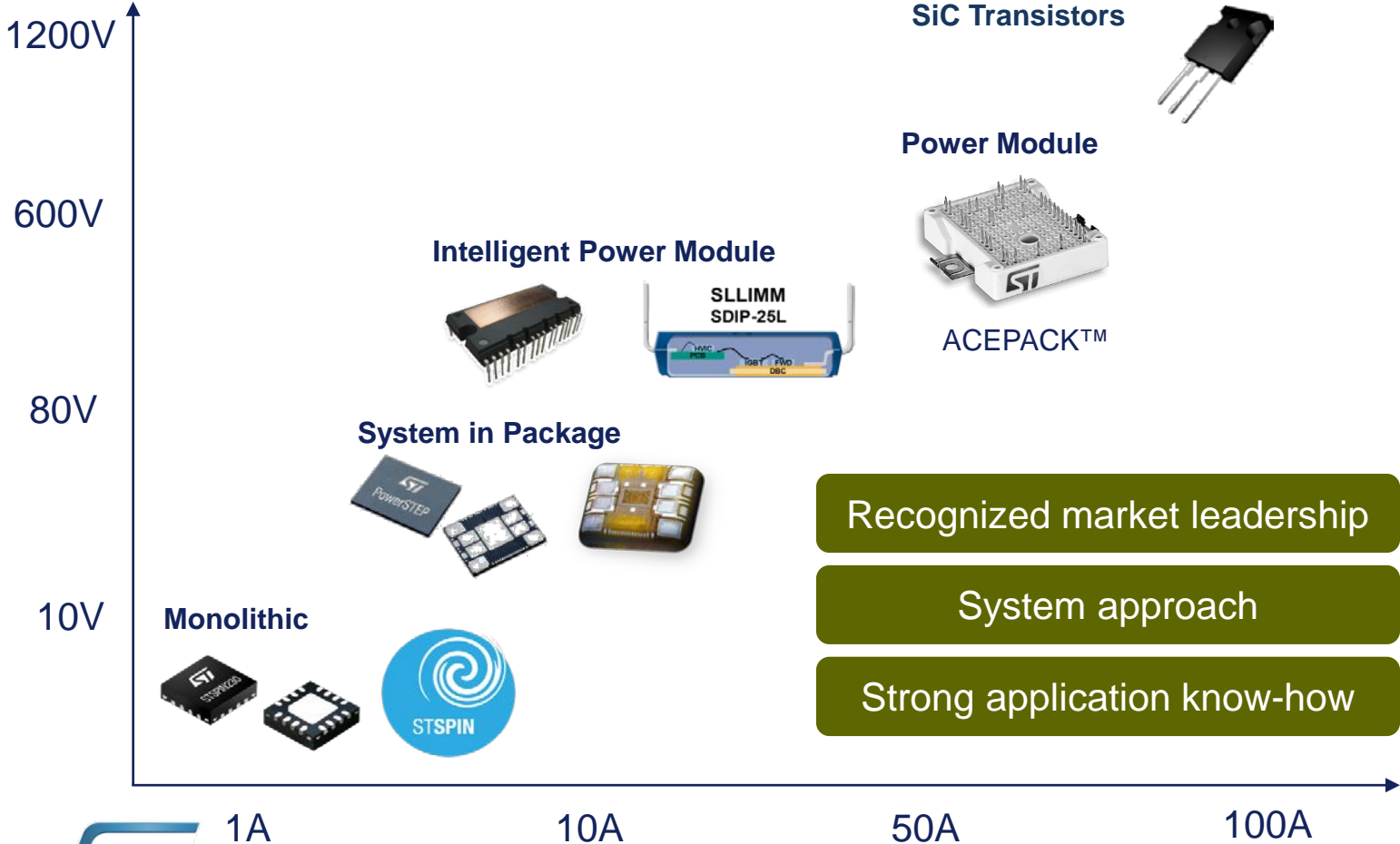
# Leading the Evolution of Motion Control

## Enabling Smart Industry

## Automation

\$ 8.7B TAM in 2016

\$ 10.9B TAM in 2019



- Recognized market leadership
- System approach
- Strong application know-how



# Smart Home Success Stories

## Buildings where people Live – Smart Appliances



Smart Water Heater

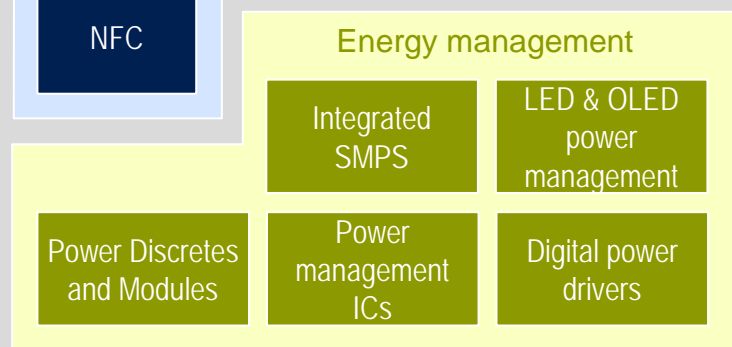
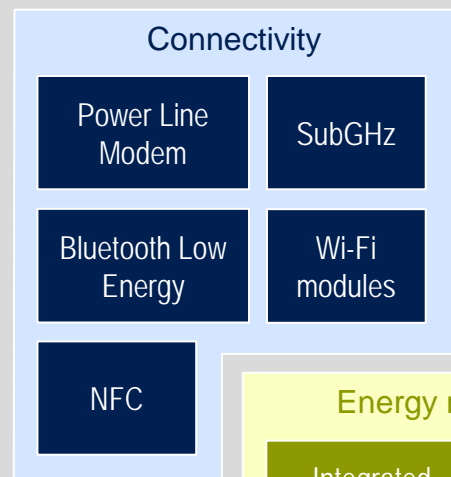
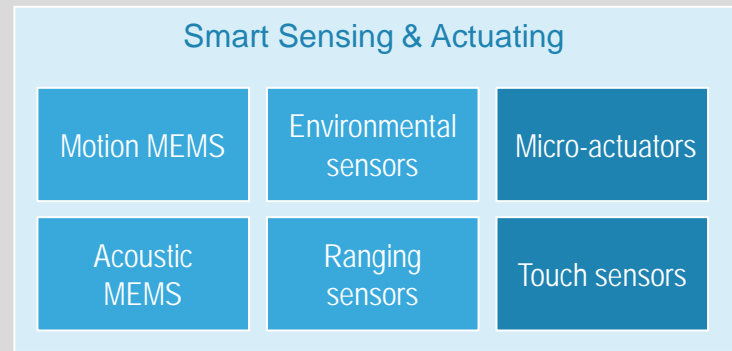
Wireless Connectivity module



Source: Qundis GmbH

Heat Cost allocator

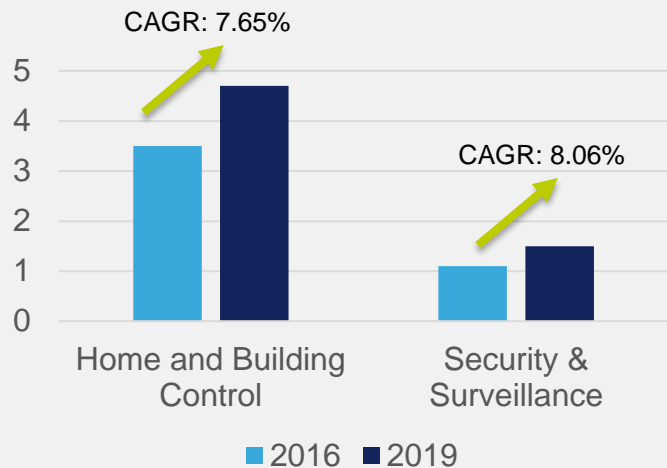
Wireless Connectivity module



For better living, higher security, and less waste

## Market

ST SAM \$B



## Key Applications



Heating & Energy Control

Smart Appliances

Security Systems

Home & Building Control

## Key Enabling Products and Technologies

- Low-power wireless connectivity
- Power management & precision analog ICs
- Motion & Environmental Sensors

## Market Leading positions

- LED driver ICs
- Motion MEMS
- Motor control ICs for Appliances

## Key success factors

- Wide variety of connectivity standards to support various application needs
- Expertise in digital security technologies
- Application Know-how

For better living, higher security, and less waste

### Sensors and Analog Front End

Detecting movement, pressure, light, humidity, proximity, gas and audio with MEMS, Biotechnologies and new materials to increase safety and security

### Connectivity

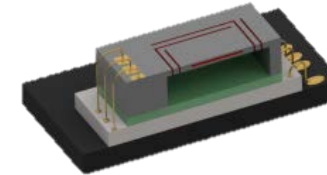
Low-power radio for short, medium and long distance with the best ratio between data rate and energy consumption, covering all available technologies and standards (subGHz, Bluetooth Low Energy, Wi-Fi, 6LowPAN)

### Power Management

Highest-efficiency products targeting zero standby power mode for lighting, computing and many other home appliances



Humidity  
Temperature  
Sensor



Pressure Sensors



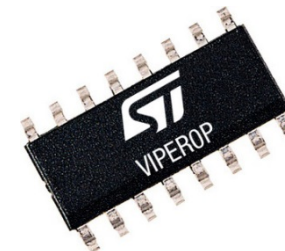
Microphones



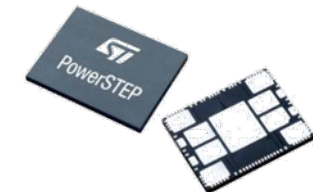
SubGHz Tx/Rx Radio



Bluetooth Low Energy  
and Wi-Fi Modules



VIPER Plus  
PM IC



PowerStep (STSPIN)  
Motor Control System-in-Package



# Smart City Success Stories

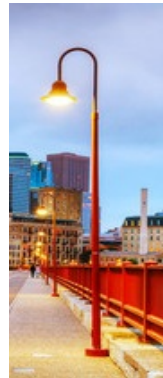
## Urban environments - smart meters, street lighting



**Smart Metering**

Processing & Metrology

STarGRID PLC



**Street Lighting**

Processing & Metrology

SubGHz connectivity

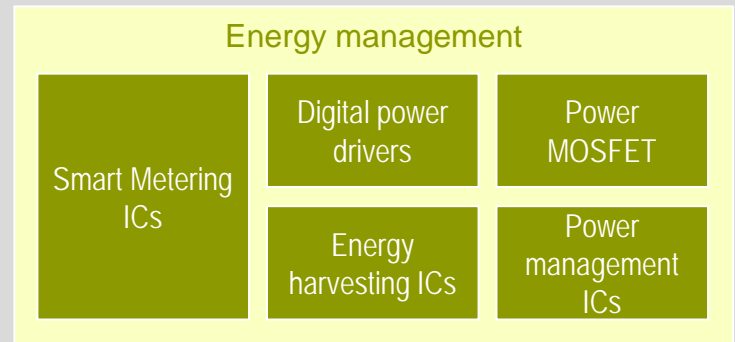
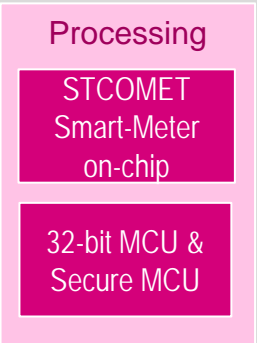
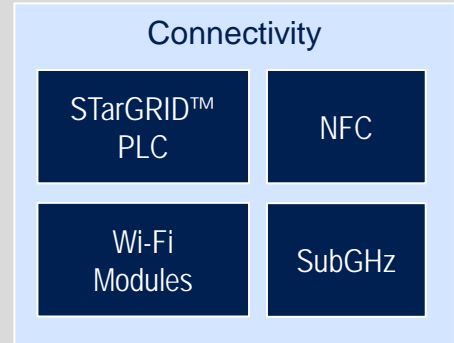
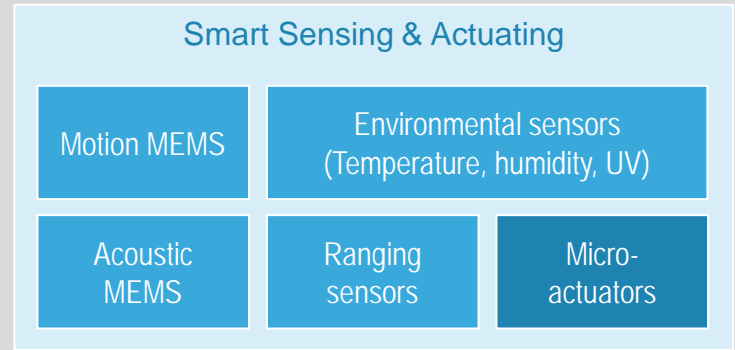


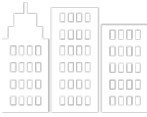
**Gas Flow Meter**

Processing

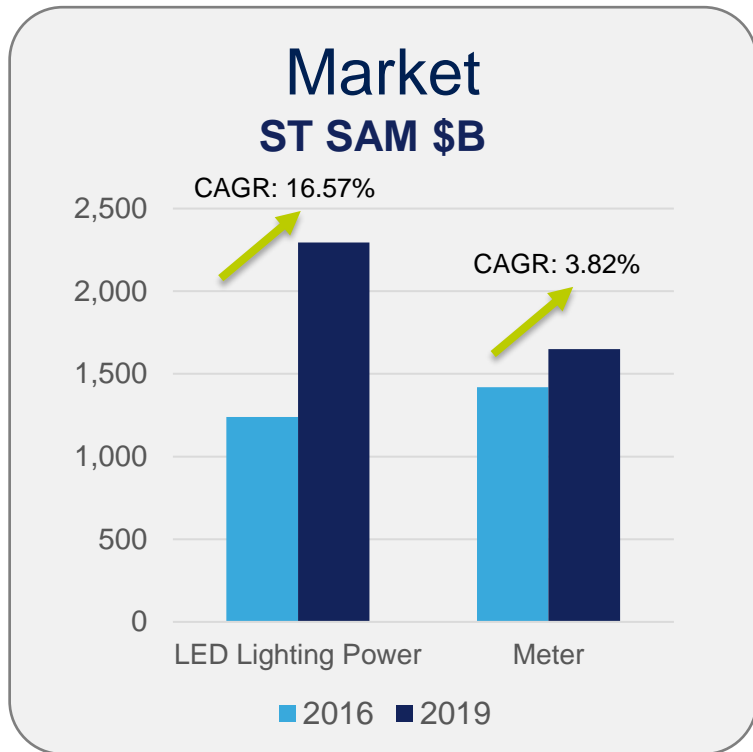
SubGHz connectivity

Smart Metering IC





## Enabling cities to make more of available resources



### Key Applications



Smart Metering

Street Lighting

Smart Transportation

Multi-Service

### Key Enabling Products and Technologies

- Wireless & power line connectivity
- Environmental sensors
- Smart Power technologies

### Market Leading positions

- Power Line modem for smart metering
- LED driver ICs
- High voltage power management

### Key success factors

- Multi-sensor network connectivity
- Expertise in digital-security technologies
- partnership with utilities and service providers, and system integrators



Enabling cities to make more of available resources

### Sensors and Analog Front End

Detection of movement, pressure, light, sound, humidity, proximity and dangerous gases



Environmental Sensors



Motion MEMS

### Connectivity

From wired power line communications to ultra-low power radio technologies (subGHz, 6LoWPAN, Meters & More, PRIME, G3, WM-Bus, SigFox)



Power Line Modem



### Power Management

From **mW** to **kW** with the highest efficiency for energy saving, renewable energy management and hybrid & electric vehicles



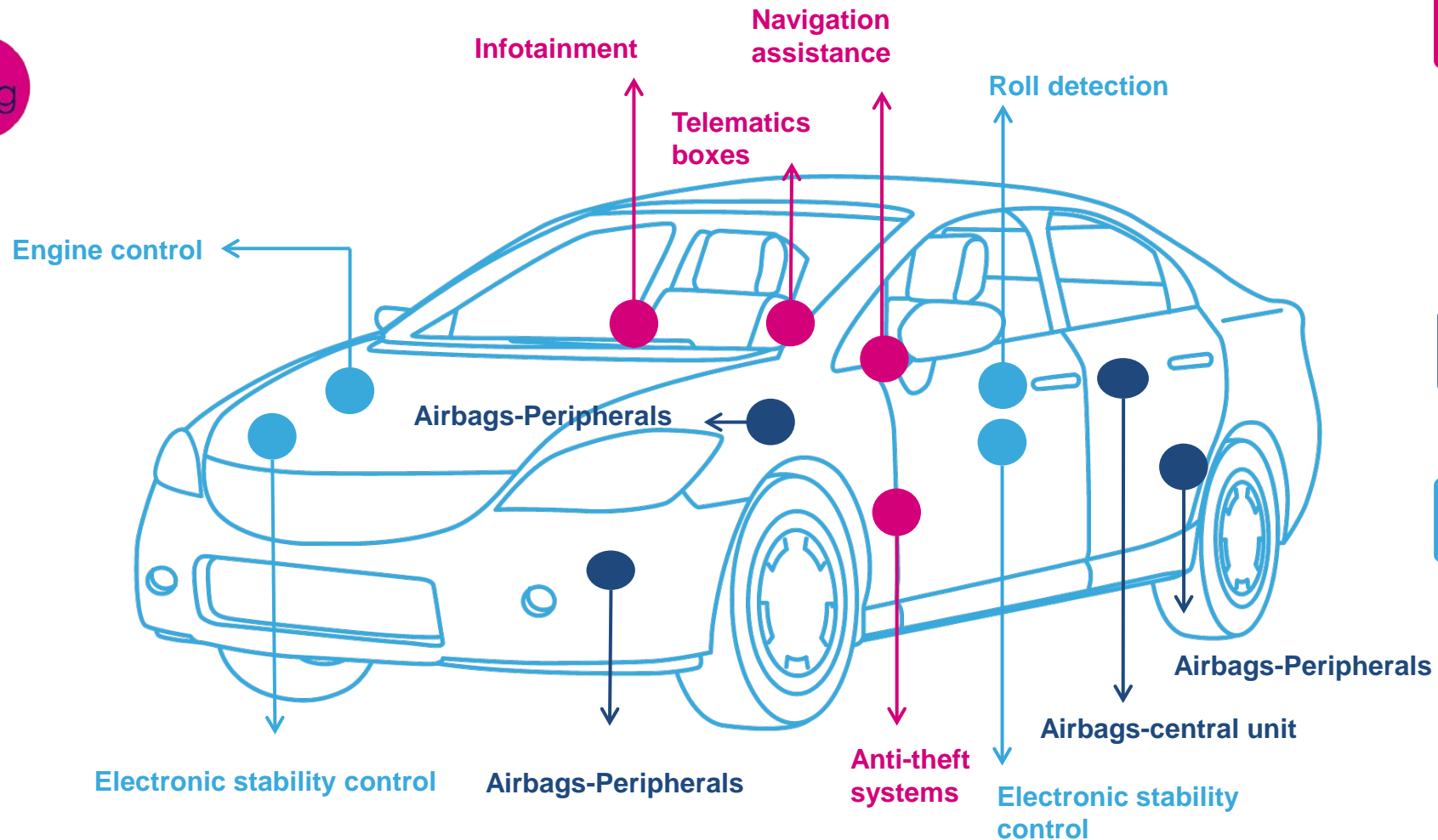
STLUX digital lighting controllers



Galvanically Isolated Gate Driver

# Sensor Technologies for Smart Driving

Making intelligent cars aware



## NON-SAFETY

- Accelerometers
- Gyroscopes
- Inertial Measurement Units
- Environmental Sensors
- Microphone

## PASSIVE SAFETY

- Accelerometers

## ACTIVE SAFETY

- Inertial Measurement Units

# Motion MEMS Leadership

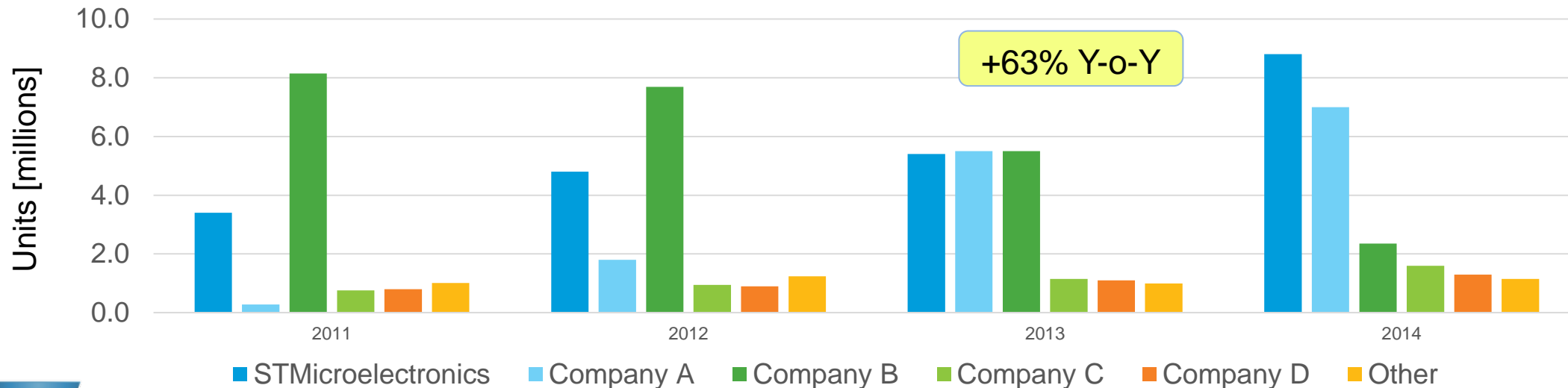
## Automotive Non-Safety

● Press release

T3714D

### STMicroelectronics Identified by IHS as Fastest Growing Automotive-Sensors Supplier

Geneva, November 10, 2015 – STMicroelectronics (NYSE: STM), a global semiconductor leader serving customers across the spectrum of electronics applications, has been recognized by IHS, the leading global source of information and analytics, as the leader in automotive sensors for navigation and telematics, as well as the fastest growing automotive-sensor supplier worldwide.<sup>1</sup>



# Sensors for Smart Driving

164

A wave of new products to fuel innovation

## Non-Safety



**A3G4250D**

First 3-axis gyroscope for automotive market



**AIS324DQ**

3-axis accelerometer for e-call and telematics



**ASM330LXH**

6-axis SiP (3D accelerometer + 3D gyroscope)

Addressing existing and new applications and markets

## Safety



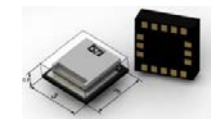
**AIS1200PS**

3-axis accelerometer for Peripheral airbags



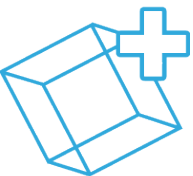
**AISx120SX**

Single- and dual-axis accelerometer for Airbag Control Units



**ASM330LXH**

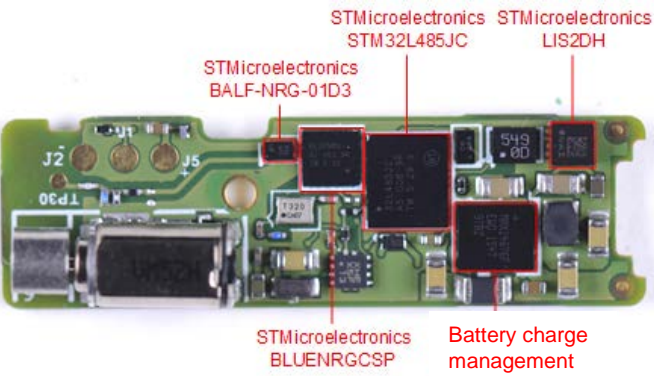
6 Degrees of freedom Inertial Measurement Unit for Electronic Stability Control



# Smart Things Success Stories

## Fitbit Alta

Inside the **Fitbit Alta**  
chipworks teardown



Source: Chipworks

## Samsung Galaxy S7



STMicroelectronics  
LSM6DS3  
6 Axis IMU

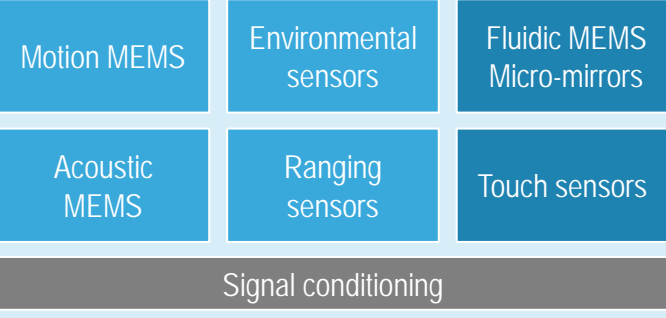


STMicroelectronics  
L2G2IS  
gyroscope

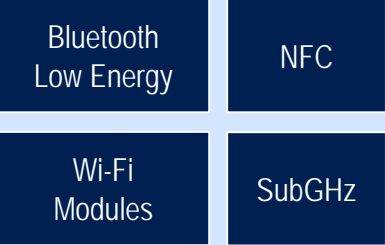


Source: Chipworks

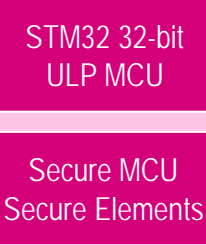
### Smart Sensing & Actuating



### Connectivity



### Processing

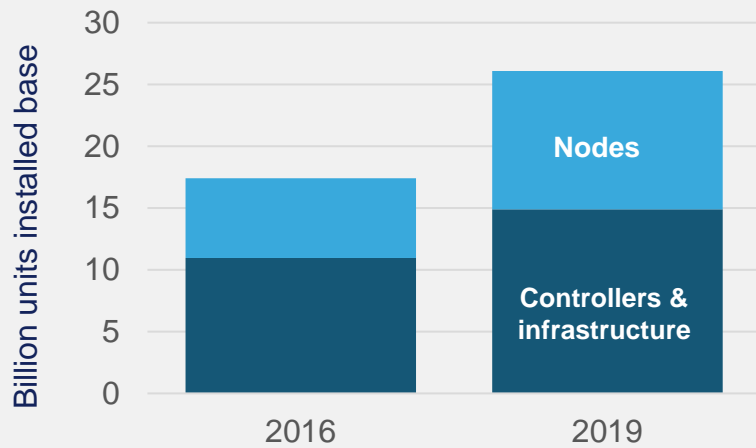


### Energy management



Making everyday things connected and more aware of their surroundings

## Market



## Key Applications



Wearable

Smartphones

Tablets

Smart consumer

## Key Enabling Products and Technologies

- MEMS
- Power and Smart Power technologies
- Ultra-low power radio for Bluetooth and subGHz
- CMOS

## Market Leading positions

- MEMS sensors & micro-actuators
- Power supply ICs for AMOLED display

## Key success factors

- Unique, full range of sensors & micro-actuators
- Free and easy-to-use software libraries for activity and gesture recognition
- Ecosystem of cloud partners for easy integration

Making everyday things connected and more aware of their surroundings

### Sensors and Analog Front End

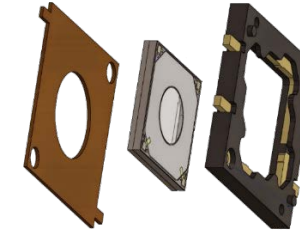
From motion MEMS to environmental sensors, from microphones to MEMS micro-actuators, the largest portfolio of products, IP and technologies on the market

### Connectivity

Ultra-low power radio for Bluetooth Low Energy and Wi-Fi applications with the lowest standby current, enabling the longest battery life

### Power Management

The best mix of Power and Smart Power technologies for the highest energy density and miniaturization - addressing traditional and new applications like Wireless Charging and power management ICs for mobile



Accelerometers and Gyroscopes



Microphones



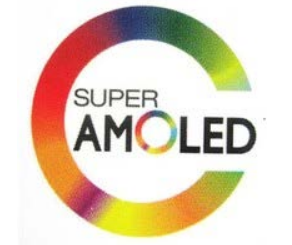
Bluetooth Low Energy



Wi-Fi Modules



Wireless Chargers



Power supply ICs for  
AMOLED

# Motion MEMS Evolution

Optical Image Stabilization (OIS)  
For Smartphones

Low-noise  
low-thickness



New Market  
penetration  
Cost effectiveness

Recreational &  
Professional  
Drones



Addressing existing and new applications and markets

Wearable

Ultra-low power  
For always-on  
wearable devices



2015

Virtual Reality  
Augmented Reality

High accuracy



2016

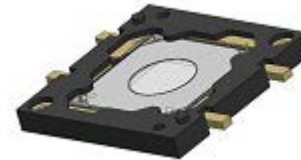




Micro-mirrors



Thin-film Piezo-electric MEMS



Instant focus  
Down to 1ms



Low power  
consumption



Constant  
field of view



Touch & re-focus  
All in focus

## 3D scanning

- In production with multiple OEMs for Intel RealSense™ Depth Camera
- Opportunities for other micro-mirror applications

## Camera Autofocus

- Lower power consumption and higher speed versus Voice-Coil Motor (VCM) based solution
- Partnering with innovative lens maker PoLight for autofocus actuator in smartphones

## Printing

High-speed inkjet print head for commercial and industrial applications

- High-viscosity materials
- Different printing materials

# Winning With Major Accounts

**Smart Things**

Apple, LG, SAMSUNG, Microsoft, Google, HUAWEI, fitbit, Seagate, Western Digital, mi, hp

**Smart Home & Smart City**

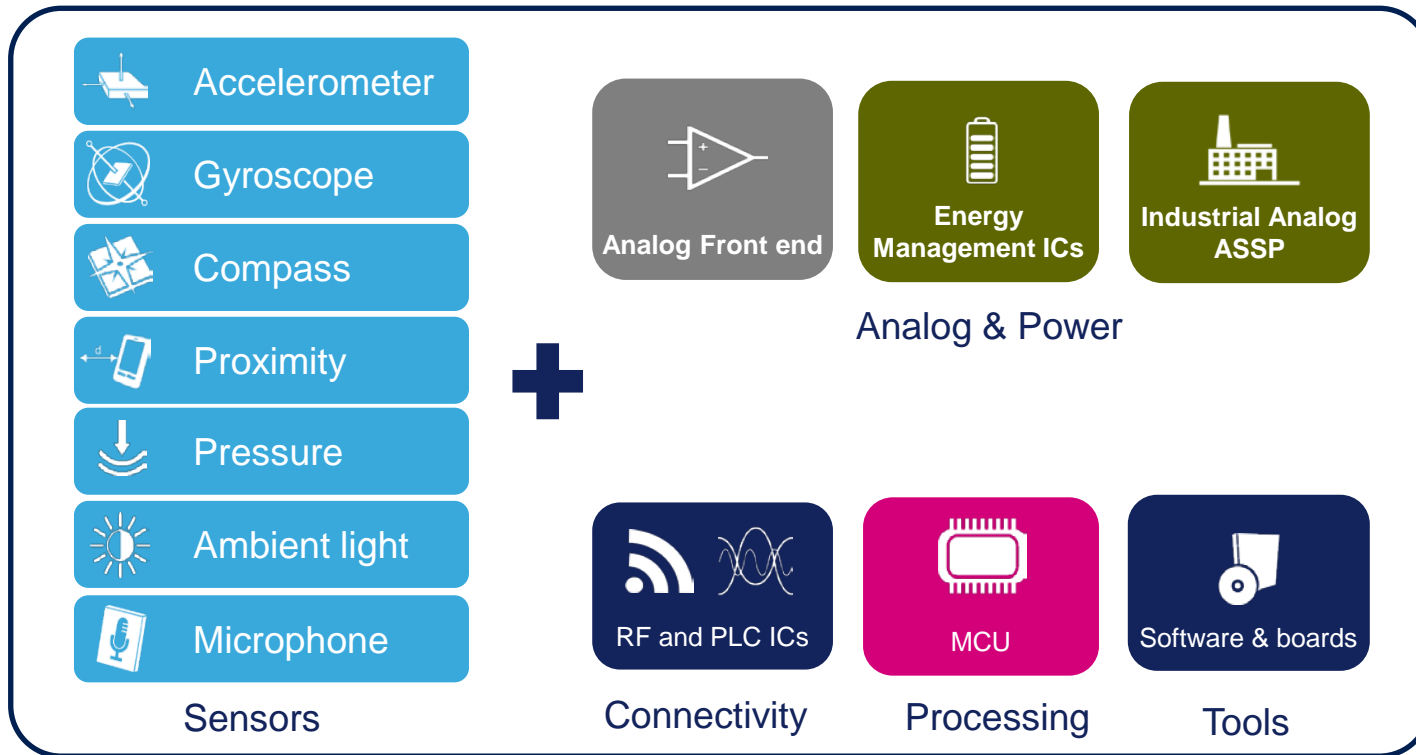
PHILIPS, DELTA, GREE, EMERSON, enel, Whirlpool, Landis+Gyr, B/S/H/, CISCO

**Smart Industry**

SIEMENS, BOSCH, PHOENIX CONTACT, Schneider Electric, ARTESYN, ABB, Nidec

Deep, long-term relationships, strong innovation pipeline with timely new product development execution, solid system and application know-how & support

## A broad Ecosystem



Solutions

- **Mass Market offers a great opportunity to grow**
  - Stability of demand thanks to multiple market segments
  - Higher margin
- **Unique position to win in the Mass Market**
  - A wide range of platforms and reference designs (SW and HW)
  - Partnership with third parties
  - Supporting design environment with selectors, design and simulation tools

Mass Market

## Key Objective

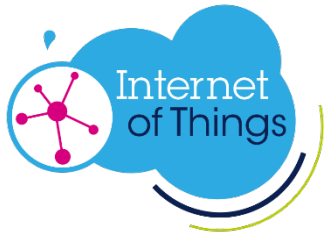
Grow revenues and achieve mid to high single-digit operating margin in mid term

### Revenue Drivers

- Wired and Wireless connectivity for IoT
- General purpose analog
- Power management in servers, smartphones and industrial
- Dedicated Analog ASICs for industrial, including metering
- MEMS
  - Automotive & Industrial MEMS
  - Piezo Micro-actuators
  - Maintain Consumer MEMS volumes

### Operating Margin

- Leverage on revenue growth
- 6" to 8" conversion in Power and Analog Fabs
- 8" to 12" Products Evolution
- Assembly Cost and Yields
- Value-add and Differentiated New Products
- Favorable Currency Effects



Smart Industry



- AMG turnaround strategy already in full execution
- Enriching our sensor portfolio to address automotive and industrial markets, while maintaining leadership in the consumer markets
- Well positioned to ride the next MEMS wave of Micro actuators
- Boosting sales of industrial and general purpose analog products in mass market.
- Focus and selective engagement with major accounts through development of dedicated analog and PMIC products.
- Enlarging our connectivity portfolio with wired and wireless solutions to address IoT



Smart City

Smart Home



Smart Things

